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## 32-Bit TRAVEO™ T1G Family Microcontroller

This section provides an overview of the S6J3120 series. The S6J3120 series is a set of 32-bit microcontrollers designed for invehicle use. It uses the Arm ${ }^{\circledR}$ Cortex $^{\circledR}$-R5 CPU as a CPU.

## Features

This section explains the features of the S6J3120 series.

## Cortex-R5 Core

■This section explains the Cortex-R5 CPU core.

- Arm Cortex-R5
- 32-bit Arm architecture
- 2-instruction issuance super scalar
- 8-stage pipeline
- Armv7/Thumb ${ }^{\circledR}-2$ instruction set
$\square$ MPU (memory protection) equipped
- 16-area support
- ECC support for the TCM ports for RAM

1-bit error correction and 2-bit error detection (SECDED)
-TCM ports
2 TCM ports

- ATCM port
- BTCM port (B0TCM, B1TCM)
-Caches
- Instruction cache 16 KB
- Data cache 16 KB
$\square$ VIC port Low latency interrupt
- AXI master interface 64-bit AXI interface (instruction/data access) 32-bit AXI interface (I/O access)
-AXI slave interface
64-bit AXI interface (TCM port access)
םETM-R5 trace


## Peripheral Functions

This section explains peripheral functions.
■Clock generation
$\square$ Main clock oscillation (4 MHz)
$\square$ No sub clock oscillation

- CR oscillation ( 100 kHz )
$\square \mathrm{CR}$ oscillation ( 4 MHz )
■Built-in Flash memory size
口Program: 1024 K + 64 KB (S6J312AHzC*)/768 K + 64 KB (S6J3129HzC*)
口 *z: A/B
- Work: 112 KB (S6J312AHzC*)/ 112 KB (S6J3129HzC*) $\quad$ *z: A/B

```
■Built-in RAM size
    \squareTCRAM }64\mathrm{ KB(S6J312AHzC*)/ 48 KB(S6J3129HzC*)
    \squareSystem SRAM 16 KB (S6J312AHzC*)/ 16 KB
        (S6J3129HzC*)
    \squareBackup RAM 8 KB (S6J312AHzC*)/ 8 KB (S6J3129HzC*)
    \square*z: A/B
■General-purpose ports: }112\mathrm{ channels (S6J312AHzC*)/ 112
    channels (S6J3129HzC*)
    \square*z: A/B
■External bus interface
    \square24-bit address, 16-bit data
■DMA controller
    \squareUp to 16 channels can be activated simultaneously.
\squareA/D converter (successive approximation type)
    \square12-bit resolution, 2 units mounted: Max 50 channels (22
    channels + 28 channels)(S6J312AHzC*)/ Max 50
    channels (22 channels + 28 channels)(S6J3129HzC*)
    \square*z: A/B
@External interrupt input: }16\mathrm{ channels
    \squareLevel ("H"/"L") and edge (rising/falling) can be detected.
■Multi-function serial (transmission and reception FIFOs
    mounted) :Max }10\mathrm{ channels(S6J312AHzC*)/ Max 10
    channels(S6J3129HzC*)
    \square*z: A/B
        < 2
    \squareFull duplex, double buffering system; 64-byte transmission
        FIFO, 64-byte reception FIFO
    \squareStandard mode (Max. }100\textrm{kbps}\mathrm{ ) is supported only.
\squareDMA transfer is supported.
            <UART (asynchronous serial interface) >
\squareFull duplex, double buffering system; 64-byte transmission
    FIFO, 64-byte reception FIFO
\squareParity check can be enabled/disabled.
\squareBuilt-in dedicated baud rate generator
\squareAn external clock can be used as a transfer clock.
\squareParity, frame, overrun error detection functions are
        available.
\squareDMA transfer is supported.
        <CSIO (synchronous serial interface) >
\squareFull duplex, double buffering system; 64-byte transmission
        FIFO, 64-byte reception FIFO
\squareSupport for SPI. Both master and slave roles are
        supported. Data length in bits can be set to a value from 5
        to 16 or one of the values of 20, 24, and 32.
\squareBuilt-in dedicated baud rate generator (master operation)
\squareExternal clock input is enabled (slave operation).
```

- Overrun error detection function is available.
-DMA transfer is supported.
$\square$ Serial chip select SPI function
<LIN-UART (asynchronous serial interface for LIN) >
$\square$ Full duplex, double buffering system; 64-byte transmission FIFO, 64-byte reception FIFO
- Support for LIN protocol revision 2.1
$\square$ Both master and slave roles are supported.
$\square$ Framing error and overrun error detection
-LIN Synch break generation and detection, LIN Synch Delimiter generation
$\square$ Built-in dedicated baud rate generator
$\square$ The external clock can be adjusted by the reload counter.
-DMA transfer is supported.
■CAN controller: CAN-FD Max 3 channel
-CAN-FD (V3.2.0)
םCAN transfer speed :5 Mbps
-CAN Clock :Max 40 MHz
- 192 message buffers/channel (reception message buffer size)
$\square 32$ message buffer/channel (transmission message buffer size)
-Base timer: MAX 30 channels
- 16-bit Timer.
- It is selectable by 4 functions of the PWM/PPG/PWC/Reload Timer.
-2-channel cascade connection enables operation as a 32bit timer.(PWC and Reload Timer)
-Reload timer: Max 10 channels
- 32-bit Timer.

■ree-run timer: Max 6 channels

- 32-bit Timer.
$\square$ Main clock oscillation and CR oscillation are available.
- Free-run timer output can work in combination with an input capture and an output compare.
■ Input capture: Max 12 channels
-32-bit Timer.
-Output compare: Max 12 channels -32-bit Timer.

■Sound generator : Max 3 channels
$\square$ Frequency and amplitude sequencers provided.
■Stepping motor controller : Max 4 channels -8-/10-bit PWM
$\square$ High current output supported (4 lines $\times 4$ channels)
$\square$ Can refer back electromotive force using pin-shared A/D converter

- LCD controller
- Common output: 4 , Segment output : 32
- Duty drive (SEG0 to SEG31) and static drive (ST0 to ST8) can be switched.
- Each of COM0 to COM3, SEG0 to SEG31, V0, V1, V2, and $V 3$ pins for duty drive can be switched to the generalpurpose port. (The SEG23 to SEG31 pins can be switched to static driving.)
$\square \mathrm{V} 0, \mathrm{~V} 1, \mathrm{~V} 2$ and V 3 pin can be used as the generalpurpose port. But V 3 pin cannot be used as an output pin.
- Each of ST0 to ST8 pins for static drive can be switched to the general-purpose port, or it can be switched to the segment output of duty drive.

■Quad position \& revolution counter(QPRC) : Max 2 channels
■Real time clock (RTC) (day/hour/minute/second)
$\square$ Main clock oscillation or CR oscillation ( 100 kHz ) can be selected as an operation clock.
■Calibration: Real time clock (RTC) driven by the CR clock
$\square$ Correction can be done by configuring the prescaler of the real time clock based on the ratio between the main clock and the CR clock.
■Clock supervisor
$\square$ Abnormality (such as damaged crystal) of the main clock oscillation ( 4 MHz ) can be monitored.

- The clock can switch to the CR clock when an abnormality is detected.
$\square$ PLL abnormality can be detected.
■CRC generation
- Fixed-length CRC
- CCITT CRC16 generator polynomial: 0x1021
- IEEE-802.3 CRC32 generator polynomial: 0x04C11DB7
-DDR HS-SPI
$\square E^{2}$ PROM and the flash device of the Single/Dual/QuadSPI protocol can be connected.
- Watchdog timer
- Hardware watchdog
$\square$ Software watchdog
■NMI
- I/O relocation
$\square$ Peripheral function pin locations can be changed.
■Low-power consumption control
$\square$ Standby function
- Power-off function
- Partial wakeup function

■ Power-on reset
■ Low-voltage detection reset

- Security
- Flash security
- Interface security (JTAG + test port)
- SHE
- Unique device ID

■ Package: LEU144 (S6J312xHzC*)

- *x:A/9, z: A/B

■CMOS 55 nm technology

- Power supply
$\square 5 \mathrm{~V}$ single power supply
$\square$ The voltage step-down circuit generates internal 1.2 V from 5 V .
$\square 5 \mathrm{~V}$ power supply is used for $\mathrm{I} / \mathrm{O}$.


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## 1. Product Lineup

The following table lists the product lineup of the S6J3120 series.
Table 1-1 Memory Size

|  |  | S6J312AHzC* | S6J3129HzC* |
| :---: | :---: | :---: | :---: |
| Flash | Program | $\begin{gathered} 1024 \text { KBytes } \\ + \\ \text { Small sector }(8 \mathrm{~KB} \times 8) \end{gathered}$ | 768 KBytes + Small sector $(8 \mathrm{~KB} \times 8)$ |
|  | Work | 112 KBytes | 112 KBytes |
| RAM | TCRAM | 64 KBytes | 48 KBytes |
|  | System SRAM | 16 KBytes | 16 KBytes |
|  | Backup RAM | 8 KBytes | 8 KBytes |

*z: A/B

Table 1-2 SHE Option

|  | S6J312xHAC* | S6J312xHBC* |
| :--- | :---: | :---: |
| Security (SHE) | ON | OFF |

* x : A/9

Table 1-3: Product Lineup

|  | S6J312xHzC*1 |
| :---: | :---: |
| CPU core | Coretex-R5 |
| CMOS 55 nm technology | 55 nm |
| Package | LEU144 |
| Main clock | 4 MHz |
| Built-in CR oscillator | 100 kHz |
|  | 4 MHz |
| Maximum CPU operating frequency | 128 MHz |
| Watchdog timer | 1 channel (hardware) <br> 1 channel (software) |
| Clock supervisor | YES |
| External power supply, low-voltage detection reset | YES |
| Internal power supply, low-voltage detection reset | YES |
| NMI request | YES |
| External interrupt | 16 channels |
| DMA controller | 16 channels |
| CAN-FD | 3 channels (192 msg buffers/ch) |
| Multi-function serial | 10 channels*2 $^{\text {2 }}$ |
| A/D converter | 12-bit (2 units) <br> Unit $0 \times 22$ channels <br> Unit $1 \times 28$ channels |
| Free-run timer | 6 channels |
| Input capture | 12 channels |
| Output compare | 12 channels |


|  | S6J312xHzC*1 |
| :--- | :---: |
| Base timer (16-bit) | 30 channels |
| Real time clock (RTC) | 1 channel |
| CR clock calibration | YES |
| CRC generation | YES |
| Low-power consumption mode | Standby function <br> Power-off function <br> Partial wakeup function |
| SHE | YES |
| External BUS I/F | Address : 24-bit Data :16-bit |
| Reload Timer(32-bit) | 10 channels |
| Quad Position \& Revolution Counter | 2 channels |
| DDR HS-SPI | YES |
| LCD Controller | 32 seg $\times 4$ com (Static drive 8 seg $\times 1$ com) |
| Sound Generator | 3 channels |
| Stepping Motor Controller | 4 channels |
| General-purpose port GPIO | 112 channels |
| Power supply | 5 V $\pm 10 \%$ |
| Operation assurance temperature (Ta) | $-40{ }^{\circ} \mathrm{C}$ to $+105{ }^{\circ} \mathrm{C}$ |
| On-chip debugger (JTAG) | YES |

*1: $\mathrm{x}: \mathrm{A} / 9, \mathrm{z}: \mathrm{A} / \mathrm{B}$
*2: $I^{2} \mathrm{C}$-UART function is not supported at Multi-function serial ch.1, ch.2, and ch. 12 .

## 2. Pin Assignment

The following figures show the pin assignment of the S6J3120 series.
Figure 2-1 Pin Assignment for S6J312xHzC*

* x: A/9, z: A/B



## 3. Pin Description

This section provides a list of the pin functions of the S6J3120 series
Table 3-1 S6J312xHzC* Pin Functions

* x: A/9, z: A/B

| Pin No. | Pin Name | Polarity | I/O Circuit Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 2 | $\begin{aligned} & \text { P000 } \\ & \text { SOT2_1 } \\ & \text { AIN8_0 } \\ & \text { MAD00 } \\ & \text { SEG8 } \end{aligned}$ |  | K | General-purpose I/O port Multi-function serial ch. 2 serial data output pin (1) QPRC ch. 8 AIN input pin (0) External bus interface address bit0 output pin LCDC segment 8 (Duty) output pin |
| 3 | $\begin{aligned} & \text { P001 } \\ & \text { SCS20_1 } \\ & \text { BIN8_0 } \\ & \text { MDATA15 } \\ & \text { SEG9 } \end{aligned}$ |  | K | General-purpose I/O port Multi-function serial ch. 2 serial chip select 0 I/O pin (1) QPRC ch. 8 BIN input pin (0) External bus interface data bus bit15 I/O pin LCDC segment 9 (Duty) output pin |
| 4 | $\begin{array}{\|l} \text { P003 } \\ \text { SCS22_1 } \\ \text { ZIN8_0 } \\ \text { MDATA14 } \\ \text { SEG10 } \end{array}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 2 serial chip select 2 output pin (1) <br> QPRC ch. 8 ZIN input pin (0) <br> External bus interface data bus bit14 I/O pin <br> LCDC segment 10 (Duty) output pin |
| 5 | $\begin{aligned} & \text { P005 } \\ & \text { SIN3_0 } \\ & \text { IN6_0 } \\ & \text { AIN9_0 } \\ & \text { MDATA13 } \\ & \text { SEG11 } \end{aligned}$ | - | K | General-purpose I/O port <br> Multi-function serial ch. 3 serial data input pin (0) Input capture ch. 6 input pin (0) <br> QPRC ch. 9 AIN input pin (0) <br> External bus interface data bus bit13 I/O pin <br> LCDC segment 11 (Duty) output pin |
| 6 | $\begin{aligned} & \text { P006 } \\ & \text { SOT3_0 } \\ & \text { SDA3_0 } \\ & \text { IN7_0 } \\ & \text { BIN9_0 } \\ & \text { MDATA12 } \\ & \text { SEG12 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 3 serial data output pin (0) <br> $1^{2} \mathrm{C}$ bus ch. 3 serial data I/O pin Input capture ch. 7 input pin (0) <br> QPRC ch. 9 BIN input pin (0) <br> External bus interface data bus bit12 I/O pin LCDC segment 12 (Duty) output pin |
| 7 | $\begin{array}{\|l\|} \hline \text { P007 } \\ \text { SCK3_0 } \\ \text { SCL3_0 } \\ \text { IN8_0 } \\ \text { ZIN9_0 } \\ \text { MDATA11 } \\ \text { SEG13 } \end{array}$ |  | K | General-purpose I/O port Multi-function serial ch. 3 clock I/O pin (0) ${ }^{2}{ }^{2} \mathrm{C}$ bus ch. 3 serial clock I/O pin Input capture ch. 8 input pin (0) QPRC ch. 9 ZIN input pin (0) External bus interface data bus bit11 I/O pin LCDC segment 13 (Duty) output pin |
| 8 | $\begin{aligned} & \text { P008 } \\ & \text { SCS30_0 } \\ & \text { IN9_0 } \\ & \text { TIOA0_0 } \\ & \text { MDATAA10 } \\ & \text { SEG14 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 3 serial chip select 0 I/O pin (0) <br> Input capture ch. 9 input pin (0) <br> Base timer ch. 0 TIOA output pin (0) <br> External bus interface data bus bit10 I/O pin <br> LCDC segment 14 (Duty) output pin |
| 9 | $\begin{aligned} & \text { P009 } \\ & \text { INT0_1 } \\ & \text { SIN11_0 } \\ & \text { IN10_0 } \\ & \text { TIOA1_0 } \\ & \text { MDATAT09 } \\ & \text { SEG15 } \end{aligned}$ |  | K | General-purpose I/O port INT0 external interrupt input pin (1) Multi-function serial ch. 11 serial data input pin (0) Input capture ch. 10 input pin (0) Base timer ch. 1 TIOA I/O pin (0) External bus interface data bus bit9 I/O pin LCDC segment 15 (Duty) output pin |


| Pin No. | Pin Name | Polarity | I/O Circuit Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 10 | P010 <br> SOT11_0 <br> SDA11_0 <br> IN11_0 <br> TIOĀ2_0 <br> MDATĀ08 <br> SEG16 |  | K | General-purpose I/O port <br> Multi-function serial ch. 11 serial data output pin (0) <br> $\mathrm{I}^{2} \mathrm{C}$ bus ch. 11 serial data I/O pin Input capture ch. 11 input pin (0) <br> Base timer ch. 2 TIOA output pin (0) <br> External bus interface data bus bit8 I/O pin LCDC segment 16 (Duty) output pin |
| 11 | P012 <br> SCK11_0 <br> SCL11_0 <br> OUT5_0 <br> TIOA3_0 <br> MOEX <br> SEG17 |  | K | General-purpose I/O port Multi-function serial ch. 11 clock I/O pin (0) $\mathrm{I}^{2} \mathrm{C}$ bus ch. 11 serial clock I/O pin Output compare ch. 5 output pin (0) Base timer ch. 3 TIOA I/O pin (0) External bus interface read enable output pin LCDC segment 17 (Duty) output pin |
| 12 | $\begin{array}{\|l} \text { P013 } \\ \text { SCS110_0 } \\ \text { OUT6_0 } \\ \text { TIOA4_0 } \\ \text { MWEX } \\ \text { SEG18 } \end{array}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 11 serial chip select 0 I/O pin (0) <br> Output compare ch. 6 output pin (0) <br> Base timer ch. 4 TIOA output pin (0) <br> External bus interface write enable output pin <br> LCDC segment 18 (Duty) output pin |
| 13 | $\begin{aligned} & \text { P015 } \\ & \text { SCS111_0 } \\ & \text { OUT7_0 } \\ & \text { TIOA5_0 } \\ & \text { MCSX0 } \\ & \text { SEG19 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 11 serial chip select 1 output pin (0) <br> Output compare ch. 7 output pin (0) <br> Base timer ch. 5 TIOA I/O pin (0) <br> External bus interface chip select 0 output pin <br> LCDC segment 19 (Duty) output pin |
| 14 | P016 <br> SCS112_0 <br> OUT8_0 <br> TIOA6_0 <br> MCSX ${ }^{-1}$ <br> SEG20 |  | K | General-purpose I/O port <br> Multi-function serial ch. 11 serial chip select 2 output pin (0) <br> Output compare ch. 8 output pin (0) <br> Base timer ch. 6 TIOA output pin (0) <br> External bus interface chip select 1 output pin <br> LCDC segment 20 (Duty) output pin |
| 15 | $\begin{aligned} & \text { P017 } \\ & \text { SCS113_0 } \\ & \text { OUT9_0 } \\ & \text { TIOA7_0 } \\ & \text { MDQM0 } \\ & \text { SEG21 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 11 serial chip select 3 output pin (0) <br> Output compare ch. 9 output pin (0) <br> Base timer ch. 7 TIOA I/O pin (0) <br> External bus interface byte mask 0 output pin <br> LCDC segment 21 (Duty) output pin |
| 16 | P018 <br> OUT10_0 <br> TIOA8_0 <br> MDQM1 <br> SEG22 |  | K | General-purpose I/O port <br> Output compare ch. 10 output pin (0) <br> Base timer ch. 8 TIOA output pin (0) <br> External bus interface byte mask 1 output pin LCDC segment 22 (Duty) output pin |
| 17 | P019 <br> TEXTO_0 <br> OUT11_0 <br> TIOBO_0 <br> MAD15 <br> SEG23/ST0 |  | K | General-purpose I/O port <br> Free-run timer 0 clock input pin (0) <br> Output compare ch. 11 output pin (0) <br> Base timer ch. 0 TIOB input pin (0) <br> External bus interface address bit15 output pin <br> LCDC segment 23 (Duty) / segment 0 (Static) output pin |
| 18 | $\begin{array}{\|l} \text { P020 } \\ \text { SOT0_0 } \\ \text { SDAO_0 } \\ \text { TEXT1_0 } \\ \text { TIOB1_0 } \end{array}$ |  | Q | General-purpose I/O port <br> Multi-function serial ch. 0 serial data output pin (0) <br> $I^{2} \mathrm{C}$ bus ch. 0 serial data $\mathrm{I} / \mathrm{O}$ pin <br> Free-run timer 1 clock input pin (0) <br> Base timer ch. 1 TIOB input pin (0) |


| Pin No. | Pin Name | Polarity | I/O Circuit Type Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 19 | $\begin{array}{\|l} \text { P021 } \\ \text { SCKO_0 } \\ \text { SCL0_0 } \\ \text { SCK4_1 } \\ \text { TIOB2_0 } \end{array}$ |  | Q | General-purpose I/O port <br> Multi-function serial ch. 0 clock I/O pin (0) <br> ${ }^{2}{ }^{2} \mathrm{C}$ bus ch. 0 serial clock I/O pin <br> Multi-function serial ch. 4 clock I/O pin (1) <br> Base timer ch. 2 TIOB input pin (0) |
| 20 | $\begin{aligned} & \text { P022 } \\ & \text { INT3_0 } \\ & \text { SINO_0 } \\ & \text { TIOB3_0 } \end{aligned}$ |  | Q | General-purpose I/O port INT3 external interrupt input pin (0) Multi-function serial ch. 0 serial data input pin (0) Base timer ch. 3 TIOB input pin (0) |
| 21 | $\begin{array}{\|l} \hline \text { P023 } \\ \text { SCS0_0 } \\ \text { SIN4_1 } \\ \text { TIOB4_0 } \\ \text { MAD16 } \\ \text { SEG24/ST1 } \end{array}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 0 serial chip select 0 I/O pin (0) <br> Multi-function serial ch. 4 serial data input pin (1) <br> Base timer ch. 4 TIOB input pin (0) <br> External bus interface address bit16 output pin <br> LCDC segment 24 (Duty) / segment 1 (Static) output pin |
| 22 | $\begin{array}{\|l\|} \hline \text { P024 } \\ \text { SOT4_1 } \\ \text { TIOB5_0 } \\ \text { MAD17 } \\ \text { SEG25/ST2 } \end{array}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 4 serial data output pin (1) <br> Base timer ch. 5 TIOB input pin (0) <br> External bus interface address bit17 output pin <br> LCDC segment 25 (Duty) / segment 2 (Static) output pin |
| 23 | $\begin{array}{\|l} \hline \text { P027 } \\ \text { SCS42_1 } \\ \text { TEXT0_1 } \\ \text { TIOB6_0 } \\ \text { TIOA4_1 } \\ \text { MAD18. } \\ \text { SEG26/ST3 } \end{array}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 4 serial chip select 2 output pin (1) <br> Free-run timer 0 clock input pin (1) <br> Base timer ch. 6 TIOB input pin (0) <br> Base timer ch. 4 TIOA output pin (1) <br> External bus interface address bit18 output pin <br> LCDC segment 26 (Duty) / segment 3 (Static) output pin |
| 24 | $\begin{array}{\|l\|} \hline \text { P028 } \\ \text { SIN1_0 } \\ \text { OUT0_1 } \\ \text { TIOB7_0 } \\ \text { MAD19 } \\ \text { SEG27/ST4 } \end{array}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 1 serial data input pin (0) <br> Output compare ch. 0 output pin (1) <br> Base timer ch. 7 TIOB input pin (0) <br> External bus interface address bit19 output pin <br> LCDC segment 27 (Duty) / segment 4 (Static) output pin |
| 25 | P029 SOT1_0 OUT1-1 MAD20 SEG28/ST5 |  | K | General-purpose I/O port <br> Multi-function serial ch. 1 serial data output pin (0) <br> Output compare ch. 1 output pin (1) <br> External bus interface address bit20 output pin <br> LCDC segment 28 (Duty) / segment 5 (Static) output pin |
| 26 | $\begin{array}{\|l\|} \hline \text { P030 } \\ \text { SCS43_1 } \\ \text { OUT2_1 } \\ \text { TIOB8_0 } \\ \text { MAD21 } \\ \text { SEG29/ST6 } \end{array}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 4 serial chip select 3 output pin (1) <br> Output compare ch. 2 output pin (1) <br> Base timer ch. 8 TIOB input pin (0) <br> External bus interface address bit21 output pin <br> LCDC segment 29 (Duty) / segment 6 (Static) output pin |
| 27 | $\begin{array}{\|l\|} \hline \text { P031 } \\ \text { SCS1_0 } \\ \text { OUT3_1 } \\ \text { MAD22 } \\ \text { SEG30/ST7 } \end{array}$ | - | K | General-purpose I/O port <br> Multi-function serial ch. 1 serial chip select 0 I/O pin (0) <br> Output compare ch. 3 output pin (1) <br> External bus interface address bit22 output pin <br> LCDC segment 30 (Duty) / segment 7 (Static) output pin |
| 28 | $\begin{array}{\|l\|} \hline \text { P100 } \\ \text { SCK1_0 } \\ \text { OUT4_1 } \\ \text { MAD23 } \\ \text { SEG31/ST8 } \end{array}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 1 clock I/O pin (0) <br> Output compare ch. 4 output pin (1) <br> External bus interface address bit23 output pin <br> LCDC segment 31 (Duty) / segment 8 (Static) output pin |


| Pin No. | Pin Name | Polarity | I/O Circuit Type Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 29 | P101 <br> AN3 <br> OUT5_1 <br> MDATA07 |  | B | General-purpose I/O port ADC analog 3 input pin Output compare ch. 5 output pin (1) External bus interface data bit7 I/O pin |
| 30 | P103 <br> AN5 <br> OUT6_1 <br> TIOB9_0 MDATĀ06 |  | B | General-purpose I/O port ADC analog 5 input pin Output compare ch. 6 output pin (1) Base timer ch. 9 TIOB input pin (0) External bus interface data bit6 I/O pin |
| 31 | P105 <br> OUT7_1 <br> TIOA9_0 <br> MDATA05 |  | Q | General-purpose I/O port Output compare ch. 7 output pin (1) Base timer ch. 9 TIOA I/O pin (0) External bus interface data bit5 I/O pin |
| 32 | P106 <br> TX1_2 <br> OUT8_1 <br> TINO <br> MDATA04 |  | Q | General-purpose I/O port CAN transmission data 1 output pin (2) Output compare ch. 8 output pin (1) Reload timer ch. 0 event input pin (0) External bus interface data bit4 I/O pin |
| 33 | P107 <br> INT2_1 <br> RX1_2 <br> OUT9_1 <br> TIOA10_0 <br> TOTO <br> MDATA03 |  | Q | General-purpose I/O port INT2 external interrupt input pin (1) CAN reception data 1 input pin (2) Output compare ch. 9 output pin (1) Base timer ch. 10 TIOA output pin (0) Reload timer ch. 0 output pin (0) <br> External bus interface data bit3 I/O pin |
| 34 | P108 <br> INT3_1 <br> AN6 <br> OUT10_1 <br> TIOA11_0 <br> TIN1 <br> MRDY |  | B | General-purpose I/O port INT3 external interrupt input pin (1) ADC analog 6 input pin Output compare ch. 10 output pin (1) Base timer ch. 11 TIOA I/O pin (0) Reload timer ch. 1 event input pin (0) External bus interface ready input pin |
| 35 | P109 <br> OUT11_1 <br> TIOA12_0 <br> TOT1 <br> MCLK |  | Q | General-purpose I/O port <br> Output compare ch. 11 output pin (1) <br> Base timer ch. 12 TIOA output pin (0) <br> Reload timer ch. 1 output pin (0) <br> External bus interface system clock output pin |
| 39 | P112 <br> AN9 <br> TIOA13_0 <br> TIN2 <br> MDATA02 |  | B | General-purpose I/O port ADC analog 9 input pin Base timer ch. 13 TIOA I/O pin (0) Reload timer ch. 2 event input pin (0) External bus interface data bit2 I/O pin |
| 40 | P113 <br> TIOA5_1 <br> TOT2 MDATA01 |  | Q | General-purpose I/O port <br> Base timer ch. 5 TIOA I/O pin (1) <br> Reload timer ch. 2 output pin (0) <br> External bus interface data bit1 I/O pin |
| 41 | P114 <br> AN10 <br> TIOA6_1 <br> TIN3 <br> MDATA00 |  | B | General-purpose I/O port ADC analog 10 input pin Base timer ch. 6 TIOA output pin (1) Reload timer ch. 3 event input pin (0) External bus interface data bit0 I/O pin |
| 45 | $\begin{array}{\|l} \hline \text { P115 } \\ \text { TIOB10_0 } \\ \text { TOT3 } \end{array}$ |  | Q | General-purpose I/O port Base timer ch. 10 TIOB input pin (0) Reload timer ch. 3 output pin (0) |


| Pin No. | Pin Name | Polarity | I/O Circuit Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 46 | P117 <br> INT4_1 <br> AN12 <br> TIOB11_0 <br> TIN16 |  | B | General-purpose I/O port INT4 external interrupt input pin (1) ADC analog 12 input pin Base timer ch. 11 TIOB input pin (0) Reload timer ch. 16 event input pin (0) |
| 47 | P118 <br> INT5_1 <br> AN13 <br> TIOB12_0 <br> TOT16 |  | B | General-purpose I/O port INT5 external interrupt input pin (1) ADC analog 13 input pin Base timer ch. 12 TIOB input pin (0) Reload timer ch. 16 output pin (0) |
| 48 | P119 <br> AN14 <br> SCS90 0 <br> TIOB13_0 <br> TIN17 |  | B | General-purpose I/O port ADC analog 14 input pin Multi-function serial ch. 9 serial chip select 0 I/O pin (0) Base timer ch. 13 TIOB input pin (0) Reload timer ch. 17 event input pin (0) |
| 49 | $\begin{array}{\|l\|} \hline \text { P120 } \\ \text { AN15 } \\ \text { SCS91_0 } \\ \text { TOT17 } \end{array}$ |  | B | General-purpose I/O port ADC analog 15 input pin Multi-function serial ch. 9 serial chip select 1 output pin (0) Reload timer ch. 17 output pin (0) |
| 50 | $\begin{array}{\|l\|} \hline \text { P122 } \\ \text { AN17 } \\ \text { SCS92_0 } \\ \text { TIOA11_1 } \\ \text { SGAO_0 } \end{array}$ |  | B | General-purpose I/O port ADC analog 17 input pin Multi-function serial ch. 9 serial chip select 2 output pin (0) Base timer ch. 11 TIOA I/O pin (1) Sound generator ch. 0 SGA output pin (0) |
| 51 | $\begin{array}{\|l\|} \hline \text { P123 } \\ \text { AN18 } \\ \text { SCS93_0 } \\ \text { TIOA12_1 } \\ \text { SGO0_0 } \end{array}$ |  | B | General-purpose I/O port ADC analog 18 input pin Multi-function serial ch. 9 serial chip select 3 output pin (0) Base timer ch. 12 TIOA output pin (1) Sound generator ch. 0 SGO output pin (0) |
| 52 | $\begin{aligned} & \hline \text { P126 } \\ & \text { AN19 } \\ & \text { SGA1_0 } \end{aligned}$ | - | B | General-purpose I/O port ADC analog 19 input pin Sound generator ch. 1 SGA output pin (0) |
| 53 | $\begin{array}{\|l} \hline \text { P127 } \\ \text { AN20 } \\ \text { TEXT1_1 } \\ \text { SGO1_0 } \end{array}$ |  | B | General-purpose I/O port ADC analog 20 input pin Free-run timer 1 clock input pin (1) Sound generator ch. 1 SGO output pin (0) |
| 54 | $\begin{array}{\|l\|} \hline \text { P128 } \\ \text { AN21 } \\ \text { TEXT2_1 } \\ \text { SGA2_0 } \end{array}$ |  | B | General-purpose I/O port ADC analog 21 input pin Free-run timer 2 clock input pin (1) Sound generator ch. 2 SGA output pin (0) |
| 55 | $\begin{aligned} & \hline \text { P129 } \\ & \text { AN22 } \\ & \text { IN6_1 } \\ & \text { SGOZ2_0 } \end{aligned}$ |  | B | General-purpose I/O port ADC analog 22 input pin Input capture ch. 6 input pin (1) Sound generator ch. 2 SGO output pin (0) |
| 56 | $\begin{aligned} & \text { P130 } \\ & \text { INT5_0 } \\ & \text { AN23 } \\ & \text { SIN9_0 } \\ & \text { IN7_1 } \end{aligned}$ |  | B | General-purpose I/O port INT5 external interrupt input pin (0) ADC analog 23 input pin Multi-function serial ch. 9 serial data input pin (0) Input capture ch. 7 input pin (1) |
| 57 | $\begin{aligned} & \hline \text { P131 } \\ & \text { AN24 } \\ & \text { SOT9_0 } \\ & \text { SDA9_0 } \\ & \text { IN8_1 } \end{aligned}$ |  | B | General-purpose I/O port ADC analog 24 input pin Multi-function serial ch. 9 serial data output pin (0) $\mathrm{I}^{2} \mathrm{C}$ bus ch. 9 serial data $\mathrm{I} / \mathrm{O}$ pin Input capture ch. 8 input pin (1) |


| Pin No. | Pin Name | Polarity | I/O Circuit Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 58 | $\begin{array}{\|l\|} \hline \text { P202 } \\ \text { INT6_1 } \\ \text { SCK9_0 } \\ \text { SCL9_0 } \\ \text { IN9_1 } \end{array}$ |  | Q | General-purpose I/O port INT6 external interrupt input pin (1) Multi-function serial ch. 9 clock I/O pin (0) $1^{2} \mathrm{C}$ bus ch. 9 serial clock $\mathrm{I} / \mathrm{O}$ pin Input capture ch. 9 input pin (1) |
| 59 | P203 <br> IN10_1 <br> TIOB19_0 <br> AIN8_1 |  | Q | General-purpose I/O port Input capture ch. 10 input pin (1) Base timer ch. 19 TIOB input pin (0) QPRC ch. 8 AIN input pin (1) |
| 60 | P204 <br> AN27 <br> IN11_1 <br> TIOB20_0 <br> BIN8_1 |  | B | General-purpose I/O port ADC analog 27 input pin Input capture ch. 11 input pin (1) Base timer ch. 20 TIOB input pin (0) QPRC ch. 8 BIN input pin (1) |
| 61 | $\begin{array}{\|l\|} \hline \text { P205 } \\ \text { AN28 } \\ \text { TEXT3_1 } \\ \text { TIOB21_0 } \\ \text { ZIN8_1- } \end{array}$ |  | B | General-purpose I/O port ADC analog 28 input pin Free-run timer 3 clock input pin (1) Base timer ch. 21 TIOB input pin (0) QPRC ch. 8 ZIN input pin (1) |
| 62 | P206 AN29 SCS43_0 TEXT4_1 TIOB22_0 |  | B | General-purpose I/O port ADC analog 29 input pin Multi-function serial ch. 4 serial chip select 3 output pin (0) Free-run timer 4 clock input pin (1) Base timer ch. 22 TIOB input pin (0) |
| 63 | P207 <br> INT7_1 <br> AN30 <br> SCK4_0 <br> SCL4_0 <br> TEXT5_1 <br> SPISEL3 |  | B | General-purpose I/O port INT7 external interrupt input pin (1) ADC analog 30 input pin Multi-function serial ch. 4 clock I/O pin (0) $\mathrm{I}^{2} \mathrm{C}$ bus ch. 4 serial clock I/O pin Free-run timer 5 clock input pin (1) HS-SPI slave select 3 output pin |
| 64 | P208 AN31 SCS42_0 TIOA19_0 SPISEL2 |  | B | General-purpose I/O port ADC analog 31 input pin Multi-function serial ch. 4 serial chip select 2 output pin (0) Base timer ch. 19 TIOA I/O pin (0) HS-SPI slave select 2 output pin |
| 65 | $\begin{array}{\|l\|} \hline \text { P209 } \\ \text { AN32 } \\ \text { SOT4_0 } \\ \text { SDA4_0 } \\ \text { TIOA20_0 } \\ \text { SPISEL1 } \end{array}$ |  | B | General-purpose I/O port ADC analog 32 input pin Multi-function serial ch. 4 serial data output pin (0) $\mathrm{I}^{2} \mathrm{C}$ bus ch. 4 serial data $\mathrm{I} / \mathrm{O}$ pin Base timer ch. 20 TIOA output pin (0) HS-SPI slave select 1 output pin |
| 66 | P210 <br> INT6_0 <br> AN33 <br> SIN4_0 <br> INO_ $\overline{2}$ <br> TIOĀ21_0 <br> SPICLK |  | B | General-purpose I/O port <br> INT6 external interrupt input pin (0) <br> ADC analog 33 input pin Multi-function serial ch. 4 serial data input pin (0) Input capture ch. 0 input pin (2) <br> Base timer ch. 21 TIOA I/O pin (0) <br> HS-SPI clock output pin |


| Pin No. | Pin Name | Polarity | I/O Circuit Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 67 | P211 <br> AN34 <br> SCS40_0 <br> IN1_2 <br> TIOĀ22_0 <br> SPIDATO |  | B | General-purpose I/O port <br> ADC analog 34 input pin <br> Multi-function serial ch. 4 serial chip select 0 I/O pin (0) <br> Input capture ch. 1 input pin (2) <br> Base timer ch. 22 TIOA output pin (0) <br> HS-SPI data 0 I/O pin |
| 68 | P212 <br> AN35 <br> SCS41_0 <br> SCS80_1 <br> IN2_2 <br> TIOA13_1 <br> SPIDAT2 |  | B | General-purpose I/O port <br> ADC analog 35 input pin <br> Multi-function serial ch. 4 serial chip select 1 output pin (0) <br> Multi-function serial ch. 8 serial chip select 0 I/O pin (1) <br> Input capture ch. 2 input pin (2) <br> Base timer ch. 13 TIOA I/O pin (1) <br> HS-SPI data 2 I/O pin |
| 69 | P213 <br> INT8_1 <br> SIN8_1 <br> IN3_2 <br> TIOA14_1 <br> SPIDAT1 1 |  | Q | General-purpose I/O port <br> INT8 external interrupt input pin (1) <br> Multi-function serial ch. 8 serial data input pin (1) <br> Input capture ch. 3 input pin (2) <br> Base timer ch. 14 TIOA output pin (1) <br> HS-SPI data 1 I/O pin |
| 70 | P214 <br> SOT8_1 <br> IN4_2 <br> TIOA15_1 SPISEL0 |  | Q | General-purpose I/O port Multi-function serial ch. 8 serial data output pin (1) Input capture ch. 4 input pin (2) Base timer ch. 15 TIOA I/O pin (1) HS-SPI slave select 0 output pin |
| 71 | P215 <br> INT9_1 <br> SCK $\overline{1}$ _1 <br> IN5_2 <br> TIOA16_1 <br> SPIDAT3 | - | Q | General-purpose I/O port INT9 external interrupt input pin (1) Multi-function serial ch. 8 clock I/O pin (1) Input capture ch. 5 input pin (2) Base timer ch. 16 TIOA output pin (1) HS-SPI data 3 I/O pin |
| 74 | P218 AN36 TEXT2_0 TIOB14_0 |  | B | General-purpose I/O port ADC analog 36 input pin Free-run timer 2 clock input pin (0) Base timer ch. 14 TIOB input pin (0) |
| 75 | P219 AN37 <br> TEXT3_0 TIOB15_0 | - | B | General-purpose I/O port ADC analog 37 input pin Free-run timer 3 clock input pin (0) Base timer ch. 15 TIOB input pin (0) |
| 76 | P220 AN38 TX2_0 SCS83_0 IN6_2_ TIOB16_0 |  | B | General-purpose I/O port <br> ADC analog 38 input pin <br> CAN transmission data 2 output pin (0) <br> Multi-function serial ch. 8 serial chip select 3 output pin (0) <br> Input capture ch. 6 input pin (2) <br> Base timer ch. 16 TIOB input pin (0) |
| 77 | $\begin{array}{\|l\|} \hline \text { P222 } \\ \text { INT7_0 } \\ \text { AN39 } \\ \text { RX2_0 } \\ \text { SIN8_0 } \\ \text { IN7_2 } \end{array}$ |  | B | General-purpose I/O port INT7 external interrupt input pin (0) ADC analog 39 input pin CAN reception data 2 input pin (0) Multi-function serial ch. 8 serial data input pin (0) Input capture ch. 7 input pin (2) |


| Pin No. | Pin Name | Polarity | I/O Circuit Type Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 78 | P223 AN40 PWU_AN0 SCS81_0 IN8_2_1 AIN9_1 |  | B | General-purpose I/O port ADC analog 40 input pin Partial wakeup ADC analog 0 input pin Multi-function serial ch. 8 serial chip select 1 output pin (0) Input capture ch. 8 input pin (2) <br> QPRC ch. 9 AIN input pin (1) |
| 79 | P224 <br> AN41 <br> PWU_AN1 <br> TXO_2 <br> SCS80_0 <br> IN9_2 <br> BIN9_1 |  | B | General-purpose I/O port ADC analog 41 input pin Partial wakeup ADC analog 1 input pin CAN transmission data 0 output pin (2) Multi-function serial ch. 8 serial chip select 0 I/O pin (0) Input capture ch. 9 input pin (2) <br> QPRC ch. 9 BIN input pin (1) |
| 80 | P225 <br> INTO_0 <br> PWU_AN2 <br> AN42 <br> RXO_2 <br> SOT $\overline{8}$ _0 <br> SDA8_0 <br> IN10 $\overline{2}$ <br> TIOB17_0 <br> ZIN9_1 |  | B | General-purpose I/O port INT0 external interrupt input pin (0) Partial wakeup ADC analog 2 input pin ADC analog 42 input pin CAN reception data 0 input pin (2) Multi-function serial ch. 8 serial data output pin (0) $1^{2} \mathrm{C}$ bus ch. 8 serial data I/O pin Input capture ch. 10 input pin (2) <br> Base timer ch. 17 TIOB input pin (0) QPRC ch. 9 ZIN input pin (1) |
| 81 | P226 <br> AN43 <br> PWU_AN3 <br> SCK8_0 <br> SCL8_0 <br> IN11_2 <br> TIOĀ17_1 |  | B | General-purpose I/O port ADC analog 43 input pin Partial wakeup ADC analog 3 input pin Multi-function serial ch. 8 clock I/O pin (0) $I^{2} \mathrm{C}$ bus ch. 8 serial clock I/O pin Input capture ch. 11 input pin (2) <br> Base timer ch. 17 TIOA I/O pin (1) |
| 87 | P229 <br> INT8_0 <br> AN46 <br> PWU_AN6 <br> OUTO_0 <br> TIOA25_0 <br> PWM1P0 |  | M | General-purpose I/O port INT8 external interrupt input pin (0) ADC analog 46 input pin Partial wakeup ADC analog 6 input pin Output compare ch. 0 output pin (0) Base timer ch. 25 TIOA I/O pin (0) SMC ch. 0 (P1) output pin |
| 88 | P230 <br> AN47 <br> PWU_AN7 <br> OUT1_0 <br> TIOA26_0 <br> PWM1M0 |  | M | General-purpose I/O port ADC analog 47 input pin Partial wakeup ADC analog 7 input pin Output compare ch. 1 output pin (0) Base timer ch. 26 TIOA output pin (0) SMC ch. 0 (M1) output pin |
| 89 | P231 <br> AN48 <br> OUT2_0 <br> TIOA27_0 <br> PWM2FO |  | M | General-purpose I/O port ADC analog 48 input pin Output compare ch. 2 output pin (0) Base timer ch. 27 TIOA I/O pin (0) SMC ch. 0 (P2) output pin |
| 90 | $\begin{array}{\|l\|} \hline \text { P300 } \\ \text { AN49 } \\ \text { OUT3_0 } \\ \text { TIOA28_0 } \\ \text { PWM2M0 } \end{array}$ |  | M | General-purpose I/O port ADC analog 49 input pin Output compare ch. 3 output pin (0) Base timer ch. 28 TIOA output pin (0) SMC ch. 0 (M2) output pin |


| Pin No. | Pin Name | Polarity | I/O Circuit Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 91 | P301 <br> AN50 <br> OUT4_0 <br> TIOA18_1 <br> PWM1P1 |  | M | General-purpose I/O port ADC analog 50 input pin Output compare ch. 4 output pin (0) Base timer ch. 18 TIOA output pin (1) SMC ch. 1 (P1) output pin |
| 92 | P302 <br> AN51 <br> TIOA19_1 <br> PWM1M1 |  | M | General-purpose I/O port ADC analog 51 input pin Base timer ch. 19 TIOA I/O pin (1) SMC ch. 1 (M1) output pin |
| 93 | P304 AN52 TEXT4_0 TIOA20_1 PWM2P1 |  | M | General-purpose I/O port ADC analog 52 input pin Free-run timer 4 clock input pin (0) Base timer ch. 20 TIOA output pin (1) SMC ch. 1 (P2) output pin |
| 94 | $\begin{array}{\|l\|} \hline \text { P305 } \\ \text { AN53 } \\ \text { TEXT5_0 } \\ \text { TIOA29_0 } \\ \text { PWM2MM } \end{array}$ |  | M | General-purpose I/O port ADC analog 53 input pin Free-run timer 5 clock input pin (0) Base timer ch. 29 TIOA I/O pin (0) SMC ch. 1 (M2) output pin |
| 97 | P307 <br> INT1 0 <br> AN55 <br> SCS102_0 <br> TIOB18 0 <br> PWM1P2 |  | M | General-purpose I/O port INT1 external interrupt input pin (0) ADC analog 55 input pin Multi-function serial ch. 10 serial chip select 2 output pin (0) Base timer ch. 18 TIOB input pin (0) SMC ch. 2 (P1) output pin |
| 98 | P308 <br> AN56 <br> IN0_1 <br> TIOA28_1 <br> PWM1M2 |  | M | General-purpose I/O port ADC analog 56 input pin Input capture ch. 0 input pin (1) Base timer ch. 28 TIOA output pin (1) SMC ch. 2 (M1) output pin |
| 99 | P309 AN57 IN1_1 TIOA29_1 PWM2P2 |  | M | General-purpose I/O port ADC analog 57 input pin Input capture ch. 1 input pin (1) Base timer ch. 29 TIOA I/O pin (1) SMC ch. 2 (P2) output pin |
| 100 | P312 <br> AN58 <br> SCS101_0 <br> IN2_1 <br> TIOB25_0 <br> PWM2M2 |  | M | General-purpose I/O port ADC analog 58 input pin Multi-function serial ch. 10 serial chip select 1 output pin (0) Input capture ch. 2 input pin (1) Base timer ch. 25 TIOB input pin (0) SMC ch. 2 (M2) output pin |
| 101 | P313 <br> INT10_1 <br> AN59 <br> SOT10_0 <br> SDA10_0 <br> IN3_1 <br> TIOB26_0 <br> PWM1P3 |  | M | General-purpose I/O port INT10 external interrupt input pin (1) ADC analog 59 input pin Multi-function serial ch. 10 serial data output pin (0) $\mathrm{I}^{2} \mathrm{C}$ bus ch. 10 serial data I/O pin Input capture ch. 3 input pin (1) Base timer ch. 26 TIOB input pin (0) SMC ch. 3 (P1) output pin |


| Pin No. | Pin Name | Polarity | I/O Circuit Type Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 102 | P314 <br> AN60 <br> SCK10_0 <br> SCL10_0 <br> IN4_1 <br> TIOB27_0 <br> TIOA7-1 <br> PWM1 M 3 |  | M | General-purpose I/O port ADC analog 60 input pin Multi-function serial ch. 10 clock I/O pin (0) $\mathrm{I}^{2} \mathrm{C}$ bus ch. 10 serial clock I/O pin Input capture ch. 4 input pin (1) Base timer ch. 27 TIOB input pin (0) Base timer ch. 7 TIOA I/O pin (1) SMC ch. 3 (M1) output pin |
| 103 | P315 <br> AN61 <br> TX1_1 <br> SCS100_0 <br> IN5_1 <br> TIOB28_0 <br> TIOA8_1 <br> PWM2 $\bar{P} 3$ |  | M | General-purpose I/O port <br> ADC analog 61 input pin <br> CAN transmission data 1 output pin (1) <br> Multi-function serial ch. 10 serial chip select 0 I/O pin (0) <br> Input capture ch. 5 input pin (1) <br> Base timer ch. 28 TIOB input pin (0) <br> Base timer ch. 8 TIOA output pin (1) <br> SMC ch. 3 (P2) output pin |
| 104 | P317 <br> INT11_1 <br> AN62 <br> RX1_1 <br> SIN10_0 <br> TIOB29_0 <br> TIOA9_1 <br> PWM2M3 |  | M | General-purpose I/O port INT11 external interrupt input pin (1) ADC analog 62 input pin CAN reception data 1 input pin (1) Multi-function serial ch. 10 serial data input pin (0) Base timer ch. 29 TIOB input pin (0) Base timer ch. 9 TIOA I/O pin (1) SMC ch. 3 (M2) output pin |
| 107 | P321 PWUTRG |  | R | General-purpose output port Partial wakeup trigger output pin |
| 110 | $\begin{array}{l\|} \hline \text { TRST } \\ \text { P322 } \end{array}$ | N | J | JTAG test reset input pin General-purpose output port |
| 111 | $\begin{array}{\|l\|} \hline \text { TDO } \\ \text { P323 } \end{array}$ |  | I | JTAG test data output pin General-purpose output port |
| 112 | $\begin{array}{\|l\|} \hline \text { TDI } \\ \text { P324 } \end{array}$ | - | D | JTAG test data input pin General-purpose output port |
| 113 | TMS | - | E | JTAG test mode state input pin |
| 114 | TCK | - | E | JTAG test clock input pin |
| 115 | $\begin{aligned} & \text { P327 } \\ & \text { WOT } \end{aligned}$ |  | Q | General-purpose I/O port RTC output pin |
| 116 | NMIX | - | F | Non-maskable interrupt input pin |
| 117 | MD | - | C | Mode pin |
| 118 | X0 | - | G | Main clock oscillation input pin |
| 119 | X1 | - | G | Main clock oscillation output pin |
| 121 | $\begin{aligned} & \hline \text { P331 } \\ & \text { MCSX3 } \\ & \text { SGA0_1 } \end{aligned}$ |  | Q | General-purpose I/O port External bus interface chip select 3 output pin Sound generator ch. 0 SGA output pin (1) |
| 122 | P400 <br> MCSX2 <br> SGO0_1 |  | Q | General-purpose I/O port External bus interface chip select 2 output pin Sound generator ch. 0 SGO output pin (1) |
| 123 | RSTX | N | F | External reset input pin |
| 127 | $\begin{array}{\|l} \hline \text { P401 } \\ \text { TX1_0 } \\ \text { INO_0 } \end{array}$ |  | Q | General-purpose I/O port CAN transmission data 1 output pin (0) Input capture ch. 0 input pin (0) |


| Pin No. | Pin Name | Polarity | I/O Circuit Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 128 | $\begin{array}{\|l} \hline \text { P402_ } \\ \text { INT2_0 } \\ \text { RX1_0 } \\ \text { IN1_0 } \\ \text { V3 } \end{array}$ |  | L | General-purpose I/O port (Input only. No output.) INT2 external interrupt input pin (0) CAN reception data 1 input pin (0) Input capture ch. 1 input pin (0) LCDC reference voltage V3 input pin |
| 129 | $\begin{aligned} & \text { P403 } \\ & \text { IN2_0 } \\ & \text { TRACEDATA0 } \\ & \text { V2 } \\ & \text { SGA1_1 } \end{aligned}$ |  | B | General-purpose I/O port <br> Input capture ch. 2 input pin (0) <br> Trace data 0 output pin <br> LCDC reference voltage V2 input pin <br> Sound generator ch. 1 SGA output pin (1) |
| 130 | P404 SCS120_0 IN3_0 TRACEDATA1 MAD14 V1 SGO1_1 | - | B | General-purpose I/O port <br> Multi-function serial ch. 12 serial chip select 0 I/O pin (0) <br> Input capture ch. 3 input pin (0) <br> Trace data 1 output pin <br> External bus interface address bit14 output pin <br> LCDC reference voltage V1 input pin <br> Sound generator ch. 1 SGO output pin (1) |
| 131 | P405 <br> INT11_0 <br> SIN12_0 <br> IN4_0 <br> TRĀCEDATA2 <br> MAD13 <br> V0 <br> SGA2_1 |  | B | General-purpose I/O port <br> INT11 external interrupt input pin (0) <br> Multi-function serial ch. 12 serial data input pin (0) <br> Input capture ch. 4 input pin (0) <br> Trace data 2 output pin <br> External bus interface address bit13 output pin <br> LCDC reference voltage V0 input pin <br> Sound generator ch. 2 SGA output pin (1) |
| 132 | $\begin{aligned} & \hline \text { P406 } \\ & \text { SOT12_0 } \\ & \text { TRACEDATA3 } \\ & \text { MAD12 } \\ & \text { COM0 } \\ & \text { SGO2_1 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 12 serial data output pin (0) <br> Trace data 3 output pin <br> External bus interface address bit12 output pin LCDC segment(duty) common 0 output pin Sound generator ch. 2 SGO output pin (1) |
| 133 | $\begin{aligned} & \hline \text { P407 } \\ & \text { SCK12_0 } \\ & \text { SCK10_1 } \\ & \text { TRACEDATA4 } \\ & \text { MAD11 } \\ & \text { COM1 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 12 clock I/O pin (0) <br> Multi-function serial ch. 10 clock I/O pin (1) <br> Trace data 4 output pin <br> External bus interface address bit11 output pin <br> LCDC segment(duty) common 1 output pin |
| 134 | $\begin{aligned} & \text { P408 } \\ & \text { SIN2_0 } \\ & \text { TRACEDATA5 } \\ & \text { TIN18 } \\ & \text { MAD10 } \\ & \text { COM2 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 2 serial data input pin (0) <br> Trace data 5 output pin <br> Reload timer ch. 18 event input pin (0) <br> External bus interface address bit10 output pin <br> LCDC segment(duty) common 2 output pin |
| 135 | $\begin{aligned} & \hline \text { P409 } \\ & \text { SOT2_0 } \\ & \text { TIOA24_1 } \\ & \text { TRACEDATA6 } \\ & \text { TOT18 } \\ & \text { MAD09 } \\ & \text { COM3 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 2 serial data output pin (0) <br> Base timer ch. 24 TIOA output pin (1) <br> Trace data 6 output pin <br> Reload timer ch. 18 output pin (0) <br> External bus interface address bit9 output pin <br> LCDC segment(duty) common 3 output pin |


| Pin No. | Pin Name | Polarity | I/O Circuit Type | Function |
| :---: | :---: | :---: | :---: | :---: |
| 136 | P411 <br> INT13_1 <br> SCK2_0 <br> SCS101_1 <br> TIOB24_0 <br> TRACEDATA7 <br> TIN19 <br> MAD08 <br> SEG0 |  | K | General-purpose I/O port <br> INT13 external interrupt input pin (1) <br> Multi-function serial ch. 2 clock I/O pin (0) <br> Multi-function serial ch. 10 serial chip select 1 output pin (1) <br> Base timer ch. 24 TIOB input pin (0) <br> Trace data 7 output pin <br> Reload timer ch. 19 event input pin (0) <br> External bus interface address bit8 output pin <br> LCDC segment 0 (Duty) output pin |
| 137 | P413 <br> INT14_1 <br> SCS20_0 <br> SCS103_1 <br> TOT19 <br> MAD07 <br> SEG1 |  | K | General-purpose I/O port <br> INT14 external interrupt input pin (1) <br> Multi-function serial ch. 2 serial chip select 0 I/O pin (0) <br> Multi-function serial ch. 10 serial chip select 3 output pin (1) <br> Reload timer ch. 19 output pin (0) <br> External bus interface address bit7 output pin <br> LCDC segment 1 (Duty) output pin |
| 138 | $\begin{aligned} & \text { P414 } \\ & \text { SCS21_0 } \\ & \text { TIN32 } \\ & \text { MAD06 } \\ & \text { SEG2 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 2 serial chip select 1 output pin (0) <br> Reload timer ch. 32 event input pin (0) <br> External bus interface address bit6 output pin <br> LCDC segment 2 (Duty) output pin |
| 139 | $\begin{aligned} & \text { P416 } \\ & \text { SIN10_1 } \\ & \text { IN5_0 } \\ & \text { TIOA22_1 } \\ & \text { TOT32_ } \\ & \text { MAD05 } \\ & \text { SEG3 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 10 serial data input pin (1) Input capture ch. 5 input pin (0) <br> Base timer ch. 22 TIOA output pin (1) <br> Reload timer ch. 32 output pin (0) <br> External bus interface address bit5 output pin LCDC segment 3 (Duty) output pin |
| 140 | P417 <br> INT15_1 <br> SOT10_1 <br> TIOA23_1 <br> TIN33 <br> MAD04 <br> SEG4 |  | K | General-purpose I/O port <br> INT15 external interrupt input pin (1) <br> Multi-function serial ch. 10 serial data output pin (1) <br> Base timer ch. 23 TIOA I/O pin (1) <br> Reload timer ch. 33 event input pin (0) <br> External bus interface address bit4 output pin <br> LCDC segment 4 (Duty) output pin |
| 141 | $\begin{aligned} & \text { P418 } \\ & \text { INT14_0 } \\ & \text { SCS22_0 } \\ & \text { TIOB23_0 } \\ & \text { TOT33 } \\ & \text { MAD03 } \\ & \text { SEG5 } \end{aligned}$ |  | K | General-purpose I/O port <br> INT14 external interrupt input pin (0) <br> Multi-function serial ch. 2 serial chip select 2 output pin (0) <br> Base timer ch. 23 TIOB input pin (0) <br> Reload timer ch. 33 output pin (0) <br> External bus interface address bit3 output pin <br> LCDC segment 5 (Duty) output pin |
| 142 | $\begin{aligned} & \text { P420 } \\ & \text { SCK2_1 } \\ & \text { TRACECLK } \\ & \text { MAD02 } \\ & \text { SEG6 } \end{aligned}$ |  | K | General-purpose I/O port <br> Multi-function serial ch. 2 clock I/O pin (1) <br> Trace clock <br> External bus interface address bit2 output pin LCDC segment 6 (Duty) output pin |
| 143 | P421 <br> INT12_1 <br> SIN2_1 <br> TRACECTL MAD01 SEG7 |  | K | General-purpose I/O port INT12 external interrupt input pin (1) Multi-function serial ch. 2 serial data input pin (1) Trace control External bus interface address bit1 output pin LCDC segment 7 (Duty) output pin |
| 42 | AVCCO | - | - | Analog power supply pin for AD converter unit 0 |



## 4. I/O Circuit Types

This section explains I/O circuit types.

| Type | Circuit | Overview |
| :---: | :---: | :---: |
| A |  | - General-purpose I/O port with analog input <br> - Output of 1 mA or 2 mA selectable <br> - $50 \mathrm{k} \Omega$ with pull-up resistor control <br> - $50 \mathrm{k} \Omega$ with pull-down resistor control <br> - CMOS hysteresis input |
| B |  | - General-purpose I/O port with analog input <br> - Output of 1 mA or 2 mA selectable <br> - $50 \mathrm{k} \Omega$ with pull-up resistor control <br> - $50 \mathrm{k} \Omega$ with pull-down resistor control <br> - Automotive/CMOS hysteresis input selectable |
| C |  | - Mode input <br> - CMOS hysteresis input |
| D |  | - JTAG <br> - General-purpose output port <br> - Output of 2 mA <br> - $50 \mathrm{k} \Omega$ with pull-up resistor control <br> - TTL input |


| Type | Circuit | Overview |
| :---: | :---: | :---: |
| E |  | - JTAG <br> - $50 \mathrm{k} \Omega$ with pull-up resistor control <br> - TTLinput |
| F |  | - CMOS hysteresis input <br> - $50 \mathrm{k} \Omega$ with pull-up resistor |
| G |  | - Main oscillation I/O |
| 1 |  | - JTAG <br> - Output of 2 mA |
| J |  | - JTAG <br> - General-purpose output port <br> - Output of 2 mA <br> - $50 \mathrm{k} \Omega$ with pull-down resistor control <br> - TTLinput |


| Type | Circuit | Overview |
| :---: | :---: | :---: |
| K |  | - General-purpose I/O port with COM/SEG output <br> - Output of 1 mA or 2 mA selectable <br> - $50 \mathrm{k} \Omega$ with pull-up resistor control <br> - $50 \mathrm{k} \Omega$ with pull-down resistor control <br> - Automotive/CMOS hysteresis input selectable |
| L |  | - General-purpose I/O port with LCDC V3 input <br> - $50 \mathrm{k} \Omega$ with pull-up resistor control <br> - $50 \mathrm{k} \Omega$ with pull-down resistor control <br> - Automotive/СМOS hysteresis input selectable |
| M |  | - General-purpose I/O port with analog input <br> - Output of 1 mA or 2 mA or 30 mA selectable <br> - $50 \mathrm{k} \Omega$ with pull-up resistor control <br> - $50 \mathrm{k} \Omega$ with pull-down resistor control <br> - Automotive/СМOS hysteresis input selectable |
| Q |  | - General-purpose I/O port <br> - Output of 1 mA or 2 mA selectable <br> - $50 \mathrm{k} \Omega$ with pull-up resistor control <br> - $50 \mathrm{k} \Omega$ with pull-down resistor control <br> - Automotive/СМOS hysteresis input selectable |


| Type | Circuit | Overview |
| :---: | :---: | :---: |
| R |  | - Output of 2 mA |
|  |  |  |
|  |  |  |
|  |  |  |
|  |  |  |

## 5. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

### 5.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

## Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

## Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.
Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.
No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

## Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.
(1) Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.
(2) Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.
Therefore, avoid this type of connection.
(3) Handling of Unused Input Pins

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

## Latch-Up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.
CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:
(1) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
(2) Be sure that abnormal current flows do not occur during the power-on sequence.

## Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

## Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

## Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).
CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

### 5.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

## Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.
Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.
If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

## Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.
You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

## Lead-Free Packaging

CAUTION: When ball grid array (BGA) packages with $\mathrm{Sn}-\mathrm{Ag}-\mathrm{Cu}$ balls are mounted using $\mathrm{Sn}-\mathrm{Pb}$ eutectic soldering, junction strength may be reduced under some conditions of use.

## Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:
(1) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
(2) Use dry boxes for product storage. Products should be stored below $70 \%$ relative humidity, and at temperatures between $5^{\circ} \mathrm{C}$ and $30{ }^{\circ} \mathrm{C}$.
When you open Dry Package that recommends humidity 40 \% to $70 \%$ relative humidity.
(3) When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
(4) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

## Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.
Condition: $125^{\circ} \mathrm{C} / 24 \mathrm{~h}$

## Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:
(1) Maintain relative humidity in the working environment between $40 \%$ and $70 \%$.

Use of an apparatus for ion generation may be needed to remove electricity.
(2) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
(3) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 $\mathrm{M} \Omega$ ).
Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
(4) Ground all fixtures and instruments, or protect with anti-static measures.
(5) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

### 5.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.
For reliable performance, do the following:
(1) Humidity

Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.
(2) Discharge of Static Electricity

When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.
(3) Corrosive Gases, Dust, or Oil

Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.
(4) Radiation, Including Cosmic Radiation

Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.
(5) Smoke, Flame

CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

## 6. Handling Devices

## For Latch-Up Prevention

The latch-up phenomenon may occur on a CMOS IC in the following cases: the voltage applied to an input or output pin is higher than $\mathrm{V}_{\mathrm{cc}}$ or lower than $\mathrm{V}_{\text {ss }}$; or the voltage applied between a VCC pin and a VSS pin exceeds the rating. A latch-up causes a rapid increase in the power supply current, possibly resulting in thermal damage to an element. When using the device, take sufficient care not to exceed the maximum rating.
Also be careful that analog power supplies (AVCC0, AVCC1, AVRH0, and AVRH1) and analog inputs do not exceed the digital power supply (VCC) at the analog system power-on and power-off times. VCC and DVCC must be set to the same voltage.
The power-on sequence is as follows. Simultaneously turn on the digital supply voltage (VCC) and analog supply voltages (AVCCO, AVCC1, AVRH0, and AVRH1), and the power supply voltage of high-current output buffer pins (DVCC), or turn on the digital supply voltage (VCC) and then the analog supply voltages (AVCC0, AVCC1, AVRH0, and AVRH1), and the power supply voltage of highcurrent output buffer pins (DVCC).

## About Handling Unused Pins

Leaving unused input pins open may cause permanent damage from a malfunction or latch-up. Take measures for unused pins, such as pulling up or pulling down the voltage with resistors of 2 kiloohms or higher.
If there are any unused input/output pins, set them to the output state and then open them, or set them to the input state and handle them in the same way as input pins.

## About Power Supply Pins

If the device has multiple VCC and VSS pins, the device is designed in such a way that the pins that should be at the same potential are connected to each other inside the device to prevent malfunctions such as latch-up. However, to reduce unwanted emissions, prevent malfunctions of strobe signals caused by an increase of the ground level, and observe standards on total output current, be sure to connect all the VCC and VSS pins to the power source and ground externally. Also handle all the VSS power supply pins in this way as shown in the following diagram. If there are multiple VCC or VSS systems, the device does not operate normally even within the guaranteed operating range.

Figure 6-1 Pin Assignment


In addition, consider connecting with low impedance from the power supply source to the VCC and VSS of this device.
In the area close to this device, a ceramic capacitor having the capacitance larger than the capacitor of $C$ pin is recommended to use as a bypass capacitor between the VCC pin and the VSS pin.

## About the Crystal Oscillation Circuit

Noise entering the X0 or X1 pin may cause a malfunction. Design the printed circuit board in such a way that the X0 and X1 pins, the crystal oscillator (or ceramic resonator), and a bypass capacitor to ground are located very close to the device.
We recommend that the printed circuit board artwork have the X0 and X1 pins enclosed by ground.

## About the Mode Pin (MD)

Use mode pin MD by directly connecting it to a VCC or VSS pin. To prevent noise from causing the device to accidentally enter test mode, reduce the pattern length between each mode pin and a VCC or VSS pin on the printed circuit board, and connect them with low impedance.

## About the Power-on Time

To prevent a malfunction of the voltage step-down circuit built in the device, the voltage rising must be monotonic during power-on

## Point to Note during PLL Clock Operation

While a PLL clock is selected, if the oscillator breaks off or input stops, the PLL clock may continue operating with the free running frequency of the internal self-oscillator circuit. This operation is outside of the guaranteed range.

## Power Supply Pin Processing of an A/D Converter

Even when no A/D converter is used, establish a connection such that $A V C C=A V R H=V C C$ and $A V S S$ AVSSS/AVRL $=V S S$.

## Points to Note About Using External Clocks

External clocks are not supported.
External direct clock input cannot be used.

## Power-on Sequence of the Power Supply Analog Inputs of an A/D Converter

Be sure to turn on the digital power supply (VCC) before the application of the power supplies (AVCC, AVRH, and AVRL) and analog inputs (AN3, AN5 to AN6, AN9 to AN10, AN12 to AN15, AN17 to AN24, AN27 to AN43, AN46 to AN53, and AN55 to AN62) of an A/D converter.
At the power-off time, turn off the power supplies and analog inputs of the A/D converter, and then turn off the digital power supply (VCC). Perform these power-on and power-off operations without AVRH exceeding AVCC. Even when using a pin shared with an analog input as an input port, do not allow the input voltage to exceed AVCC. (Turning on or off the analog supply voltage and digital supply voltage simultaneously is not a problem.)

## Treatment of Power supplies for High Current Output Buffer Pins (DVCC, DVSS)

Be sure to turn on the digital power supply voltage (VCC) first, and then turn on the power supply voltage for high current output buffer pins (DVCC, DVSS). Also, turn off the power supplies for high current output buffer pins first, and then turn off the digital power supply voltage (VCC).
Even if the high current output buffer pins are used as general-purpose ports, the power supply voltage of high current output buffer pins (DVCC, DVSS) must be powered. (The power supplies of high current output buffer pins and the digital power supplies can be turned on or off simultaneously.)
Connect the pins to have DVCC $=$ VCC and DVSS $=$ VSS .

## About C Pin Processing

This device has a built-in voltage step-down circuit. Be sure to connect a capacitor to the C pin (pin 126 in S6J312xHzC* specifications) for internal stabilization of the device. For the standard values, see "Recommended operating conditions" in the latest data sheet.

[^0]
## Precautions on Designing a Mounting Substrate

Measures against heat generation from the package must be taken for the mounting substrate to observe the absolute maximum rating (operating temperature). Design a mounting substrate with 4 or more layers. Connect the back of the package stage and the substrate pad with solder paste. Arrange thermal via holes on the substrate pad. For detailed information about mount conditions, contact your sales representative.

## Notes on Writing to a Register Containing a Status Flag

In writing to a register containing a status flag (particularly an interrupt request flag, etc.) to control a function, it is important to take care not to accidentally clear the status flag.
Therefore, before the write operation, configure the status bit such that the flag is not cleared, and then set the control bit to the desired value.
Especially for control bits configured as a set of multiple bits, bit instructions cannot be used (bit instructions have only 1-bit access). In such cases, byte, half-word, or word access is used to write to the control bits and a status flag simultaneously. However, at this time, be careful not to accidentally clear bits other than the intended ones (the status flag bit in this case).
Note: Bit instructions take this point into account for registers that support bit-band units, so it does not need to be a concern. You need to take care when using bit instructions for registers that do not support bit-band units.

## 7. Block Diagram

This section provides block diagrams of the S6J3120 series.
Figure 7-1 S6J312xHzC* Block Diagram
*x: A/9, z: A/B


## 8. Memory Map

This section explains the memory map.
Figure 8-1 Memory Map(S6J312AHzC/9HzC*)


S6J3120 Series

ם Only the CPU core can access $0000 \_0000 \sim 01 F F$ FFFFF. Bus masters other than the CPU core cannot access the region.

- Internal area of CR5 complex ( 0000 _0000 ~ 01FF_FFFF) is mapped to AXI_SLAVE_COREO. All bus masters can access to internal area of CR5 complex via AXI_SLAVE_COREO.
- In each of the following memory area combinations, the areas are physically the same memory area.

1. TCM FLASH ( $\left.0 \times 00 \mathrm{~A} 0 \_0000-\right)$ and AXI FLASH MEMORY ( $0 \times 01$ A0_0000 -)
2. TCM FLASH Small Sector (0x009F_0000 -) and AXI FLASH MEMORY Small Sector (0x019F_0000-)
3. WORKFLASH (0x0E00_0000 -), WORKFLASH (0x0E20_0000 -), and WORKFLASH (0x0E30_0000-)

The ECC movement in TCM port is based on ECC setting inside the CPU.
$\square$ The differences between the TCM FLASH and AXI FLASH include the following.

| Function | TCM FLASH | AXI FLASH |
| :--- | :---: | :---: |
| High-speed Access Using Dedicated Bus | Applicable | Not applicable |
| Write and Erase | Not applicable <br> (Read-only) | Applicable |
| Read | Applicable | Applicable |

ㅁThe differences between WORKFLASH areas include the following.

| Area | Function |
| :--- | :--- |
| WORKFLASH Area 1 | Used in write operation (with ECC) |
| WORKFLASH Area 3 | Used in write operation (without ECC) |
| WORKFLASH Area 4 | Used in read operation |

$\square$ Terms are as follows.

| Term |  |
| :--- | :--- |
| TCM RAM | Main RAM |
| TCM FLASH | Program FLASH (TCM area) |
| AXI FLASH | Program FLASH (AXI area) <br> This is physically the same as the TCM FLASH. <br> SYSTEM RAM <br> AXI SLAVE CORE <br> SORKFLASH <br> BACKUP RAM <br> EBI MEMORY <br> HSSPIO MEMORY CPU control area <br> Peri area FLASH for work |
| APPS\#5 | Backup RAM |
| APPS\#7 | Memory for External bus interface |
| ERRCFG | Entire area for peripheral functions |
| BootROM | Part of area for peripheral functions |

## S6J312xHzC* Peripheral Map

* x: A/9, z:A/B

| START <br> Address | $\begin{aligned} & \hline \text { END } \\ & \text { Address } \end{aligned}$ | Group | Function | PPU No |
| :---: | :---: | :---: | :---: | :---: |
| B000_0000 | B010_7FFF |  | Reserved | - |
| B010_0000 | B010_03FF |  | EBI registers | 0 |
| B010_0400 | B010_0FFF |  | Reserved | - |
| B010_1000 | B010_13FF |  | DDR_HSSPI | 1 |
| B010_0400 | B010_7FFF |  | Reserved | - |
| B010_8000 | B010_80FF | SystemSRAM | SystemSRAM registers | - |
| B010_8100 | B02F_FFFF |  | Reserved | - |
| B030_0000 | B030_7FFF | SYSC1 | Sy stem Controller \#1 | - |
| B030_8000 | B03F_FFFF | SYSC1 | SWDT | - |
| B040_0000 | B040_7FFF | MEMORY_CONFIG_GROUP | IRC0 | 21 |
| B040_8000 | B040_FFFF | MEMORY_CONFIG_GROUP | TPU0 | 19 |
| B041_0000 | B041_0FFF | MEMORY_CONFIG_GROUP | TCRAM Control Status Register | 16 |
| B041_1000 | B041_1FFF | MEMORY_CONFIG_GROUP | TCFlash Control Status Register | 17 |
| B041_2000 | B041_20FF | MEMORY_CONFIG_GROUP | WFlash Control Status Register | 18 |
| B041_2100 | B04F_FFFF |  | Reserved | - |
| B050_0000 | B05F_FFFF |  | Reserved | - |
| B060_0000 | B060_007F | MCU_CONFIG_GROUP | Protection register area |  |
| B060_0080 | B060_00FF | MCU_CONFIG_GROUP | RUN profile register area | - |
| B060_0100 | B060_017F | MCU_CONFIG_GROUP | PSS profile register area |  |
| B060_0180 | B060_01FF | MCU_CONFIG_GROUP | APP profile register area |  |
| B060_0200 | B060_027F | MCU_CONFIG_GROUP | STS profile register area |  |
| B060_0280 | B060_02FF | MCU_CONFIG_GROUP | System register area | - |
| B060_0300 | B060_037F | MCU_CONFIG_GROUP | CSV |  |
| B060_0380 | B060_03FF | MCU_CONFIG_GROUP | RESET |  |
| B060_0400 | B060_047F | MCU_CONFIG_GROUP | SCT(Fast CR) | 34 |
| B060_0480 | B060_04FF | MCU_CONFIG_GROUP | SCT(Slow CR) | 33 |
| B060_0500 | B060_05FF | MCU_CONFIG_GROUP | SCT(Main clock) | 35 |
| B060_0600 | B060_067F | MCU_CONFIG_GROUP | Clock Sy stem |  |
| B060_0680 | B060_06FF | MCU_CONFIG_GROUP | Special register area |  |
| B060_0700 | B060_07FF | MCU_CONFIG_GROUP | Debug register area | - |
| B060_0800 | B060_BFFF | MCU_CONFIG_GROUP | Mode | - |
| B060_C000 | B060_FFFF | MCU_CONFIG_GROUP | HWDT | - |
| B061_0000 | B061_7FFF |  | Reserved | - |
| B061_8000 | B061_FFFF | MCU_CONFIG_GROUP | RTC | 32 |
| B062_0000 | B063_FFFF | MCU_CONFIG_GROUP | EIC |  |
| B064_0000 | B065_FFFF |  | Reserved | - |
| B066_0000 | B067_FFFF |  | Reserved | - |
| B068_0000 | B068_7FFF | MCU_CONFIG_GROUP | BURAMIF |  |
| B068_8000 | B068_83FF | MCU_CONFIG_GROUP | EICU | 37 |
| B068_8400 | B068_87FF | MCU_CONFIG_GROUP | CR_Calibration | 38 |
| B068_8800 | B068_8BFF | MCU_CONFIG_GROUP | IRQ ALL | 42 |
| B068_8C00 | B068_FFFF | MCU_CONFIG_GROUP | CAN Prescaler | 43 |
| B069_0000 | B06F_FFFF |  | Reserved | - |
| B070_0000 | B07F_FFFF |  | Reserved | - |
| B080_0000 | B0FF_FFFF | Bit RMW alias | BBU for MCU Config (Covers B060_0000 -- B06F_FFFF) | - |
| B100_0000 | B10F_FFFF | Bit RMW alias | BBU for SYSC1 (Covers B030_0000 -- B031_FFFF) | - |
| B110_0000 | B11F_FFFF | Bit RMW alias | BBU for MEMC (Covers B040_0000 -- B041_FFFF) | - |
| B120_0000 | B1FF_FFFF |  | Reserved | - |
| B200_0000 | B20F_FFFF | SHE | SHE configuration registers | 63 |
| B210_0000 | B46F_FFFF |  | Reserved | - |

S6J3120 Series

| START <br> Address | END Address | Group | Function | PPU No |
| :---: | :---: | :---: | :---: | :---: |
| B470_0000 | B470_3FFF | CommonPERI \#2 | DMAC \#0 registers | 64 |
| B470_4000 | B470_FFFF |  | Reserved | - |
| B471_0000 | B471_0FFF | CommonPERI \#2 | MPU for DMAC\#0 | 66 |
| B471_1000 | B471_3FFF |  | Reserved | - |
| B471_4000 | B471_4FFF | CommonPERI \#2 | DMA Complex \#0 registers (Additional registers, RLTs) | 68 |
| B471_5000 | B471_7FFF |  | Reserved | - |
| B471_8000 | B471_83FF | CommonPERI \#2 | CRC\#0 | 70 |
| B471_8400 | B471_87FF | CommonPERI \#2 | CRC\#1 | 71 |
| B471_8800 | B471_8BFF | CommonPERI \#2 | CRC\#2 | 72 |
| B471_8C00 | B471_8FFF | CommonPERI \#2 | CRC\#3 | 73 |
| B471_9000 | B473_7FFF |  | Reserved | - |
| B473_8000 | B473_FFFF | CommonPERI \#2 | GPIO | 74 |
| B474_0000 | B474_7FFF | CommonPERI \#2 | PPC | 75 |
| B474_8000 | B474_FFFF | CommonPERI \#2 | RIC | 76 |
| B475_0000 | B475_7FFF | CommonPERI \#2 | PPU |  |
| B475_8000 | B478_7FFF |  | Reserved | - |
| B478_8000 | B478_83FF | CommonPERI \#2 | Reload Timer ch. 32 | 160 |
| B478_8400 | B478_87FF | CommonPERI \#2 | Reload Timer ch. 33 | 161 |
| B478_8800 | B478_FBFF |  | Reserved | - |
| B478_FC00 | B478_FFFF | CommonPERI \#2 | Misc registers | 82 |
| B479_0000 | B47F_FFFF |  | Reserved | - |
| B480_0000 | B480_03FF | CommonPERI \#0 | M.F.Serial ch. 0 | 176 |
| B480_0400 | B480_07FF | CommonPERI \#0 | M.F.Serial ch. 1 | 177 |
| B480_0800 | B480_0BFF | CommonPERI \#0 | M.F.Serial ch. 2 | 178 |
| B480_0C00 | B480_0FFF | CommonPERI \#0 | M.F.Serial ch. 3 | 179 |
| B480_1000 | B480_13FF | CommonPERI \#0 | M.F.Serial ch. 4 | 180 |
| B480_1400 | B480_7FFF |  | Reserved | - |
| B480_8000 | B480_83FF | CommonPERI \#0 | BaseTimer ch. 0 | 88 |
| B480_8400 | B480_87FF | CommonPERI \#0 | BaseTimer ch. 1 | 89 |
| B480_8800 | B480_8BFF | CommonPERI \#0 | BaseTimer ch. 2 | 90 |
| B480_8C00 | B480_8FFF | CommonPERI \#0 | BaseTimer ch. 3 | 91 |
| B480_9000 | B480_93FF | CommonPERI \#0 | BaseTimer ch. 4 | 92 |
| B480_9400 | B480_97FF | CommonPERI \#0 | BaseTimer ch. 5 | 93 |
| B480_9800 | B480_9BFF | CommonPERI \#0 | BaseTimer ch. 6 | 94 |
| B480_9C00 | B480_9FFF | CommonPERI \#0 | BaseTimer ch. 7 | 95 |
| B480_A000 | B480_A3FF | CommonPERI \#0 | BaseTimer ch. 8 | 96 |
| B480_A400 | B480_A7FF | CommonPERI \#0 | BaseTimer ch. 9 | 97 |
| B480_A800 | B480_ABFF | CommonPERI \#0 | BaseTimer ch. 10 | 98 |
| B480_AC00 | B480_AFFF | CommonPERI \#0 | BaseTimer ch. 11 | 99 |
| B480_B000 | B480_FFFF |  | Reserved |  |
| B481_0000 | B481_03FF | CommonPERI \#0 | Reload Timer ch. 0 | 128 |
| B481_0400 | B481_07FF | CommonPERI \#0 | Reload Timer ch. 1 | 129 |
| B481_0800 | B481_0BFF | CommonPERI \#0 | Reload Timer ch. 2 | 130 |
| B481_0C00 | B481_0FFF | CommonPERI \#0 | Reload Timer ch. 3 | 131 |
| B481_1000 | B481_FFFF |  | Reserved |  |
| B482_0000 | B482_03FF | CommonPERI \#0 | FRT ch. 0 | 208 |
| B482_0400 | B482_07FF | CommonPERI \#0 | FRT ch. 1 | 209 |
| B482_0800 | B482_0BFF | CommonPERI \#0 | FRT ch. 2 | 210 |
| B482_0C00 | B482_0FFF | CommonPERI \#0 | FRT ch. 3 | 211 |
| B482_1000 | B482_13FF | CommonPERI \#0 | FRT ch. 4 | 212 |
| B482_1400 | B482_17FF | CommonPERI \#0 | FRT ch. 5 | 213 |
| B482_1800 | B482_7FFF |  | Reserved | - |
| B482_8000 | B482_83FF | CommonPERI \#0 | ICU ch.0 / ch. 1 | 224 |
| B482_8400 | B482_87FF | CommonPERI \#0 | ICU ch. $2 /$ ch. 3 | 225 |
| B482_8800 | B482_8BFF | CommonPERI \#0 | ICU ch. 4 / ch. 5 | 226 |
| B482_8C00 | B482_8FFF | CommonPERI \#0 | ICU ch. 6 / ch. 7 | 227 |
| B482_9000 | B482_93FF | CommonPERI \#0 | ICU ch. 8 / ch. 9 | 228 |
| B482_9400 | B482_97FF | CommonPERI \#0 | ICU ch. 10 / ch. 11 | 229 |
| B482_9800 | B482_FFFF |  | Reserved | - |

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| START <br> Address | $\begin{aligned} & \hline \text { END } \\ & \text { Address } \end{aligned}$ | Group | Function | PPU No |
| :---: | :---: | :---: | :---: | :---: |
| B483_0000 | B483_03FF | CommonPERI \#0 | OCU ch. 0 / ch. 1 | 240 |
| B483_0400 | B483_07FF | CommonPERI \#0 | OCU ch. 2 / ch. 3 | 241 |
| B483_0800 | B483_0BFF | CommonPERI \#0 | OCU ch. 4 / ch. 5 | 242 |
| B483_0C00 | B483_0FFF | CommonPERI \#0 | OCU ch. 6 / ch. 7 | 243 |
| B483_1000 | B483_13FF | CommonPERI \#0 | OCU ch. 8 / ch. 9 | 244 |
| B483_1400 | B483_17FF | CommonPERI \#0 | OCU ch. 10 / ch. 11 | 245 |
| B483_1800 | B483_FBFF |  | Reserved | - |
| B483_FC00 | B483_FFFF | Common PERI \#0 | M isc registers | 80 |
| B484_0000 | B484_FFFF | APPS \#5 | APPS\#5 area | - |
| B485_0000 | B487_FFFF |  | Reserved | - |
| B488_0000 | B488_03FF | CommonPERI\#1 | M.F.Serial ch. 8 | 184 |
| B488_0400 | B488_07FF | CommonPERI \#1 | M.F.Serial ch. 9 | 185 |
| B488_0800 | B488_0BFF | CommonPERI\#1 | M.F.Serial ch. 10 | 186 |
| B488_0C00 | B488_0FFF | CommonPERI\#1 | M.F.Serial ch. 11 | 187 |
| B488_1000 | B488_13FF | CommonPERI\#1 | M.F.Serial ch. 12 | 188 |
| B488_1400 | B488_FFFF |  | Reserved | - |
| B489_0000 | B489_03FF | CommonPERI \#1 | Reload Timer ch. 16 | 144 |
| B489_0400 | B489_07FF | CommonPERI \#1 | Reload Timer ch. 17 | 145 |
| B489_0800 | B489_0BFF | CommonPERI \#1 | Reload Timer ch. 18 | 146 |
| B489_0C00 | B489_0FFF | CommonPERI\#1 | Reload Timer ch. 19 | 147 |
| B489_1000 | B489_7FFF |  | Reserved | - |
| B489_8000 | B489_83FF | CommonPERI \#1 | QPRC ch. 8 | 200 |
| B489_8400 | B489_87FF | CommonPERI \#1 | QPRC ch. 9 | 201 |
| B489_8800 | B48B_0FFF |  | Reserved | - |
| B48B_1000 | B48B_FBFF |  | Reserved | - |
| B48B_FC00 | B48B_FFFF | CommonPERI \#1 | Misc registers | 81 |
| B48C_0000 | B48C_FFFF | APPS \#7 | APPS\#7 area | - |
| B48D_0000 | B48F_FFFF |  | Reserved | - |
| B490_0000 | B490_FFFF | CommonPERI \#0 | CAN_FD ch. 0 | 256 |
| B491_0000 | B491_FFFF | CommonPERI \#0 | CAN_FD ch. 1 | 257 |
| B492_0000 | B492_FFFF | CommonPERI \#0 | CAN_FD ch. 2 | 258 |
| B493_0000 | B4BF_FFFF |  | Reserved | - |
| B4C0_0000 | B4FF_FFFF | Bit RMW alias | BBU for CommonPERI\#0 (Covers B490_0000 -- B497_FFFF) | - |
| B500_0000 | B5FF_FFFF |  | Reserved | - |
| B600_0000 | B6FF_FFFF |  | Reserved | - |
| B700_0000 | B77F_FFFF | Bit RMW alias | BBU alias for CommonPERI\#2 (Covers B470_0000 -- B47F_FFFF) | - |
| B780_0000 | B7BF_FFFF | Bit RMW alias | BBU alias for CommonPERI\#0 (Covers B480_0000-- B487_FFFF) | - |
| B7C0_0000 | B7FF_FFFF | Bit RMW alias | BBU alias for CommonPERI\#1 (Covers B488_0000 -- B48F_FFFF) | - |
| B800_0000 | FFFE_DFFF |  | Reserved | - |
| FFFE_E000 | FFFE_FBFC | Error Config | IRC | - |
| FFFE_FC00 | FFFE_FFFF | Error Config | BootROM I/F | 20 |

■- APPS\#5 area

| START <br> Address | END <br> Address |  | Function | PPU No |
| :---: | :---: | :---: | :---: | :---: |
| B484_0000 | B484_03FF | APPS \#5 | Sound Generator ch. 0 | 264 |
| B484_0400 | B484_07FF | APPS \#5 | Sound Generator ch. 1 | 265 |
| B484_0800 | B484_0BFF | APPS \#5 | Sound Generator ch. 2 | 266 |
| B484_0C00 | B484_37FF |  | Reserved | - |
| B484_3800 | B484_3BFF | APPS \#5 | BaseTimer ch. 12 | 278 |
| B484_3C00 | B484_3FFF | APPS \#5 | BaseTimer ch. 13 | 279 |
| B484_4000 | B484_43FF | APPS \#5 | BaseTimer ch. 14 | 280 |
| B484_4400 | B484_47FF | APPS \#5 | BaseTimer ch. 15 | 281 |
| B484_4800 | B484_4BFF | APPS \#5 | BaseTimer ch. 16 | 282 |
| B484_4C00 | B484_4FFF | APPS \#5 | BaseTimer ch. 17 | 283 |
| B484_5000 | B484_53FF | APPS \#5 | BaseTimer ch. 18 | 284 |
| B484_5400 | B484_57FF | APPS \#5 | BaseTimer ch. 19 | 285 |
| B484_5800 | B484_5BFF | APPS \#5 | BaseTimer ch. 20 | 286 |
| B484_5C00 | B484_5FFF | APPS \#5 | BaseTimer ch. 21 | 287 |
| B484_6000 | B484_63FF | APPS \#5 | BaseTimer ch. 22 | 288 |
| B484_6400 | B484_67FF | APPS \#5 | BaseTimer ch. 23 | 289 |
| B484_6800 | B484_6BFF | APPS \#5 | BaseTimer ch. 24 | 290 |
| B484_6C00 | B484_6FFF | APPS \#5 | BaseTimer ch. 25 | 291 |
| B484_7000 | B484_73FF | APPS \#5 | BaseTimer ch. 26 | 292 |
| B484_7400 | B484_77FF | APPS \#5 | BaseTimer ch. 27 | 293 |
| B484_7800 | B484_7BFF | APPS \#5 | BaseTimer ch. 28 | 294 |
| B484_7C00 | B484_7FFF | APPS \#5 | BaseTimer ch. 29 | 295 |
| B484_8000 | B484_83FF | APPS \#5 | A/D unit0 | 296 |
| B484_8400 | B484_87FF | APPS \#5 | A/D unit 1, Partial Wake Up | 297 |
| B484_8800 | B484_8BFF | APPS \#5 | A/D analog input control | 298 |
| B484_8C00 | B484_8FFF |  | Reserved | - |
| B484_9000 | B484_93FF | APPS \#5 | Global Timer | 300 |
| B484_9400 | B484_FFFF |  | Reserved | - |

■- APPS\#7 area

| START <br> Address | END <br> Address |  |  |  |
| :--- | :--- | :--- | :--- | :--- |
| B48C_0000 | B48C_3FFF |  | Reserved | PPU No |
| B48C_4000 | B48C_43FF | APPS \#7 | Stepper Motor Control ch.0 | - |
| B48C_4400 | B48C_47FF | APPS \#7 | Stepper Motor Control ch.1 | 317 |
| B48C_4800 | B48C_4BFF | APPS \#7 | Stepper Motor Control ch.2 | 318 |
| B48C_4C00 | B48C_4FFF | APPS \#7 | Stepper Motor Control ch.3 | 319 |
| B48C_5000 | B48C_57FF |  | Reserved | 320 |
| B48C_5800 | B48C_5BFF | APPS \#7 | SMC Trigger Generator | - |
| B48C_5C00 | B48C_5FFF | APPS \#7 | Liquid Crystal Display Controller | 323 |
| B48C_6000 | B48C_63FF | APPS \#7 | Liquid Crystal Display input/output control | 3 |
| B48C_6400 | B48C_FFFF |  | Reserved | 324 |

When MPU attribute of Cortex ${ }^{\circledR}$-R5 is configured as "Normal", store buffer inside Cortex ${ }^{\circledR}$-R5 can operate and write data can be merged. To avoid influence of this data merger, MPU attribute "Device" or "Strongly Ordered" should be used.
MPU attribute "Device" or "Strongly Ordered" must be used for areas below, to avoid this influence.

- Backup RAM area (BACKUP_RAM) [0E80_0000 ~ 0E87_FFFF]
- Peripheral area (Peri area) [B000_0000 ~ B7FF_FFFF]
- Error Config area (ERRCFG) [FFFE_E000 ~ FFFE_FFFF]

MPU attribute "Device" or "Strongly Ordered" is required for accesses to areas below, in particular situation.

- FLASH Memory (when writing commands)

SHE OFF product is prohibited to access SHE area (B200_0000 to B20F_FFFF)

## 9. Pin Statuses In CPU Status

Table 9-1 Pin State Table (1/2)


Table 9-2 Pin State Table (2/2)

*1: Input disable is not valid when external interrupts are enabled.
*2: Recovery from standby (power off) becomes a factor.
*3: The pin state from the time that HOLDIO_PD2 was set (SYSCO_SPECFGR.HOLDIO_PD2 $=1$ ) is retained. If power-off has not occurred and HOLDIO_PD2 has not been set (SYSC0_SPECFGR.HOLDIO_PD2 = 0), the last state is retained.
*4: To power off power domains 2 and 3, be sure to set HOLDIO_PD2 (SYSC0_SPECFGR.HOLDIO_PD2 = 1).
*5: The pin state when the PORT function is enabled is shown.
*6: When Port is used as LCD setting, PIN state becomes the following.

| Power Domain 2 <br> Control | Power-Off | Power-on |  |  |
| :--- | :---: | :---: | :---: | :---: |
| mode | - | Except PSS Main <br> oscillation <br> Timer mode | PSS Main oscillation <br> Timer mode |  |
| Main oscillation <br> enable setting | - | - | enable (LCRO:LCEN = 1) | disable (LCR0:LCEN =0) |
| PIN state | Output "L" / <br> Input <br> blocked | Output "L" / <br> Input blocked | Retention of LCD display | Output "L" / <br> Input blocked |

*7: When the PWU function is enabled, a change to output occurs.
*8: When PPC_PCFGRijj:POF[2:0] is set to initial value.
*9: When reset is issued, the following ports become "L" output as the initial state.

- P019, P023, P024, P027, P028, P029, P030, P031, P100, P406, P407, P408, P409

Therefore, don't add the Pull-up registers outside of this product to the above ports.
In case that the above ports are used as Pull-up, use the Pull-up function implemented in this product.
-External Reset Factor 1
Power-on reset (PONR)
RAM retention low-voltage detection reset (RVD)
Internal power supply low-voltage detection reset (LVDL1R)
RSTX pin + MD pin simultaneous assert reset (INITX)
-External Reset Factor 2
RSTX pin input reset (RSTX)
-External Reset Factor 3
Hardware watchdog reset (HWDR)
Software watchdog reset (SWDR)
PLL clock supervisor reset (CSVPRn)
SSCG clock supervisor reset (CSVSRn)
Profile error reset (PRFERR)
Software trigger hard reset (SHRST)
Software reset (SRST)
-Internal Reset Factor
Standby transition reset/ Power domain reset

## 10. Electrical Characteristics

### 10.1 Absolute Maximum Ratings

| Parameter | Symbol | Rating |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Max |  |  |
| Power supply voltage ${ }^{* 1,{ }^{*} 2}$ | Vcc | Vss-0.3 | $\mathrm{V}_{\text {SS }}+6.0$ | V |  |
|  | DVcc | Vss-0.3 | Vss+6.0 | V | $D V_{c c}=V_{c c}$ |
| Analog supply voltage*1,*2 | AVcc | Vss-0.3 | $\mathrm{V}_{\mathrm{ss}}+6.0$ | V | $\mathrm{AV} \mathrm{cc}=\mathrm{Vcc}$ |
| Analog reference voltage*1 | AVRH | Vss-0.3 | Vss+6.0 | V | AVRH $\leq$ AV ${ }_{\text {cc }}$ |
| Input voltage*1 | $V_{11}$ | Vss-0.3 | $\mathrm{V}_{\mathrm{cc}}+0.3$ | V |  |
|  | $\mathrm{V}_{12}$ | DVss-0.3 | DVcc+0.3 | V | SMC shared pin |
| Analog pin input voltage ${ }^{* 1}$ | $\mathrm{V}_{\mathrm{IA} 1}$ | Vss-0.3 | $\mathrm{V}_{\mathrm{cc}}+0.3$ | V |  |
|  | $\mathrm{V}_{\text {IA2 }}$ | DVss-0.3 | DVCc +0.3 | V | SMC shared pin |
| Output voltage ${ }^{* 1}$ | Vo1 | Vss-0.3 | Vcc+0.3 | V |  |
|  | Vo2 | DVss-0.3 | DVcc+0.3 | V | SMC shared pin |
| Maximum clamp current | \|Iclamp| | - | 4 | mA | *8 |
| Total maximum clamp current | $\Sigma \mid$ Iclamp $\mid$ | - | 20 | mA | *8 |
| "L"-level maximum output current*3 | lol1 | - | 3.5 | mA | When setting is $1 \mathrm{~mA}^{* 6}$ |
|  | lol2 | - | 7 | mA | When setting is 2 mA |
|  | lol3 | - | 40 | mA | When setting is $30 \mathrm{~mA}^{* 7}$ |
| "L"-level average output current*4 | lolav1 | - | 1 | mA | When setting is $1 \mathrm{~mA}^{* 6}$ |
|  | lolav2 | - | 2 | mA | When setting is 2 mA |
|  | lolav3 | - | 30 | mA | When setting is $30 \mathrm{~mA}^{*} 7$ |
| "L"-level total output current*5 | EloL1 | - | 40 | mA | *6 |
|  | Elol2 | - | 150 | mA | *7 |
| " H "-level maximum output current ${ }^{* 3}$ | ІOH1 | - | -3.5 | mA | When setting is $1 \mathrm{~mA}^{* 6}$ |
|  | Іон2 | - | -7 | mA | When setting is 2 mA |
|  | Іонз | - | -40 | mA | When setting is $30 \mathrm{~mA}^{* 7}$ |
| " H "-level average output current ${ }^{*} 4$ | Іоhav1 | - | -1 | mA | When setting is $1 \mathrm{~mA}^{* 6}$ |
|  | Іоhav2 | - | -2 | mA | When setting is 2 mA |
|  | Іоhav3 | - | -30 | mA | When setting is $30 \mathrm{~mA}^{* 7}$ |
| "H"-level total output current*5 | ミloh1 | - | -40 | mA | *6 |
|  | £ ${ }_{\text {loh2 }}$ | - | -150 | mA | *7 |
| Power consumption | PD | - | 2000 | mW | S6J312xHzC*9 |
| Operating temperature | $\mathrm{T}_{\mathrm{A}}$ | -40 | +105 | ${ }^{\circ} \mathrm{C}$ |  |
| Storage temperature | Tstg | -55 | +150 | ${ }^{\circ} \mathrm{C}$ |  |

*1: These parameters are based on the condition that VSS = DVSS = AVSS $=0.0 \mathrm{~V}$.
*2: AVCC, DVCC and VCC must be set to the same voltage. It is required that AVCC and DVCC do not exceed VCC and that the voltage at the analog inputs does not exceed AVCC when the power is switched on.
*3: The maximum output current is defined as the value of the peak current flowing through any one of the corresponding pins.
*4: The average output current is defined as the value of the average current flowing through any one of the corresponding pins for a 10 ms period. The average value is the operation current X the operation ratio.
*5: The total output current is defined as the maximum current value flowing through all of corresponding pins.
*6: Corresponding pins: general-purpose ports
*7: Corresponding pins: P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317
*8: Corresponding pins: All general-purpose ports and analog input pins

- Use the device within the recommended operating conditions.
- Use the device with direct voltage (current).
- The + B signal should always be applied by connecting a limiting resistor between the +B signal and the microcontroller.
- The value of the limiting resistor should be set so that the current input to the microcontroller pin does not exceed rated values at any time regardless of instantaneously or constantly when the +B signal is input.
- Note that when the microcontroller drive current is low, such as in the low-power consumption modes, the $+B$ input potential can increase the potential at the VCC pin via a protective diode, possibly affecting other devices.
- Note that if the + B signal is input when the microcontroller is off (not fixed at 0 V ), since the power is supplied through the pin, the microcontroller may operate incompletely.
- Note that if the +B signal is input at power-on, since the power is supplied through the pin, the power-on reset may not function in the power supply voltage.
- Do not leave + B input pins open.
*9: It is standard when four-layer substrate is used.

Example of a recommended circuit


## WARNING:

- $\quad$ Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings. Do not exceed any of these ratings.


### 10.2 Recommended Operating Conditions

$$
\left(\mathrm{V}_{\mathrm{ss}}=\mathrm{DV} \mathrm{VS}_{\mathrm{ss}}=\mathrm{A} \mathrm{~V}_{\mathrm{sS}}=0.0 \mathrm{~V}\right)
$$

| Parameter | Symbol | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Max |  |  |
| Supply voltage | Vcc | 4.5 | 5.5 | V | Recommended operation assurance range |
|  | DVcc | 4.5 | 5.5 | V |  |
|  | AV cc | 4.5 | 5.5 | V |  |
|  | Vcc | 3.5 | 5.5 | V | Operation assurance range |
|  | DVcc | 3.5 | 5.5 | V |  |
|  | $\mathrm{AV}_{\text {cc }}$ | 3.5 | 5.5 | V |  |
| Smoothing capacitor* | Cs1 | 4.7 |  | $\mu \mathrm{F}$ | Tolerance of up to $\pm 40 \%, 126$ pin Use a ceramic capacitor or a capacitor that has the similar frequency characteristics. <br> Use a capacitor with a capacitance greater than CS as the smoothing capacitor on the VCC pin. |
| Operating temperature | $\mathrm{T}_{\text {A }}$ | -40 | +105 | ${ }^{\circ} \mathrm{C}$ | $\begin{aligned} & \text { S6J312xHzC* } \\ & \text { * x:A/9, z:A/B } \end{aligned}$ |

*: For the connections of smoothing capacitor Cs1, see the following diagram.

## - C Pin Connection Diagram



## WARNING:

1. The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.
2. Any use of semiconductor devices will be under their recommended operating condition.
3. Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.
4. No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

## Notes:

- $\quad$ The following condition should be satisfied in order to facilitate heat dissipation.

1. 4 or more layers $P C B$ should be used.
2. The area of $P C B$ should be $114.3 \mathrm{~mm} \times 76.2 \mathrm{~mm}$ or more, and the thickness should be 1.6 mm or more. (JEDEC standard)
3. 1 layer of middle layers at least should be used for dedicated layer to radiate heat with residual copper rate $90 \%$ or more. The layer can be used for system ground.
4. $35 \sim 50 \%$ of the die stage area which is exposed at back surface of package should be soldered to a part of $1^{\text {st }}$ layer.
5. The part of $1^{\text {st }}$ layer should be connected to the dedicated heat radiation layer with more than 10 thermal via holes.

Figure10.2-1: Example thermal via holes on PCB.


## Notes:

- Figure 10.2-1 is a schematic diagram showing PCB in section.
- Figure 10.2-2 in the following pages are recommended land patterns for each package series. Thermal via holes should closely be placed and aligned with lands.
- If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

Figure 10.2-2: Land Pattern and Thermal Via LEU144


### 10.3 DC Characteristics

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{SS}}=\mathrm{DV}_{\mathrm{SS}}=\mathrm{AV}$ SS $=0.0 \mathrm{~V}$ )

| Parameter | Symbo I | Pin Name | Conditions | Value |  |  | Unit | Remark s |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| "H" level input voltage | $\mathrm{V}_{\text {IH1 }}$ | P000 to P001, P003, P005 to P010, P012 to P013, P015 to P024, <br> P027 to P031, P100 to P101, P103, <br> P105 to P109, P112 to P115, P117 to P120, P122 to P123, P126 to P131, P202 to P215, P218 to P220, P222 to P226, P327, P331, P400 to P409, P411, P413 to P414, P416 to P418, P420 to P421 | CMOS <br> Schmitt input level selected | $0.7 \times V_{\text {cc }}$ | - | $\mathrm{V}_{\mathrm{cc}}+0.3$ | V |  |
|  |  | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 |  | $0.7 \times \mathrm{DV}_{\text {cc }}$ | - | DV ${ }_{\text {cc }}+0.3$ | V |  |
| "H" level input voltage | $\mathrm{V}_{1+2}$ | P000 to P001, P003, P005 to P010, <br> P012 to P013, P015 to P024, P027 to P031, P100 to P101, P103, <br> P105 to P109, P112 to P115, P117 to P120, P122 to P123, P126 to P131, P202 to P215, P218 to P220, P222 to P226, P327 to P331 P400 to P409, P411, P413 to P414, P416 to P418, P420 to P421 | Automotive input level selected | $0.8 \times \mathrm{V}_{\text {cc }}$ | - | $\mathrm{V}_{\mathrm{cc}}+0.3$ | V |  |
|  |  | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 |  | $0.8 \times \mathrm{DV} \mathrm{cc}$ | - | DV $\mathrm{cc}^{+}+0.3$ | V |  |
|  | $\mathrm{V}_{\text {IH4 }}$ | RSTX, NMIX | - | $0.7 \times V_{\text {cc }}$ | - | $\mathrm{V}_{\mathrm{cC}}+0.3$ | V |  |
|  | $\mathrm{V}_{\text {H55 }}$ | MD | - | $0.7 \times V_{\text {cc }}$ | - | $\mathrm{V}_{\mathrm{cc}}+0.3$ | V |  |
|  | $\mathrm{V}_{\text {IH6 }}$ | TRST, TCK, TDI, TMS | TTL input level | 2.3 | - | $\mathrm{V}_{\mathrm{cc}}+0.3$ | V |  |
| "L" level input voltage | $\mathrm{V}_{\text {LL }}$ | P000 to P001, P003, P005 to P010, <br> P012 to P013, P015 to P024, P027 to P031, P100 to P101, P103, <br> P105 to P109, P112 to P115, P117 to P120, P122 to P123, P126 to P131, P202 to P215, P218 to P220, P222 to P226, P327 to P331, P400 to P409, P411, <br> P413 to P414, P416 to P418, P420 to P421 | cMOS <br> Schmitt input level selected | Vss-0.3 | - | $0.3 \times V_{\text {cc }}$ | V |  |
|  |  | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 |  | DVss-0.3 | - | $0.3 \times \mathrm{DV}$ cc | V |  |

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{ss}}=\mathrm{DV} \mathrm{ss}=\mathrm{AV} \mathrm{ss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| "L" level input voltage | $\mathrm{V}_{\text {IL2 }}$ | P000 to P001, P003, P005 to P010, P012 to P013, P015 to P024, <br> P027 to P031, P100 to P101, P103, <br> P105 to P109, P112 to P115, <br> P117 to P120, P122 to P123, <br> P126 to P131, P202 to P215, <br> P218 to P220, P222 to P226, P327, <br> P331, P400 to P409, P411, <br> P413 to P414, P416 to P418, <br> P420 to P421 | Automotive input level selected | Vss-0.3 | - | $0.5 \times \mathrm{Vcc}$ | V |  |
|  |  | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 |  | DVss-0.3 | - | $0.5 \times \mathrm{DVcc}$ | V |  |
|  | $\mathrm{V}_{\text {IL4 }}$ | RSTX, NMIX | - | Vss-0.3 | - | $0.3 \times \mathrm{Vcc}$ | V |  |
|  | $\mathrm{V}_{\text {IL5 }}$ | MD | - | Vss-0.3 | - | $0.3 \times \mathrm{Vcc}$ | V |  |
|  | $\mathrm{V}_{\text {IL6 }}$ | TRST, TCK, TDI, TMS | TTL input level | Vss-0.3 | - | 0.8 | V |  |
| " H " level output voltage | $\mathrm{V}_{\text {OH1 }}$ | P000 to P001, P003, P005 to P010, P012 to P013, P015 to P024, P027 to P031, P100 to P101, P103, P105 to P109, P112 to P115, P117 to P120, P122 to P123, P126 to P131, P202 to P215, P218 to P220, P222 to P226, P321 to P324, P327, P331, P400 to P401, P403 to P409, P411, P413 to P414, P416 to P418, P420 to P421 | $\begin{gathered} \mathrm{Vcc}=4.5 \mathrm{~V} \\ \mathrm{I}_{\mathrm{OH}}=-2.0 \mathrm{~mA} \end{gathered}$ | Vcc-0.5 | - | Vcc | V |  |
|  |  | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 | $\begin{aligned} & \mathrm{DVcc}=4.5 \mathrm{~V} \\ & \mathrm{I}_{\mathrm{OH}}=-2.0 \mathrm{~mA} \end{aligned}$ | DVcc-0.5 | - | DVcc | V |  |
| "H" level output voltage | $\mathrm{V}_{\mathrm{OH} 2}$ | $\begin{aligned} & \text { P000 to P001, P003, P005 to P010, } \\ & \text { P012 to P013, P015 to P024, } \\ & \text { P027 to P031, P100 to P101, P103, } \\ & \text { P105 to P109, P112 to P115, } \\ & \text { P117 to P120, P122 to P123, } \\ & \text { P126 to P131, P202 to P215, } \\ & \text { P218 to P220, P222 to P226, } \\ & \text { P321 to P324, P327, P331, } \\ & \text { P400 to P401, P403 to P409, P411, } \\ & \text { P413 to P414, P416 to P418, } \\ & \text { P420 to P421 } \end{aligned}$ | $\begin{gathered} \mathrm{Vcc}=4.5 \mathrm{~V} \\ \mathrm{I}_{\mathrm{OH}}=-1.0 \mathrm{~mA} \end{gathered}$ | Vcc-0.5 | - | Vcc | V |  |
|  |  | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 | $\begin{aligned} & \mathrm{DVcc}=4.5 \mathrm{~V} \\ & \mathrm{I}_{\mathrm{OH}}=-1.0 \mathrm{~mA} \end{aligned}$ | DVcc-0.5 | - | DVcc | V |  |
| " H " level output voltage | Vон3 | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 | $\begin{gathered} \mathrm{DVcc}=4.5 \mathrm{~V} \\ \mathrm{I}_{\mathrm{OH}}=-30.0 \mathrm{~mA} \end{gathered}$ | DVcc-0.5 | - | DVcc | V |  |

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{ss}}=\mathrm{DV} \mathrm{ss}=\mathrm{AV} \mathrm{ss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| "L" level output voltage | $\mathrm{V}_{\text {OL1 }}$ | P000 to P001, P003, P005 to P010, P012 to P013, P015 to P024, P027 to P031, P100 to P101, P103, P105 to P109, P112 to P115, P117 to P120, P122 to P123, P126 to P131, P202 to P215, P218 to P220, P222 to P226, P321 to P324, P327, P331, P400 to P401, P403 to P409, P411, P413 to P414, P416 to P418, P420 to P421 | $\begin{aligned} & \mathrm{Vcc}=4.5 \mathrm{~V} \\ & \mathrm{I}_{\mathrm{LL}}=2.0 \mathrm{~mA} \end{aligned}$ | 0 | - | 0.4 | V |  |
|  |  | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 | $\begin{gathered} \mathrm{DVcc}=4.5 \\ \mathrm{~V} \\ \mathrm{I}_{\mathrm{OL}}=2.0 \mathrm{~mA} \end{gathered}$ | 0 | - | 0.4 | V |  |
| "L" level output voltage | $\mathrm{V}_{\mathrm{OL} 2}$ | P000 to P001, P003, P005 to P010, P012 to P013, P015 to P024, P027 to P031, P100 to P101, P103, P105 to P109, P112 to P115, P117 to P120, P122 to P123, P126 to P131, P202 to P215, P218 to P220, P222 to P226, P321 to P324, P327, P331, P400 to P401, P403 to P409, P411, P413 to P414, P416 to P418, P420 to P421 | $\begin{aligned} & \mathrm{Vcc}=4.5 \mathrm{~V} \\ & \mathrm{l}_{\mathrm{OL}}=1.0 \mathrm{~mA} \end{aligned}$ | 0 | - | 0.4 | V |  |
|  |  | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 | $\begin{gathered} \hline \mathrm{DVcc}=4.5 \\ \mathrm{~V} \\ \mathrm{I}_{\mathrm{LL}}=1.0 \mathrm{~mA} \end{gathered}$ | 0 | - | 0.4 | V |  |
| "L" level output voltage | Vol3 | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 | $\begin{gathered} \hline \mathrm{DVcc}=4.5 \\ \mathrm{~V} \\ \mathrm{I}_{\mathrm{o}}=30.0 \\ \mathrm{~mA} \end{gathered}$ | 0 | - | 0.55 | V |  |

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{V}_{\mathrm{ss}}=\mathrm{DV} \mathrm{Ss}=\mathrm{AV} \mathrm{Ss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Input leakage current | IIL | All input pins | $\begin{gathered} \mathrm{V}_{\mathrm{cc}}=\mathrm{DV} \mathrm{Vcc}= \\ \mathrm{AV} \mathrm{~V}_{\mathrm{cc}}=5.5 \mathrm{~V} \\ \mathrm{~V}_{\mathrm{sc}}<\mathrm{VI}<\mathrm{V}_{\mathrm{cc}} \end{gathered}$ | -5 | - | +5 | $\mu \mathrm{A}$ |  |
| Pull-up resistor | Rup1 | RSTX, NMIX | - | 25 | - | 100 | k $\Omega$ |  |
|  | Rup2 | P000 to P001, P003, P005 to P010, P012 to P013, P015 to P024, P027 to P031, P100 to P101, P103, P105 to P109, P112 to P115, P117 to P120, P122 to P123, P126 to P131, P202 to P215, P218 to P220, P222 to P226, P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317, P327, P331, P400 to P409, P411, P413 to P414, P416 to P418, P420 to P421 | Pull-up resistor selected | 25 | - | 100 | k $\Omega$ |  |
|  | Rup3 | TDI(P324), TMS, TCK | - | 25 | - | 100 | k $\Omega$ |  |
| Pull-down resistor | Rown1 | P000 to P001, P003, P005 to P010, P012 to P013, P015 to P024, P027 to P031, P100 to P101, P103, P105 to P109, P112 to P115, P117 to P120, P122 to P123, P126 to P131, P202 to P215, P218 to P220, P222 to P226, P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317, P327, P331, P400 to P409, P411, P413 to P414, P416 to P418, P420 to P421 | Pull-down resistor selected | 25 | - | 100 | k $\Omega$ |  |
|  | Rdown2 | TRST(P322) | - | 25 | - | 100 | k $\Omega$ |  |
| Input capacitance | Cin | Pins other than VCC, VSS, AVCC0, AVCC1, AVSS0, AVSS1 | - | - | 5 | 15 | pF |  |

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{Vss}=\mathrm{DVss}=\mathrm{AVss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Power supply current$\begin{aligned} & \text { S6J312xHzC } \\ & \text { * } \\ & \text { *x:A/9 } \\ & \text { z: A/B } \end{aligned}$ | Icc5 | VCC | Normal operation | - | 90 | 195 | mA | Operating at 128 MHz |
|  |  |  | Flash write/erase | - | 125 | 255 | mA | Operating at 128 MHz |
|  | Iccs5 |  | CPU Sleep | - | 60 | 160 | mA | Operating at 128 MHz |
|  | Ісст5 |  | Timer mode | - | 480 | 1450 | $\mu \mathrm{A}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> Slow-CR source Oscillation |
|  | Icctim |  | Timer mode (Main OSC) | - | 1340 | 2525 | $\mu \mathrm{A}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> Main source Oscillation* |
|  | ICCH5 |  | Stop mode | - | 480 | 1450 | $\mu \mathrm{A}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |
|  | Iccp |  | PWU mode (Shutdown) | - | 52.5 | 129.7 | $\mu \mathrm{A}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> (PWU operation cycle 16 ms ) |
|  |  |  |  | - | 46.2 | 115.5 | $\mu \mathrm{A}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> (PWU operation cycle 32 ms ) |
|  | Icct52 |  | Timer mode (Shutdown) | - | 40 | 100 | $\mu \mathrm{A}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> Slow-CR source Oscillation |
|  | ICCT52M |  | Timer mode (Main OSC) (Shut down) | - | 350 | 520 | $\mu \mathrm{A}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> Main source Oscillation* |
|  | Іссн52 |  | Stop mode (Shutdown) | - | 40 | 100 | $\mu \mathrm{A}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |

Refer to Hardware manual "APPENDIX State transition" for Internal clock frequency setting / Setting of the power domain / Regulator setting.
*: The external load capacitance connected to $\mathrm{X} 0 / \mathrm{X} 1$ is considerd as 10 pF .
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{ss}}=\mathrm{DV} \mathrm{Ss}=\mathrm{AV} \mathrm{Vs}^{\mathrm{S}}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| High current Output drive Capacity Phase to phase deviation1 | $\Delta \mathrm{V}_{\text {он3 }}$ | PWM1Pn, PWM1Mn, PWM2Pn, PWM2Mn ( $\mathrm{n}=0$ to 3 ) | $\begin{gathered} \mathrm{DV}_{\mathrm{cc}}=4.5 \mathrm{~V} \\ \mathrm{loH}=-30.0 \mathrm{~mA} \\ \text { Maximum } \\ \text { deviation of } \mathrm{V}_{\mathrm{OH}} \end{gathered}$ | - | - | 90 | mV | * |
| High current Output drive Capacity Phase to phase Deviation2 | $\Delta \mathrm{V}_{\text {ol3 }}$ | PWM1Pn, PWM1Mn, PWM2Pn, PWM2Mn ( $\mathrm{n}=0$ to 3 ) | $\begin{gathered} \mathrm{DV}_{\mathrm{cc}}=4.5 \mathrm{~V} \\ \mathrm{I}_{\mathrm{oH}}=-30.0 \mathrm{~mA} \end{gathered}$ <br> Maximum deviation of Vol3 | - | - | 90 | mV | * |
| LCD divider resistor | Rlcd | V0 to V1, <br> V1 to V2, <br> V2 to V3 | - | 6.25 | 12.5 | 25 | $\mathrm{k} \Omega$ |  |
| COM0 to COM3 output impedance | Rvcom | $\begin{gathered} \mathrm{COMm} \\ (\mathrm{~m}=0 \text { to } 3) \end{gathered}$ | - | - | - | 4.5 | k $\Omega$ |  |
| SEG00 to SEG31 output impedance | Rvseg | $\begin{gathered} \text { SEGn } \\ (\mathrm{n}=00 \text { to } 31) \end{gathered}$ | - | - | - | 17 | k $\Omega$ |  |
| LCDC leak current | Ilcde | $\begin{gathered} \text { V0 to } \mathrm{V} 3, \\ \text { COMm } \\ (\mathrm{m}=0 \text { to } 3) \\ \text { SEGn } \\ (\mathrm{n}=00 \text { to } 31) \end{gathered}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | -0.5 | - | +0.5 | $\mu \mathrm{A}$ |  |

*: If PWM1P0/PWM1M0/PWM2P0/PWM2M0 of ch. 0 is turned on simultaneously, the maximum deviation of VOH3/VOL3 for each pin is defined. Same for other channels.

### 10.4 AC Characteristics

### 10.4.1 Source Clock Timing

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{SS}}=\mathrm{DV}_{\mathrm{SS}}=\mathrm{AV} \mathrm{VS}_{\mathrm{SS}}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Source oscillation clock frequency | $\mathrm{F}_{\mathrm{C}}$ | X0, X1 | - | - | 4 | - | MHz |  |
| Source oscillation clock cycle time | $t_{\text {cyL }}$ | X0, X1 | - | - | 250 | - | ns |  |
| CAN PLL jitter (during lock) | $t_{\text {PJ }}$ | - | - | -10 | - | +10 | ns | * |
| Built-in slow-CR oscillation frequency | $\mathrm{F}_{\text {CRS }}$ | - | - | 50 | 100 | 150 | kHz |  |
| Built-in fast-CR oscillation frequency | $\mathrm{F}_{\text {CRF }}$ | - | - | 2.4 | 4 | 6.0 | MHz |  |
| PLL input clock frequency | $\mathrm{F}_{\text {PLLI }}$ | - | - | - | 4 | - | MHz |  |
| PLL macro oscillation clock frequency | $\mathrm{F}_{\text {PLLO }}$ | - | - | 400 | - | 512 | MHz |  |
| SSCG-PLL input clock frequency | $\mathrm{F}_{\text {SSGGPLLI }}$ | - | - | - | 4 | - | MHz |  |
| SSCG-PLL macro oscillation clock frequency | Fsscgrlo | - | - | 400 | - | 512 | MHz |  |

*: The maximum/minimum values have been standardized with the main clock and PLL clock in use.


## - CAN PLL jitter

A time difference from the ideal clock is guaranteed for each cycle period within 20,000 cycles.

10.4.2 Internal Clock Timing
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{ss}=\mathrm{AV} \mathrm{ss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | S6J312xHzC* Value * x:A/9, z:A/B |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Internal Clock Frequency | Fclk_CPu | - | - | - | - | 128 | MHz | CLK_CPU |
|  | FCLK_FCLK | - | - | - | - | 64 | MHz | CLK_FCLK |
|  | FCLK_ATB | - | - | - | - | 64 | MHz | CLK_ATB |
|  | FCLK_DBG | - | - | - | - | 64 | MHz | CLK_DBG |
|  | FCLK_HPM | - | - | - | - | 32 | MHz | CLK_HPM |
|  | FCLK_HPM2 | - | - | - | - | 16 | MHz | CLK_HPM2 |
|  | FcLK_DMA | - | - | - | - | 32 | MHz | CLK_DMA |
|  | FCLK_MEMC | - | - | - | - | 32 | MHz | CLK_MEMC |
|  | Fclk_extbus | - | - | - | - | 25 | MHz | CLK_EXTBUS |
|  | Fclk_SYSC1 | - | - | - | - | 32 | MHz | CLK_SYSC1 |
|  | FCLK_HAPPOAO | - | - | - | - | 32 | MHz | CLK_HAPPOA0 |
|  | FCLK_HAPPOA1 | - | - | - | - | 32 | MHz | CLK_HAPP0A1 |
|  | FCLK_HAPP1B0 | - | - | - | - | 32 | MHz | CLK_HAPP1B0 |
|  | FCLK_HAPP1B1 | - | - | - | - | 32 | MHz | CLK_HAPP1B1 |
|  | FCLK_LLPBM | - | - | - | - | 128 | MHz | CLK_LLPBM |
|  | FCLK_LLPBM2 | - | - | - | - | 64 | MHz | CLK_LLPBM2 |
|  | FCLK_LCP | - | - | - | - | 64 | MHz | CLK_LCP |
|  | FCLK_LCP0 | - | - | - | - | 32 | MHz | CLK_LCP0 |
|  | FCLK_LCPOA | - | - | - | - | 32 | MHz | CLK_LCPOA |
|  | FCLK_LCP1 | - | - | - | - | 32 | MHz | CLK_LCP1 |
|  | FCLK_LCP1A | - | - | - | - | 32 | MHz | CLK_LCP1A |
|  | Fclk_LapP0 | - | - | - | - | 32 | MHz | CLK_LAPP0 |
|  | Fclk_LAPPOA | - | - | - | - | 32 | MHz | CLK_LAPP0A |
|  | Fclk_LAPP1 | - | - | - | - | 32 | MHz | CLK_LAPP1 |
|  | Fclk_LAPP1A | - | - | - | - | 32 | MHz | CLK_LAPP1A |
|  | Fclk_TRC | - | - | - | - | 64 | MHz | CLK_TRC |
|  | FCLK_HSSPI | - | - | - | - | 32 | MHz | CLK_HSSPI |
|  | FCLK_SYSCOH | - | - | - | - | 32 | MHz | CLK_SYSCOH |
|  | Fclk_comb | - | - | - | - | 32 | MHz | CLK_COMH |
|  | FCLK_RAMOH | - | - | - | - | 32 | MHz | CLK_RAMOH |
|  | FCLK_RAM1H | - | - | - | - | 32 | MHz | CLK_RAM1H |
|  | FCLK_SYSCOP | - | - | - | - | 32 | MHz | CLK_SYSCOP |
|  | Fclk_comp | - | - | - | - | 32 | MHz | CLK_COMP |
|  | FCANFD_CCLK | - | - | - | - | 40 | MHz | CANFD_CCLK |


| Parameter | Symbol | Pin Name | Conditions | $\begin{gathered} \text { S6J312xHzC* Value } \\ { }^{*} \text { x:A/9, z:A/B } \end{gathered}$ |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Internal clock cycle time | tcLk_CPU | - | - | 7.82 | - | - | ns | CLK_CPU |
|  | tclk_flash | - | - | 15.64 | - | - | ns | CLK_FCLK |
|  | tclk_AtB | - | - | 15.64 | - | - | ns | CLK_ATB |
|  | tcLk_DBG | - | - | 15.64 | - | - | ns | CLK_DBG |
|  | tcLk_HPM | - | - | 31.28 | - | - | ns | CLK_HPM |
|  | tcLk_HPM2 | - | - | 62.54 | - | - | ns | CLK_HPM2 |
|  | tclk_DMA | - | - | 31.28 | - | - | ns | CLK_DMA |
|  | tclk_memc | - | - | 31.28 | - | - | ns | CLK_MEMC |
|  | tclk_Extbus | - | - | 40.00 | - | - | ns | CLK_EXTBUS |
|  | tclk_SYSC1 | - | - | 31.28 | - | - | ns | CLK_SYSC1 |
|  | tcLK_HAPPOAO | - | - | 31.28 | - | - | ns | CLK_HAPPOAO |
|  | tcLK_HAPP0A1 | - | - | 31.28 | - | - | ns | CLK_HAPP0A1 |
|  | tcLK_HAPP1B0 | - | - | 31.28 | - | - | ns | CLK_HAPP1B0 |
|  | tcLK_HAPP1B1 | - | - | 31.28 | - | - | ns | CLK_HAPP1B1 |
|  | tcle_LLPBM | - | - | 7.82 | - | - | ns | CLK_LLPBM |
|  | tCLK_LLPBM2 | - | - | 15.64 | - | - | ns | CLK_LLPBM2 |
|  | tCLK_LCP | - | - | 15.64 | - | - | ns | CLK_LCP |
|  | tCLK_LCP0 | - | - | 31.28 | - | - | ns | CLK_LCP0 |
|  | tclk_LCPoA | - | - | 31.28 | - | - | ns | CLK_LCPOA |
|  | tclk_LCP1 | - | - | 31.28 | - | - | ns | CLK_LCP1 |
|  | tclk_LCP1A | - | - | 31.28 | - | - | ns | CLK_LCP1A |
|  | tclk_Lappo | - | - | 31.28 | - | - | ns | CLK_LAPP0 |
|  | tclk_LAPP0A | - | - | 31.28 | - | - | ns | CLK_LAPP0A |
|  | tclk_LAPP1 | - | - | 31.28 | - | - | ns | CLK_LAPP1 |
|  | tCLK_LAPP1A | - | - | 31.28 | - | - | ns | CLK_LAPP1A |
|  | tclk_TRC | - | - | 15.64 | - | - | ns | CLK_TRC |
|  | tclk_HSSPI | - | - | 31.28 | - | - | ns | CLK_HSSPI |
|  | tclk_SYscor | - | - | 31.28 | - | - | ns | CLK_SYSCOH |
|  | tclk_Comh | - | - | 31.28 | - | - | ns | CLK_COMH |
|  | tcle_RamOH | - | - | 31.28 | - | - | ns | CLK_RAMOH |
|  | tclk_Ram1H | - | - | 31.28 | - | - | ns | CLK_RAM1H |
|  | tclk_SYSCop | - | - | 31.28 | - | - | ns | CLK_SYSCOP |
|  | tclk_COMP | - | - | 31.28 | - | - | ns | CLK_COMP |
|  | tcanfd_cclk | - | - | 25.00 | - | - | ns | CANFD_CCLK |

- Guaranteed operation range

Internal operation clock frequency vs. Power supply voltage


Note: A supply voltage that is equal to or less than the set voltage for low-voltage detection causes a reset.

Relationship between the oscillation clock frequency and internal clock frequency

| Oscillation Clock <br> Frequency | Main Clock | PLL Multiplier <br> Setting | PLL Output <br> Division Setting | PLL Clock |
| :---: | :---: | :---: | :---: | :---: |
| 4 MHz | 4 MHz | 128 | 4 | 128 MHz |
| 4 MHz | 4 MHz | 120 | 6 | 80 MHz |

- Oscillation circuit example


Notes:
When configuring the oscillator circuit, it is recommended to ask matching evaluation of the circuit to oscillator manufacturers for the design.
The maximum PLL clock frequency must be 128 MHz .
Output division configuration can be set by the following.

- PLLDIVM bit in SYSCO_RUNPLLOCNTR register
- PLLDIVM bit in SYSC0_PSSPLLOCNTR register
- SSCGDIVM bit in SYSC̄0_RUNSSCG0CNTR0 register
- SSCGDIVM bit in SYSC0_PSSSSCG0CNTR0 register
(e.g. If PLLout is 448 MHz , these settings must be configured as "multiply by 4 " and over multiplication setting)

AC characteristics are specified by the following measurement reference voltage values.

| $-\quad$ Input signal waveform | - Output signal waveform |
| :--- | :--- |
| Hysteresis input pin (Automotive) | Output pin |

Hysteresis input pin (CMOS Schmitt)


Hysteresis input pin (TTL)


### 10.4.3 Reset Input

( $\mathrm{T}_{\mathrm{A}}:$ Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{ss}}=\mathrm{DV} \mathrm{Ss}=\mathrm{AV} \mathrm{ss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Reset input time | $\mathrm{t}_{\text {RStL }}$ | RSTX | - | 10 | - | $\mu \mathrm{s}$ |  |
| Width for reset input removal |  |  |  | 1 | - | $\mu \mathrm{s}$ |  |



### 10.4.4 Power-on Conditions

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{V} \mathrm{ss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Level detection voltage | - | VCC | - | 2.15 | 2.35 | 2.55 | V |  |
| Level detection hysteresis width | - | VCC | - | - | 100 | - | mV |  |
| Level detection time | - | - | - | - | - | 540 | $\mu \mathrm{s}$ | *1 |
| Level release voltage | - | VCC | - | 2.25 | 2.45 | 2.65 | V |  |
| Power off time | - | VCC | - | 1 | - | - | ms | *2 |
| Power ramp rate | dV/dt | VCC | $\begin{gathered} \text { VCC: } \\ 0.2 \text { V to } 2.55 \text { V } \end{gathered}$ | - | - | 6 | $\mathrm{mV} / \mu \mathrm{s}$ | *3 |
| Maximum ramp rate guaranteed to not generate power-on reset | \|dV/dt| | VCC | VCC: <br> Between 2.6 V and 4.5 V | - | - | 50 | $\mathrm{mV} / \mu \mathrm{s}$ | *4 |

*1: If a power fluctuation precedes the low-voltage detection time, the detection may occur or be canceled after the supply voltage passes the detection voltage range.
${ }^{*}$ : If VCC is held below 0.2 V for a minimum period of tOFF, power-on reset will occur. If tOFF is not satisfied, power-on reset will still occur if the power ramp rate is kept below $6 \mathrm{mV} / \mu \mathrm{s}$.
${ }^{* 3}$ : This is the power ramp rate with which power-on reset will always occur regardless of power-off time, as mentioned in *2.
${ }^{*} 4$ : When VCC is within $2.6 \mathrm{~V}-4.5 \mathrm{~V}$, and VCC fluctuation is below $50 \mathrm{mV} / \mathrm{us}$, the power-on reset is suppressed. Between 4.5 V 5.5 V , the power-on reset does not occur with any VCC fluctuation.

Note:
When neither *2 nor *3 can be satisfied, assert external reset (RSTX) at power-up and at any brownout event.

## - Power off time, Power ramp rate at Power-on

vcc



- Maximum ramp rate guaranteed to not generate power-on reset



### 10.4.5 Clock Output Timing

(External load capacitance 16 pF )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Cycle time | tcyc | MCLK | 2 mA is selected in ODR bit in PPC_PCFGR register. | 40 | - | ns |  |
| Clock high width *1 | tchcl | MCLK |  | dhttcyc -7 | $\mathrm{dhtayc}^{+} 7$ | ns |  |
| Clock low width *2 | tcleh | MCLK |  | dıttyc- 7 | dıtcyc +7 | ns |  |

*1: If division-ratio is even value, $\mathrm{d}_{\mathrm{H}}$ is equivalent to 0.5 .
Otherwise, $\mathrm{d}_{\mathrm{H}}$ is calculated as the following.
$\mathrm{d}_{\mathrm{H}}=$ The number rounding "division-ratio $\times 0.5$ " down to the nearest integer / division-ratio division-ratio is multiplication value among SYSDIV bit, HPMDIV bit and EXTBUSDIV bit setting.
ex). Setting SYSDIV to 1-division, HPMDIV to 7-division, EXTBUSDIV to 1-division, $\mathrm{d} н$ is calculated as 0.429 .
*2: If division-ratio is even value, $\mathrm{d}_{\mathrm{L}}$ is equivalent to 0.5 .
Otherwise, $\mathrm{d}_{\mathrm{L}}$ is calculated as the following.
$\mathrm{dL}=$ The number rounding "division-ratio $\times 0.5$ " up to the nearest integer / division-ratio division-ratio is multiplication value among SYSDIV bit, HPMDIV bit and EXTBUSDIV bit setting.
ex). Setting SYSDIV to 1-division, HPMDIV to 7-division, EXTBUSDIV to 1-division, dL is calculated as 0.571 .


### 10.4.6 External Bus Interface Timing

10.4.6.1 Common Timing Between Read and Write
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DVss}=\mathrm{AVss}=0.0 \mathrm{~V}$ )
(External load capacitance 16 pF )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Cycle time (without MRDY) | tcre | MCLK | 2 mA is selected in ODR bit in PPC_PCFGR register. | 40 | - | ns |  |
| Cycle time (with MRDY) | tcre | MCLK |  | 50 | - | ns | If using MRDY, set MCLK to 20 MHz or less. |
| CS delay time | tcso | MCLK, MCSX0 to MCSX3 |  | 0.5 | 18 | ns |  |
| Address delay time | $t_{\text {AO }}$ | MCLK, <br> MAD00 to MAD23 |  | 0.5 | 18 | ns |  |
| RDY setup time | trdys | MCLK, MRDY | "CMOS Schmitt input" and "Disable noise filter" are selected in PPC_PCFGR register. | 21 | - | ns |  |
| RDY hold time | $t_{\text {RDYH }}$ | MCLK, MRDY |  | 0 | - | ns |  |

External bus $\mathrm{I} / \mathrm{F}$ common timing
( $\mathrm{T}_{\mathrm{A}}:$ Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{ss}=\mathrm{AVss}=0.0 \mathrm{~V}$ ) (External load capacitance 16 pF )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Data setup time | tDSR | MOEX, <br> MDATA00 to MDATA15 | "CMOS Schmitt input" and "Disable noise filter" are selected in PPC_PCFGR register. | $21+\mathrm{t}_{\text {cyc }}$ | - | ns |  |
| Data hold time | tohr | MOEX, <br> MDATA00 to MDATA15 |  | 0 | - | ns |  |
| MOEX delay time | trdo | MCLK, MOEX | 2 mA is selected in ODR bit in PPC_PCFGR register. | 0.5 | 18 | ns |  |


( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{ss}}=\mathrm{DV} \mathrm{ss}=\mathrm{AV} \mathrm{ss}=0.0 \mathrm{~V}$ ) (External load capacitance 16 pF )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| MWEX delay time | tweo | MCLK, MWEX | 2 mA is selected in ODR bit in PPC_PCFGR register. | 0.5 | 18 | ns |  |
| Byte mask delay time | twro | MCLK, <br> MDQM0 to MDQM1 |  | 0.5 | 18 | ns |  |
| Data delay time | too | MCLK, <br> MDATA00 to MDATA15 |  | 0.5 | 18 | ns |  |
| Data delay time (Hi-Z output) | tooz | MCLK, MDATA00 to MDATA15 |  | - | 18 | ns |  |


(5-1-1) Normal Synchronous Transfer (SCR:SPI = 0) and Serial Clock Output Signal Detect Level "H" (SMR:SCINV = 0)
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{SS}}=\mathrm{DV}_{\mathrm{SS}}=\mathrm{AV}$ SS $=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Serial clock cycle time | $t_{\text {scrc }}$ | SCK0 to SCK4, SCK8 to SCK12 | Master mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $4 t_{\text {cLK_LCPnA }}{ }^{*}$ | - | ns |  |
| $\begin{aligned} & \text { SCK } \downarrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | tslovi | SCK0 to SCK4, SCK8 to SCK12, SOTO to SOT4, SOT8 to SOT12 |  | -30 | +30 | ns |  |
| Valid SIN $\rightarrow$ SCK $\uparrow$ setup time | $\mathrm{t}_{\text {IVSH\| }}$ | SCK0 to SCK4, SCK8 to SCK12, |  | 30 | - | ns |  |
| SCK $\uparrow \rightarrow$ Valid SIN hold time | tsHIXI | SIN0 to SIN4, SIN8 to SIN12 |  | 0 | - | ns |  |
| Serial clock "H" pulse width | tsHSL | SCK0 to SCK4, SCK8 to SCK12 | Slave mode ( $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$, $\mathrm{I}_{\mathrm{LL}}=-2 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}$ ), ( $\mathrm{CL}_{\mathrm{L}}=20 \mathrm{pF}$, $\mathrm{I}_{\mathrm{LL}}=-1 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}$ ) | $\mathrm{t}_{\text {CLK_LPPPA }}{ }^{*}+10$ | - | ns |  |
| Serial clock "L" pulse width | tsLSH |  |  | $2 t_{\text {cLK_LCPAA }}{ }^{*}-10$ | - | ns |  |
| $\begin{aligned} & \text { SCK } \downarrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $\mathrm{t}_{\text {slove }}$ | SCK0 to SCK4, SCK8 to SCK12, SOT0 to SOT4, SOT8 to SOT12 |  | - | 30 | ns |  |
| Valid SIN $\rightarrow$ SCK $\uparrow$ setup time | $\mathrm{tivSHE}^{\text {d }}$ | SCK0 to SCK4, SCK8 to SCK12, |  | 10 | - | ns |  |
| SCK $\uparrow \rightarrow$ Valid SIN hold time | $\mathrm{t}_{\text {SHIXE }}$ | SIN0 to SIN4, SIN8 to SIN12 |  | 20 | - | ns |  |
| SCK fall time | $\mathrm{t}_{\mathrm{F}}$ | SCK0 to SCK4, SCK8 to SCK12 |  | - | 5 | ns |  |
| SCK rise time | $\mathrm{t}_{\mathrm{R}}$ | SCK0 to SCK4, SCK8 to SCK12 |  | - | 5 | ns |  |

*: $\mathrm{n}=0: \mathrm{ch} .0$ to ch. $4, \mathrm{n}=1:$ ch. 8 to ch. 12

## Notes:

- $\quad$ This is the AC characteristic in CLK synchronized mode.
- $\quad C L$ is the load capacitance applied to pins during testing.
- $\quad$ The maximum baud rate is limited by the internal operating clock used and other parameters.

For details, see the hardware manual.

(5-1-2) Normal Synchronous Transfer (SCR:SPI = 0) and Serial Clock Output Signal Detect Level "L" (SMR:SCINV = 1)
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{SS}}=\mathrm{DV} \mathrm{VS}_{\mathrm{SS}}=\mathrm{AV} \mathrm{SS}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Serial clock cycle time | $t_{\text {scyc }}$ | SCK0 to SCK4, SCK8 to SCK12 | Master mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{CL}_{\mathrm{L}}=20 \mathrm{p},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $4 t_{\text {cLK_LCPnA }}{ }^{*}$ | - | ns |  |
| $\begin{aligned} & \text { SCK } \uparrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $\mathrm{t}_{\text {SHOVI }}$ | SCK0 to SCK4, SCK8 to SCK12, SOT0 to SOT4, SOT8 to SOT12 |  | -30 | +30 | ns |  |
| Valid SIN $\rightarrow$ SCK $\downarrow$ setup time | $\mathrm{t}_{\text {IVSLI }}$ | SCK0 to SCK4, SCK8 to SCK12, SIN0 to SIN4, SIN8 to SIN12 |  | 30 | - | ns |  |
| SCK $\downarrow \rightarrow$ Valid SIN hold time | $\mathrm{t}_{\text {sulx }}$ |  |  | 0 | - | ns |  |
| Serial clock "H" pulse width | tsHSL | SCK0 to SCK4, SCK8 to SCK12 | Slave mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{CL}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $\mathrm{t}_{\text {CLK_LCPnA }}{ }^{*}+10$ | - | ns |  |
| Serial clock "L" pulse width | tsLSH |  |  | $2 \mathrm{t}_{\text {cLK_LCPnA }}{ }^{*}-10$ | - | ns |  |
| $\begin{aligned} & \text { SCK } \uparrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $\mathrm{t}_{\text {shove }}$ | SCK0 to SCK4, SCK8 to SCK12, SOT0 to SOT4, SOT8 to SOT12 |  | - | 30 | ns |  |
| Valid SIN $\rightarrow$ SCK $\downarrow$ setup time | $t_{\text {IVSLE }}$ | SCK0 to SCK4, SCK8 to SCK12, |  | 10 | - | ns |  |
| SCK $\downarrow \rightarrow$ Valid SIN hold time | tsLIXE | SIN0 to SIN4, SIN8 to SIN12 |  | 20 | - | ns |  |
| SCK fall time | $\mathrm{t}_{\mathrm{F}}$ | SCK0 to SCK4, SCK8 to SCK12 |  | - | 5 | ns |  |
| SCK rise time | $t_{R}$ | SCK0 to SCK4, SCK8 to SCK12 |  | - | 5 | ns |  |

*: $\mathrm{n}=0: \mathrm{ch} .0$ to ch. $4, \mathrm{n}=1: \mathrm{ch} .8$ to ch. 12

## Notes:

- $\quad$ This is the AC characteristic in CLK synchronized mode.
- $\quad C L$ is the load capacitance applied to pins during testing.
- $\quad$ The maximum baud rate is limited by the internal operating clock used and other parameters.

For details, see the hardware manual.

(5-1-3) SPI Supported (SCR:SPI = 1), and Serial Clock Output Signal Detect Level "H" (SMR:SCINV = 0)
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{ss}}=\mathrm{DV}_{\mathrm{ss}}=\mathrm{AV} \mathrm{VS}_{\mathrm{ss}}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Serial clock cycle time | $\mathrm{t}_{\text {scyc }}$ | SCK0 to SCK4, SCK8 to SCK12 | Master mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $4 t_{\text {cLK_LCP }}{ }^{*}{ }^{*}$ | - | ns |  |
| SCK $\uparrow \rightarrow$ SOT delay time | $\mathrm{t}_{\text {shovi }}$ | SCK0 to SCK4, SCK8 to SCK12, SOT0 to SOT4, SOT8 to SOT12 |  | -30 | +30 | ns |  |
| Valid SIN $\rightarrow$ SCK $\downarrow$ setup time | $\mathrm{t}_{\text {IVSLI }}$ | SCK0 to SCK4, SCK8 to SCK12, SIN0 to SIN4, SIN8 to SIN12 |  | 30 | - | ns |  |
| SCK $\downarrow \rightarrow$ Valid SIN hold time | $\mathrm{t}_{\text {suxi }}$ |  |  | 0 | - | ns |  |
| $\text { SOT } \rightarrow \text { SCK } \downarrow$ <br> delay time | $\mathrm{t}_{\text {sovLI }}$ | SCK0 to SCK4, SCK8 to SCK12, SOT0 to SOT4, SOT8 to SOT12 |  | $2 t_{\text {clk_LCPnA }}{ }^{*}-30$ | - | ns |  |
| Serial clock "H" pulse width | tsHsL | SCK0 to SCK4, SCK8 to SCK12 | Slave mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $\mathrm{t}_{\text {CLK_LCPnA }}{ }^{*}+10$ | - | ns |  |
| Serial clock "L" pulse width | tsts |  |  | $2 t_{\text {cLK_LCPnA }}{ }^{*}-10$ | - | ns |  |
| SCK $\uparrow \rightarrow$ SOT delay time | $\mathrm{t}_{\text {shove }}$ | SCK0 to SCK4, SCK8 to SCK12, SOT0 to SOT4, SOT8 to SOT12 |  | - | 30 | ns |  |
| Valid SIN $\rightarrow$ SCK $\downarrow$ setup time | $\mathrm{t}_{\text {IVSLE }}$ | SCK0 to SCK4, SCK8 to SCK12, |  | 10 | - | ns |  |
| SCK $\downarrow \rightarrow$ Valid SIN hold time | $\mathrm{t}_{\text {sLIXE }}$ | SIN0 to SIN4, SIN8 to SIN12 |  | 20 | - | ns |  |
| SCK fall time | $\mathrm{t}_{\mathrm{F}}$ | SCK0 to SCK4, SCK8 to SCK12 |  | - | 5 | ns |  |
| SCK rise time | $\mathrm{t}_{\mathrm{R}}$ | SCK0 to SCK4, SCK8 to SCK12 |  | - | 5 | ns |  |

*: $\mathrm{n}=0: \mathrm{ch} .0$ to ch. $4, \mathrm{n}=1:$ ch. 8 to ch. 12

## Notes:

- $\quad$ This is the AC characteristic in CLK synchronized mode.
- $\quad C L$ is the load capacitance applied to pins during testing.
- $\quad$ The maximum baud rate is limited by the internal operating clock used and other parameters.

For details, see the hardware manual.

(5-1-4) SPI Supported (SCR:SPI = 1), and Serial Clock Output Signal Detect Level "L" (SMR:SCINV = 1)
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} s \mathrm{ss}=\mathrm{AVss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Serial clock cycle time | tscyc | SCK0 to SCK4, SCK8 to SCK12 | Master mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{CL}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $4 t_{\text {cle_LCPPA }}{ }^{*}$ | - | ns |  |
| $\begin{aligned} & \text { SCK } \downarrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | tsLovi | SCKO to SCK4, SCK8 to SCK12, SOT0 to SOT4, SOT8 to SOT12 |  | -30 | +30 | ns |  |
| Valid SIN $\rightarrow$ SCK $\uparrow$ setup time | $\mathrm{tivSH}^{\text {l }}$ | SCK0 to SCK4, SCK8 to SCK12, SIN0 to SIN4, SIN8 to SIN12 |  | 30 | - | ns |  |
| SCK $\uparrow \rightarrow$ Valid SIN hold time | tsHIXI |  |  | 0 | - | ns |  |
| $\begin{aligned} & \text { SOT } \rightarrow \text { SCK } \uparrow \\ & \text { delay time } \end{aligned}$ | $\mathrm{t}_{\text {SOVHI }}$ | SCK0 to SCK4, SCK8 to SCK12, SOT0 to SOT4, SOT8 to SOT12 |  | $2 t_{\text {CLK_LCPnA }}{ }^{*}-30$ | - | ns |  |
| Serial clock "H" pulse width | $\mathrm{t}_{\text {SHSL }}$ | SCK0 to SCK4, SCK8 to SCK12 | Slave mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $\mathrm{t}_{\text {CLK_LCPnA }}{ }^{*}+10$ | - | ns |  |
| Serial clock "L" pulse width | tsLSH |  |  | $2 t_{\text {CLK_LCPnA }}{ }^{*}-10$ | - | ns |  |
| $\begin{aligned} & \text { SCK } \downarrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $\mathrm{t}_{\text {slove }}$ | SCK0 to SCK4, SCK8 to SCK12, SOTO to SOT4, SOT8 to SOT12 |  | - | 30 | ns |  |
| Valid SIN $\rightarrow$ SCK $\uparrow$ setup time | $\mathrm{t}_{\text {IVSHE }}$ | SCK0 to SCK4, SCK8 to SCK12, |  | 10 | - | ns |  |
| SCK $\uparrow \rightarrow$ Valid SIN hold time | $\mathrm{t}_{\text {SHIXE }}$ | SIN0 to SIN4, SIN8 to SIN12 |  | 20 | - | ns |  |
| SCK fall time | $\mathrm{t}_{\mathrm{F}}$ | SCK0 to SCK4, SCK8 to SCK12 |  | - | 5 | ns |  |
| SCK rise time | $t_{R}$ | SCK0 to SCK4, SCK8 to SCK12 |  | - | 5 | ns |  |

*: $\mathrm{n}=0: \mathrm{ch} .0$ to ch. $4, \mathrm{n}=1: \mathrm{ch} .8$ to ch. 12

## Notes:

- $\quad$ This is the AC characteristic in CLK synchronized mode.
- CL is the load capacitance applied to pins during testing.
- $\quad$ The maximum baud rate is limited by the internal operating clock used and other parameters. For details, see the hardware manual.

* Changes when writing to the TDR

Slave mode

## (5-1-5) Serial Chip Select Used (SCSCR:CSEN = 1)

■Mark level "H" of serial clock output (SMR, SCSFR:SCINV = 0)
■Inactive level "H" of serial chip select (SCSCR, SCSFR:CSLVL = 1)
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{ss}=\mathrm{AVss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| $\text { SCS } \downarrow \rightarrow \text { SCK } \downarrow$ <br> setup time | $\mathrm{t}_{\text {css }}$ | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | Master mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{CL}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $\mathrm{tcssu}^{* 1}-50$ | - | ns |  |
| SCK $\uparrow \rightarrow$ SCS $\uparrow$ hold time | $\mathrm{t}_{\text {cSH }}$ |  |  | $\mathrm{tcSHo}^{* 2}+0$ | - | ns |  |
| SCS deselect time | $\mathrm{t}_{\text {csbl }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | $\begin{gathered} \mathrm{t}_{\text {csiss }}{ }^{* 3}-50 \\ +5 \mathrm{t}_{\text {CLK_LCPAA }}{ }^{* 4} \end{gathered}$ | - | ns |  |
| $\text { SCS } \downarrow \rightarrow \text { SCK } \downarrow$ <br> setup time | $\mathrm{t}_{\text {csse }}$ | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | Slave <br> mode $\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $3 \mathrm{CLLK}_{\text {_LCPAA }}{ }^{* 4}+30$ | - | ns |  |
| SCK $\uparrow \rightarrow$ SCS $\uparrow$ hold time | $\mathrm{t}_{\text {CSHE }}$ |  |  | 0 | - | ns |  |
| SCS deselect time | $\mathrm{t}_{\text {csie }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | $3 \mathrm{CLLK}_{\text {_LCPAA }}{ }^{* 4}+30$ | - | ns |  |
| $\begin{aligned} & \text { SCS } \downarrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $\mathrm{t}_{\text {DSE }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x, } \\ & \text { SOT0 to SOT4, } \\ & \text { SOT8 to SOT12 } \end{aligned}$ |  | - | 40 | ns |  |
| $\begin{aligned} & \text { SCS } \uparrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $\mathrm{t}_{\text {DEE }}$ |  |  | 0 | - | ns |  |
| SCK $\downarrow \rightarrow$ SCS $\downarrow$ clock switching time | tscc | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | Master mode round operation ( $\mathrm{CL}=50 \mathrm{pF}$, $\mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}$ ), ( $\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}$, $\mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}$ ) | $3 \mathbf{t c L K}$ _LCPnA $^{* 4}+0$ | $3 \mathbf{c c L L K}_{\text {_LCPnA }}{ }^{* 4}+50$ | ns |  |

*1: tcssu = SCSTR:CSSU[7:0] x serial chip select timing operating clock
*2: tcshd $=$ SCSTR:CSHD[7:0] x serial chip select timing operating clock
*3: tcsds $=$ SCSTR:CSDS[15:0] $x$ serial chip select timing operating clock
For details on *1, *2, and *3 above, see the hardware manual.
*4 tclk_LCPnA $n=0: c h .0$ to ch. $4, \mathrm{n}=1: \mathrm{ch} .8$ to ch. 12

## Notes:

- $\quad$ This is the AC characteristic in CLK synchronized mode.
- $\quad C L$ is the load capacitance applied to pins during testing.
- $\quad$ The maximum baud rate is limited by the internal operating clock used and other parameters. For details, see the hardware manual.


Clock switching example by master mode round operation ( $x, y=0,1,2,3,4,8,9,10,11,12: x$ and $y$ are different value)

## (5-1-6) Serial Chip Select Used (SCSCR:CSEN = 1)

■Serial clock output signal detect level "L" (SMR, SCSFR:SCINV = 1)
■Serial chip select inactive level "H" (SCSCR, SCSFR:CSLVL = 1)
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{ss}=\mathrm{AV} \mathrm{ss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| $\begin{aligned} & \text { SCS } \downarrow \rightarrow \text { SCK } \uparrow \\ & \text { setup time } \end{aligned}$ | $\mathrm{t}_{\text {css }}$ | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | Master mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{CLL}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{LL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $\mathrm{tcssu}^{* 1}-50$ | - | ns |  |
| $\text { SCK } \downarrow \rightarrow \text { SCS } \uparrow$ <br> hold time | $\mathrm{t}_{\text {cSHI }}$ |  |  | $\mathrm{tcSHo}^{* 2}+0$ | - | ns |  |
| SCS deselect time | $\mathrm{t}_{\text {csol }}$ | $\begin{aligned} & \text { SCS0x to SCS } 4 x \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | $\mathrm{t}_{\mathrm{csos}}{ }^{* 3}-50+$ <br> 5tclk_LCPnA ${ }^{* 4}$ | - | ns |  |
| $\begin{aligned} & \text { SCS } \downarrow \rightarrow \text { SCK } \uparrow \\ & \text { setup time } \end{aligned}$ | $\mathrm{t}_{\text {csse }}$ | SCK0 to SCK4, SCK8 to SCK12, | Slave mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{CLL}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{LL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $3 \mathrm{c}_{\text {cLK_LCPnA }}{ }^{* 4}+30$ | - | ns |  |
| $\text { SCK } \downarrow \rightarrow \text { SCS } \uparrow$ <br> hold time | $\mathrm{t}_{\text {cSHE }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | 0 | - | ns |  |
| SCS deselect time | $t_{\text {csie }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | $3 \mathrm{c}_{\text {cLK_LCPnA }}{ }^{* 4}+30$ | - | ns |  |
| $\begin{aligned} & \text { SCS } \downarrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $\mathrm{t}_{\text {DSE }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x, } \\ & \text { SOT0 to SOT4, } \\ & \text { SOT8 to SOT12 } \end{aligned}$ |  | - | 40 | ns |  |
| $\begin{aligned} & \text { SCS } \uparrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $t_{\text {dee }}$ |  |  | 0 | - | ns |  |
| SCK $\uparrow \rightarrow$ SCS $\downarrow$ clock switching time | tscc | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | Master mode round operation (CL = 50 pF , $\mathrm{l}_{\mathrm{OL}}=-2 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}$ ), ( $\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}$, $\mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}$ ) | $3 \mathbf{t c L K}_{\text {_LCPnA }}{ }^{* 4}+0$ | $3 \mathrm{tcLE}_{\text {_LCPAA }}{ }^{* 4}+50$ | ns |  |

*1: tcssu = SCSTR:CSSU[7:0] x serial chip select timing operating clock
*2: tcshd = SCSTR:CSHD[7:0] x serial chip select timing operating clock
*3: tcsds $=$ SCSTR:CSDS[15:0] $x$ serial chip select timing operating clock
For details on *1, *2, and *3 above, see the hardware manual.
*4 tclk LCPnA $\mathrm{n}=0$ :ch. 0 to ch. $4, \mathrm{n}=1: \mathrm{ch} .8$ to ch. 12

## Notes:

- $\quad$ This is the AC characteristic in CLK synchronized mode.
- $\quad C L$ is the load capacitance applied to pins during testing.
- $\quad$ The maximum baud rate is limited by the internal operating clock used and other parameters.

For details, see the hardware manual.



Clock switching example by master mode round operation
$(x, y=0,1,2,3,4,8,9,10,11,12: x$ and $y$ are different value) ( $x, y=0,1,2,3,4,8,9,10,11,12: x$ and $y$ are different value)

## (5-1-7) Serial Chip Select Used (SCSCR:CSEN = 1)

■Serial clock output signal detect level "H" (SMR, SCSFR:SCINV = 0)
■Serial Chip select inactive level "L" (SCSCR, SCSFR:CSLVL = 0
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{Vs}=\mathrm{AV} \mathrm{Vs}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| $\text { SCS } \uparrow \rightarrow \text { SCK } \downarrow$ <br> setup time | tcssi | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | Master mode ( $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$, $\mathrm{I}_{\mathrm{LL}}=-2 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}$ ), ( $\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}$, $\mathrm{I}_{\mathrm{LL}}=-1 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}$ ) | $\mathrm{tcssu}^{* 1}-50$ | - | ns |  |
| SCK $\uparrow \rightarrow$ SCS $\downarrow$ hold time | $\mathrm{t}_{\text {cSHII }}$ |  |  | $\mathrm{tcSHo}^{* 2}+0$ | - | ns |  |
| SCS deselect time | $\mathrm{t}_{\text {csol }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | $\begin{gathered} \mathrm{t}_{\text {csds }}{ }^{* 3}-50 \\ +5 \mathrm{t}_{\text {cLK_LCPnA }}{ }^{* 4} \end{gathered}$ | - | ns |  |
| $\text { SCS } \uparrow \rightarrow \text { SCK } \downarrow$ setup time | $\mathrm{t}_{\text {csse }}$ | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | Slave mode <br> ( $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$, <br> $\mathrm{l}_{\mathrm{OL}}=-2 \mathrm{~mA}$, <br> $\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}$ ), <br> ( $\mathrm{CL}=20 \mathrm{pF}$, <br> $\mathrm{l}_{\mathrm{OL}}=-1 \mathrm{~mA}$, <br> $\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}$ ) | $3 \mathrm{t}_{\text {CLK_LCPna }}{ }^{* 4}+30$ | - | ns |  |
| SCK $\uparrow \rightarrow$ SCS $\downarrow$ hold time | $\mathrm{t}_{\text {CSHE }}$ |  |  | 0 | - | ns |  |
| SCS deselect time | $\mathrm{t}_{\text {csie }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | $3 \mathrm{t}_{\text {cLK_LCPna }}{ }^{* 4}+30$ | - | ns |  |
| $\begin{aligned} & \mathrm{SCS} \uparrow \rightarrow \mathrm{SOT} \\ & \text { delay time } \end{aligned}$ | $t_{\text {dSE }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x, } \\ & \text { SOT0 to SOT4, } \\ & \text { SOT8 to SOT12 } \end{aligned}$ |  | - | 40 | ns |  |
| $\begin{aligned} & \text { SCS } \downarrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $t_{\text {DEE }}$ |  |  | 0 | - | ns |  |
| SCK $\downarrow \rightarrow$ SCS $\uparrow$ clock switching time | $t_{s c c}$ | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | $\begin{gathered} \text { Master mode } \\ \text { round } \\ \text { operation } \\ \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ \left(\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \\ \hline \end{gathered}$ | $3 \mathrm{c}_{\text {cLK_LCPnA }}{ }^{* 4}+0$ | $3 \mathrm{c}_{\text {cLK_LCPnA }}{ }^{* 4}+50$ | ns |  |

*1: tcssu = SCSTR:CSSU[7:0] x serial chip select timing operating clock
*2: tcshd $=$ SCSTR:CSHD[7:0] x serial chip select timing operating clock
*3: tcsds $=$ SCSTR:CSDS[15:0] $\times$ serial chip select timing operating clock
For details on *1, *2, and *3 above, see the hardware manual.
*4 tcLk_LCPnA $\mathrm{n}=0: \mathrm{ch} .0$ to ch. $4, \mathrm{n}=1: \mathrm{ch} .8$ to ch. 12

## Notes:

- $\quad$ This is the AC characteristic in CLK synchronized mode.
- $\quad C L$ is the load capacitance applied to pins during testing.
- $\quad$ The maximum baud rate is limited by the internal operating clock used and other parameters. For details, see the hardware manual



## (5-1-8) Serial Chip Select Used (SCSCR:CSEN = 1)

■Serial clock output signal detect level "L" (SMR, SCSFR:SCINV = 1)
■Serial Chip select inactive level "L" (SCSCR, SCSFR:CSLVL = 0)
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} s \mathrm{ss}=\mathrm{AVss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| $\begin{array}{\|l} \hline \mathrm{SCS} \uparrow \rightarrow \mathrm{SCK} \uparrow \\ \text { setup time } \end{array}$ | $\mathrm{t}_{\text {css }}$ | SCK0 to SCK4, SCK8 to SCK12, | Master mode$\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{LL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{CLL}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{LL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $\mathrm{tcssu}^{* 1}-50$ | - | ns |  |
| $\text { SCK } \downarrow \rightarrow \text { SCS } \downarrow$ hold time | $\mathrm{t}_{\text {cSHI }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | $\mathrm{tcSHo}^{* 2}+0$ | - | ns |  |
| SCS deselect time | $\mathrm{t}_{\text {csol }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | $\begin{gathered} \mathrm{t}_{\text {csps }}{ }^{3}-50 \\ +5 \mathrm{t}_{\text {cLK_LCPnA }}{ }^{* 4} \end{gathered}$ | - | ns |  |
| $\begin{array}{\|l} \hline \mathrm{SCS} \uparrow \rightarrow \mathrm{SCK} \uparrow \\ \text { setup time } \end{array}$ | $\mathrm{t}_{\text {csse }}$ | SCK0 to SCK4, SCK8 to SCK12, | Slave mode ( $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$, $\mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}$ ), ( $\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}$, $\mathrm{l}_{\mathrm{OL}}=-1 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}$ ) | $3 \mathrm{tcLLK}_{\text {_LCPaA }}{ }^{* 4}+30$ | - | ns |  |
| $\text { SCK } \downarrow \rightarrow \text { SCS } \downarrow$ hold time | $\mathrm{t}_{\text {cSHE }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | 0 | - | ns |  |
| SCS deselect time | $\mathrm{t}_{\text {csie }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x } \end{aligned}$ |  | 3tclı__LCPnA ${ }^{* 4}+30$ | - | ns |  |
| $\begin{array}{\|l} \mathrm{SCS} \uparrow \rightarrow \text { SOT } \\ \text { delay time } \end{array}$ | $\mathrm{t}_{\text {DSE }}$ | $\begin{aligned} & \text { SCS0x to SCS4x, } \\ & \text { SCS8x to SCS12x, } \\ & \text { SOT0 to SOT4, } \\ & \text { SOT8 to SOT12 } \end{aligned}$ |  | - | 40 | ns |  |
| $\begin{aligned} & \text { SCS } \downarrow \rightarrow \text { SOT } \\ & \text { delay time } \end{aligned}$ | $t_{\text {deE }}$ |  |  | 0 | - | ns |  |
| SCK $\uparrow \rightarrow$ SCS $\uparrow$ clock switching time | tscc | SCK0 to SCK4, SCK8 to SCK12, SCS0x to SCS4x, SCS8x to SCS12x | Master mode round operation ( $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$, $\mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}$ ), ( $\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}$, $\mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}$, $\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}$ ) | $3 \mathrm{tcluk}_{\text {_LCPna }}{ }^{* 4}+0$ | $\begin{gathered} 3 \mathrm{t}_{\mathrm{CLK} \_ \text {LCPPA }}{ }^{* 4} \\ +50 \end{gathered}$ | ns |  |

*1: tcssu = SCSTR:CSSU[7:0] x serial chip select timing operating clock
*2: tcshd $=$ SCSTR:CSHD[7:0] x serial chip select timing operating clock
*3: tcsds $=$ SCSTR:CSDS[15:0] $x$ serial chip select timing operating clock
For details on *1, *2, and *3 above, see the hardware manual.
*4 tclk_LCPnA $n=0: c h .0$ to ch. $4, \mathrm{n}=1: \mathrm{ch} .8$ to ch. 12

## Notes:

- $\quad$ This is the AC characteristic in CLK synchronized mode.
- $\quad C L$ is the load capacitance applied to pins during testing.
- $\quad$ The maximum baud rate is limited by the internal operating clock used and other parameters.

For details, see the hardware manual.


| SCSx output | $\xrightarrow{\text { sscc }}$ |
| :---: | :---: |
| SCSy output | $\mathrm{V}_{\mathrm{OH}}$ |
| SCK output | $\sqrt{\mathrm{v}_{\mathrm{OH}}}$ <br> mode round operation $y$ are different value) |

### 10.4.7.2 UART (Async Serial Interface) Timing (SMR:MD[2:0] $=000_{B}, 001_{B}$ )

## (5-2-1) External Clock Selected (BGR:EXT = 1)

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{ss}=\mathrm{AVss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Serial clock "L" pulse width | tstsh | SCK0 to SCK4, SCK8 to SCK12 | $\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $\mathrm{t}_{\text {cLK_LCPAA }}{ }^{*}+10$ | - | ns |  |
| Serial clock " H " pulse width | $\mathrm{t}_{\text {SHSL }}$ |  |  | $\mathrm{t}_{\text {LLK_LCPAA }}{ }^{*}+10$ | - | ns |  |
| SCK fall time | $\mathrm{t}_{\mathrm{F}}$ |  |  | - | 5 | ns |  |
| SCK rise time | $\mathrm{t}_{\mathrm{R}}$ |  |  | - | 5 | ns |  |

*: $\mathrm{n}=0: \mathrm{ch} .0$ to ch. $4, \mathrm{n}=1: \mathrm{ch} .8$ to ch. 12


External clock selected
10.4.7.3 LIN Interface (v2.1) (LIN Communication Control Interface (v2.1)) Timing (SMR:MD[2:0] = 011B)

## (5-3-1) External Clock Selected (BGR:EXT = 1)

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{V}_{\mathrm{ss}}=\mathrm{DV}$ ss $=\mathrm{AV} \mathrm{Ss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Serial clock "L" pulse width | tstsh | SCK0 to SCK4, SCK8 to SCK12 | $\begin{aligned} & \left(\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-2 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=2 \mathrm{~mA}\right), \\ & \left(\mathrm{CL}_{\mathrm{L}}=20 \mathrm{pF},\right. \\ & \mathrm{I}_{\mathrm{OL}}=-1 \mathrm{~mA}, \\ & \left.\mathrm{I}_{\mathrm{OH}}=1 \mathrm{~mA}\right) \end{aligned}$ | $\mathrm{t}_{\text {cLK_LCPna }}{ }^{*}+10$ | - | ns |  |
| Serial clock "H" pulse width | $\mathrm{t}_{\text {SHSL }}$ |  |  | $\mathrm{t}_{\text {CLK_LCPna }}{ }^{*}+10$ | - | ns |  |
| SCK fall time | $\mathrm{t}_{\mathrm{F}}$ |  |  | - | 5 | ns |  |
| SCK rise time | $\mathrm{t}_{\mathrm{R}}$ |  |  | - | 5 | ns |  |

*: $\mathrm{n}=0: \mathrm{ch} .0$ to ch. $4, \mathrm{n}=1: \mathrm{ch} .8$ to ch. 12


External clock selected
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=5.0 \mathrm{~V}+5 \% /-10 \%, \mathrm{~V} s=\mathrm{AV} s=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Standard Mode |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| SCL clock frequency | fscL | $\begin{gathered} \text { SCLO, SCL3, SCL4, } \\ \text { SCL8 to SCL11 } \end{gathered}$ | $\begin{gathered} \mathrm{CL}=50 \mathrm{pF}, \\ \mathrm{R}=(\mathrm{Vp} / \mathrm{loL})^{* 1} \end{gathered}$ | 0 | 100 | kHz |  |
| Repeat "start" condition hold time SDA $\downarrow \rightarrow$ SCL $\downarrow$ | $\mathrm{t}_{\text {hdsta }}$ | ```SDA0, SDA3, SDA4, SDA8 to SDA11 SCL0, SCL3, SCL4, SCL8 to SCL11``` |  | 4.0 | - | $\mu \mathrm{s}$ |  |
| Period of "L" for SCL clock | tow | $\begin{gathered} \text { SCL0, SCL3, SCL4, } \\ \text { SCL8 to SCL11 } \end{gathered}$ |  | 4.7 | - | $\mu \mathrm{s}$ |  |
| Period of "H" for SCL clock | $\mathrm{t}_{\text {HIGH }}$ |  |  | 4.0 | - | $\mu \mathrm{s}$ |  |
| Repeat "start" condition setup time SCL $\uparrow \rightarrow$ SDA $\downarrow$ | $\mathrm{t}_{\text {SUSTA }}$ | ```SDA0, SDA3, SDA4, SDA8 to SDA11 SCL0, SCL3, SCL4, SCL8 to SCL11``` |  | 4.7 | - | $\mu \mathrm{s}$ |  |
| Data hold time <br> SCL $\downarrow \rightarrow$ SDA $\downarrow \uparrow$ | $\mathrm{th}_{\text {hdat }}$ |  |  | 0 | $3.45^{*}$ | $\mu \mathrm{s}$ |  |
| Data setup time <br> SDA $\downarrow \uparrow \rightarrow$ SCL $\uparrow$ | $\mathrm{t}_{\text {sudat }}$ |  |  | 250 | - | ns |  |
| "Stop" condition setup time SCL $\uparrow \rightarrow$ SDA $\uparrow$ | $\mathrm{t}_{\text {susto }}$ |  |  | 4.0 | - | $\mu \mathrm{s}$ |  |
| Bus-free time between "stop" condition and "start" condition | $\mathrm{t}_{\text {buF }}$ | - |  | 4.7 | - | $\mu \mathrm{s}$ |  |
| Noise filter | $\mathrm{t}_{\text {sp }}$ | - |  | $\mathrm{t}_{\text {NFT }}{ }^{*}$ | - | ns |  |

*1: R and CL represent the pull-up resistance and load capacitance of the SCL and SDA output lines, respectively Vp shows that the power-supply voltage of the pull-up resistor and IOL shows the VOL guarantee current.
*2: The maximum tHDDAT only has to be met if the device does not extend the "L" width (tLOW) of the SCL signal.
*3: tNFT $=($ NFCR:NFT[4:0]+1) $\times 2 \times$ tCLK_LCP0A

## Notes:

- In this device, Standard mode ( Max. 100 kbps ) is supported only.
- $\quad$ This model does not support high-speed mode. (Max. 400 kbps ).
- $\quad$ This model does not support Min. Iol $=3 \mathrm{~mA}$ with V OL $=0.4 \mathrm{~V}$.

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{ss}=\mathrm{AV} \mathrm{ss}=0.0 \mathrm{~V}$ )
(External load capacitance 16 pF )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Cycle time | tcycm | SPICLK | 2 mA is selected in ODR bit in PPC_PCFGR register. | 62.5 | - | ns | Slave mode is not supported. |
| Clock high width | tcwh | SPICLK |  | 0.5tсусм - 4 | - | ns |  |
| Clock low width | tcwL | SPICLK |  | 0.5tсусм - 4 | - | ns |  |
| Valid SPISEL $\rightarrow$ SPICLK start time (mode0 / mode4) | toslsksdr | SPICLK, SPISELO to SPISEL3 |  | 1.5tсусм- 15 | - | ns | Minimum setting value of SS2CD bit is $01_{B}$ |
| SPICLK end $\rightarrow$ Invalid SPISEL time (mode0 / mode4) | toskslsdr |  |  | tсусм - 10 | - | ns |  |
| SPIDAT output time | tosdatsdr | SPICLK, SPIDAT0 to SPIDAT3 |  | -10 | 10 | ns |  |
| SPIDAT setup | tDSSETSDR | SPICLK, SPIDATO to SPIDAT3 | "CMOS Schmitt input" and "Disable noise filter" are selected in PPC_PCFGR register. | 14 | - | ns |  |
| SPIDAT hold (mode0) | tsdholdsdro |  |  | 0.5 tcycm | - | ns |  |
| SPIDAT hold (mode4) | tsdholdsir 4 |  |  | 0 | - | ns |  |




### 10.4.8.2 DDR Mode Timing

( $\mathrm{T}_{\mathrm{A}}:$ Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{Ss}=\mathrm{AVss}=0.0 \mathrm{~V}$ )
(External load capacitance 16 pF )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Cycle time | tcycm | SPICLK | 2 mA is selected in ODR bit in PPC_PCFGR register. | 62.5 | - | ns | Slave mode is not supported. |
| Clock high width | tcwh | SPICLK |  | 0.5tсусм - 4 | - | ns |  |
| Clock low width | tcw | SPICLK |  | 0.5tсусм - 4 | - | ns |  |
| Valid SPISEL $\rightarrow$ SPICLK start time (mode0) | toslskddr | SPICLK, SPISELO to SPISEL3 |  | $\begin{gathered} 1.75 \text { tсусм }_{15} \end{gathered}$ | - | ns | Minimum setting value of SS2CD bit is 01в |
| SPICLK end $\rightarrow$ Invalid SPISEL time (mode0) | toskslddr |  |  | $\begin{gathered} 0.75 \text { tсусм - } \\ 10 \end{gathered}$ | - | ns |  |
| SPIDAT output time | tosdatdor | SPICLK, SPIDATO to SPIDAT3 |  | 0.25tсусм-10 | $\begin{gathered} 0.25 t_{\text {tүсм }}+ \\ 10 \end{gathered}$ | ns |  |
| SPIDAT setup | tDSSETDDR | SPICLK, SPIDATO to SPIDAT3 | "CMOS Schmitt input" and <br> "Disable noise filter" are selected in PPC_PCFGR register. | 14 | - | ns |  |
| SPIDAT hold (mode0) | tsdholdddr |  |  | 0 | - | ns |  |



### 10.4.9 High Current Output Slew Rate

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{Vss}=\mathrm{DV} \mathrm{ss}=\mathrm{AVss}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Output rise / fall time | $\begin{aligned} & \mathrm{t}_{\mathrm{R} 2}, \\ & \mathrm{t}_{\mathrm{F} 2} \end{aligned}$ | P229 to P231, P300 to P302, P304 to P305, P307 to P309, P312 to P315, P317 | - | 15 | - | 100 | ns | load capacitance 85 pF |

- $\quad$ Slew rate output timing

tR2

tF2


### 10.5 Timer Input Timing

$$
\text { ( } \mathrm{T}_{\mathrm{A}}: \text { Recommended operating conditions, } \mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V} \mathrm{ss}=\mathrm{DV} \mathrm{ss}=\mathrm{AV} \mathrm{ss}=0.0 \mathrm{~V} \text { ) }
$$

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Input pulse width | $\mathrm{t}_{\mathrm{TWH}}$, <br> $\mathrm{t}_{\text {TWL }}$ | TIN0 to TIN3, TIN16 to TIN19 | - | 4tclk_LCPnA ${ }^{\text {* }}$ | - | ns | 4tclk_LCPnA ${ }^{*} \geq 100 \mathrm{~ns}$ |
|  |  |  |  | 100 |  |  | 4tclk_LCPnA ${ }^{*}<100 \mathrm{~ns}$ |
|  |  | TIN32 to TIN33 | - | $4 \mathrm{t}_{\text {CLK_LLPBM2 }}$ | - | ns | $4 \mathrm{t}_{\text {cL__LLPBM2 } 2} \geq 100 \mathrm{~ns}$ |
|  |  |  |  | 100 |  |  | $4 \mathrm{t}_{\text {CLK_LLPBM2 }}<100 \mathrm{~ns}$ |
|  |  | IN0 to IN11 | - | $4 \mathrm{t}_{\text {CLK_LCPOA }}$ | - | ns | $4 \mathrm{t}_{\text {CLK_LCPOA }} \geq 100 \mathrm{~ns}$ |
|  |  |  |  | 100 |  |  | $4 \mathrm{t}_{\text {cLK_LCPOA }}<100 \mathrm{~ns}$ |
|  |  | TEXTO to 5 | - | $4 \mathrm{t}_{\text {CLK_LCPOA }}$ | - | ns | $4 \mathrm{t}_{\text {CLK_LCPOA }} \geq 100 \mathrm{~ns}$ |
|  |  |  |  | 100 |  |  | $4 \mathrm{t}_{\text {CLK_LCPOA }}<100 \mathrm{~ns}$ |
|  |  | TIOA0 to TIOA29 TIOB0 to TIOB29 | - | $4 \mathrm{t}_{\text {CLK_LCPOA }}$ | - | ns | $4 \mathrm{t}_{\text {CLK_LCPOA }} \geq 100 \mathrm{~ns}$ |
|  |  |  |  | 100 |  |  | $4 \mathrm{t}_{\text {CLK_LCPOA }}<100 \mathrm{~ns}$ |

*: $\mathrm{n}=0:$ ch. 0 to ch.3, $\mathrm{n}=1: \mathrm{ch} .16$ to ch. 19

- $\quad$ Timer input timing

TINx
INx
TEXTx TIOAx, TIOBx


### 10.6 QPRC Timing

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{sS}}=\mathrm{DV}_{\mathrm{SS}}=\mathrm{AV} \mathrm{VS}_{\mathrm{SS}}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| AIN pin "H" width | $\mathrm{t}_{\text {AHL }}$ | AIN8 to AIN9 | - | 4tcLk_LCP1A | - | ns | $\begin{aligned} & \text { 4tCLK_LCP1A } \\ & \geq 100 \mathrm{~ns} \end{aligned}$ |
| AIN pin "L" width | tall | AIN8 to AIN9 | - |  |  |  |  |
| BIN pin "H" width | $\mathrm{t}_{\mathrm{BHL}}$ | BIN8 to BIN9 | - |  |  |  |  |
| BIN pin "L" width | tblı | BIN8 to BIN9 | - |  |  |  |  |
| Time from AIN pin "H" level to BIN rise | $t_{\text {aubu }}$ | AIN8 to AIN9, BIN8 to BIN9 | PC_Mode2 or PC_Mode3 |  |  |  |  |
| Time from BIN pin "H" level to AIN fall | $t_{\text {buad }}$ | AIN8 to AIN9, BIN8 to BIN9 | PC_Mode2 or PC_Mode3 |  |  |  |  |
| Time from AIN pin "L" level to BIN fall | $t_{\text {Adbd }}$ | AIN8 to AIN9, BIN8 to BIN9 | PC_Mode2 or PC_Mode3 |  |  |  |  |
| Time from BIN pin "L" level to AIN rise | $t_{\text {bdau }}$ | AIN8 to AIN9, BIN8 to BIN9 | PC_Mode2 or PC_Mode3 |  |  |  |  |
| Time from BIN pin "H" level to AIN rise | truau | AIN8 to AIN9, BIN8 to BIN9 | PC_Mode2 or PC_Mode3 |  |  |  |  |
| Time from AIN pin "H" level to BIN fall | $t_{\text {AUBD }}$ | AIN8 to AIN9, BIN8 to BIN9 | PC_Mode2 or PC_Mode3 |  |  |  |  |
| Time from BIN pin "L" level to AIN fall | $t_{\text {tbdad }}$ | AIN8 to AIN9, BIN8 to BIN9 | PC_Mode2 or PC_Mode3 |  |  |  |  |
| Time from AIN pin "L" level to BIN rise | $t_{\text {AdBu }}$ | AIN8 to AIN9, BIN8 to BIN9 | PC_Mode2 or PC_Mode3 |  |  |  |  |
| ZIN pin "H" width | tzHL | ZIN8 to ZIN9 | QCR:CGSC = "0" |  |  |  |  |
| ZIN pin "L" width | tzLL | ZIN8 to ZIN9 | QCR:CGSC = "0" |  |  |  |  |
| Time from determined ZIN level to AIN/BIN rise and fall | tzabe | AIN8 to AIN9, BIN8 to BIN9, ZIN8 to ZIN9 | QCR:CGSC = "1" |  |  |  |  |
| Time from AIN/BIN rise and fall time to determined ZIN level | $t_{\text {ABEZ }}$ | AIN8 to AIN9, BIN8 to BIN9, ZIN8 to ZIN9 | QCR:CGSC = "1" |  |  |  |  |





ZIN


### 10.7 Trigger Input Timing

$$
\text { ( } \mathrm{T}_{\mathrm{A}}: \text { Recommended operating conditions, } \mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{SS}}=\mathrm{DV} \mathrm{VS}_{\mathrm{SS}}=\mathrm{AV} \mathrm{SS}=0.0 \mathrm{~V} \text { ) }
$$

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Input pulse width | $\mathrm{t}_{\text {TRGH }}$, $\mathrm{t}_{\text {tRGL }}$ | INT0 to INT15 | - | 100 | - | ns |  |
|  |  | INT0 to INT15 | - | 1 | - | $\mu \mathrm{s}$ | Stop mode |

- $\quad$ Trigger input timing

INTx RXx
 ttrgh



### 10.8 NMI Input Timing

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{V}_{\mathrm{ss}}=\mathrm{AV}$ ss $=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Max |  |  |
| Input pulse width | t $_{\text {NMIL }}$ | NMIX | - | 300 | - |  |  |

NMIX input timing

10.9 Low-Voltage Detection (External Low-Voltage Detection)
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{V}_{\mathrm{SS}}=\mathrm{AV} \mathrm{V}_{\mathrm{SS}}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Power supply voltage range | VDP5 | VCC | - | 3.5 | - | 5.5 | V |  |
| Detection voltage | V DLO | VCC | $\begin{aligned} & \text { *1 } \\ & * 3 \end{aligned}$ | 3.6 | 3.8 | 4.0 | V | When power-supply voltage falls and detection level is set initially |
|  | VDL1 | VCC | $\begin{aligned} & * 1 \\ & * 4 \end{aligned}$ | 3.8 | 4.0 | 4.2 | V |  |
|  | VDL2 | VCC | $\begin{aligned} & \text { *1 } \\ & \text { *5 } \end{aligned}$ | 4 | 4.2 | 4.4 | V |  |
| Hysteresis width | Vhys | VCC | - | - | 100 | - | mV | When power-supply voltage rises |
| Low-voltage detection time | Td | - | - | - | - | 30 | $\mu \mathrm{s}$ |  |
| Power supply voltage regulation | - | VCC | - | -2 | - | 2 | V/ms | *2 |

*1: If the fluctuation of the power supply has exceeded the detection voltage range within the time less than the low-voltage detection time $\left(\mathrm{T}_{\mathrm{d}}\right)$, there is the possibility to generate or release after the power supply voltage has exceeded the detection voltage range.
*2: Please suppress the change of the power supply within the range of the power-supply voltage regulation to do a low-voltage detection by detecting voltage (VL)
*3: SYSC0_RUNLVDCFGR.LVDH1V $=0100$ в or SYSC0_PSSLVDCFGR.LVDH1V $=0100_{\text {в }}$
*4: SYSC0_RUNLVDCFGR.LVDH1V = 0101 в or SYSC0_PSSLVDCFGR.LVDH1V $=0101_{\mathrm{B}}$
*5: SYSC0_RUNLVDCFGR.LVDH1V $=0110_{\text {в }}$ or SYSC0_PSSLVDCFGR.LVDH1V $=0110_{\text {в }}$

### 10.10Low-Voltage Detection (RAM Retention Low-Voltage Detection)

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{V} s \mathrm{~s}=\mathrm{AV} s \mathrm{~s}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |
| Power supply voltage range | $\mathrm{V}_{\text {RDP5 }}$ | - | - | 0.6 | - | 1.4 | V |  |
| Detection voltage* | $\mathrm{V}_{\text {RDL }}$ | - | *1 | 0.9 | 0.95 | 1.0 | V | When power-supply voltage falls |
| Hysteresis width | $\mathrm{V}_{\text {RHYS }}$ | - | - | - | 75 | - | mV | When power-supply voltage rises |
| Low-voltage detection time | $\mathrm{T}_{\text {Rd }}$ | - | - | - | - | 30 | $\mu \mathrm{s}$ |  |

*: This LVD cannot be used to reliably generate a reset before voltage dips below minimum guaranteed MCU operation voltage, as this detection level is below the minimum guaranteed MCU operation voltage.
*1: If the fluctuation of the power supply has exceeded the detection voltage range within the time less than the low-voltage detection time $\left(T_{R d}\right)$, there is the possibility to generate or release after the power supply voltage has exceeded the detection voltage range.

### 10.11 Low-Voltage Detection (1.2 V Power Supply Low-Voltage Detection)

( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{V}_{\mathrm{SS}}=\mathrm{AV} \mathrm{V}_{\mathrm{SS}}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Conditions | Value |  |  | Unit | Remarks | Guaranteed MCU operation range |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Min | Typ | Max |  |  |  |
| Power supply voltage range | $\mathrm{V}_{\text {RDP5 }}$ | - | - | 0.6 | - | 1.4 | V |  | No |
| Detection voltage* | $\mathrm{V}_{\text {RDLO }}$ | - | $\begin{aligned} & \text { *1 } \\ & \text { *2 } \\ & \text { *4 } \end{aligned}$ | 0.92 | 0.97 | 1.02 | V | When powersupply voltage falls |  |
|  | $\mathrm{V}_{\text {RDL } 1}$ | - | $\begin{aligned} & * 3 \\ & * 4 \end{aligned}$ | 1.02 | 1.07 | 1.12 | v |  |  |
| Hysteresis width | $\mathrm{V}_{\text {RHYS }}$ | - | - | - | 75 | - | mV | When powersupply voltage rises |  |
| Low-voltage detection time | $\mathrm{T}_{\text {Rd }}$ | - | - | - | - | 30 | $\mu \mathrm{s}$ |  |  |

*: This LVD cannot be used to reliably generate a reset before voltage dips below minimum guaranteed MCU operation voltage, as these detection levels are below the minimum guaranteed MCU operation voltage.
*1: If the fluctuation of the power supply has exceeded the detection voltage range within the time less than the low-voltage detection time $\left(T_{R d}\right)$, there is the possibility to generate or release after the power supply voltage has exceeded the detection voltage range.
*2: SYSC0_RUNLVDCFGR.LVDL1V = 10 ${ }_{\mathrm{B}}$ or SYSC0_PSSLVDCFGR.LVDL1V = $10_{\mathrm{B}}$
*3: SYSC0_RUNLVDCFGR.LVDL1V $=11_{\mathrm{B}}$ or $\operatorname{SYSC0\_ PSSLVDCFGR.LVDL1V~}=11_{\mathrm{B}}$
*4: These detection voltage level settings are below the minimum operation voltage.
Between these detection voltages and the minimum operation voltage, MCU functions are not guaranteed except for the low voltage detector.
Note that although the detection level is below the minimum operation voltage, the LVD reset factor flag is set as the voltage drops below the detection level.

### 10.12A/D Converter

10.12.1 Electrical Characteristics
( $\mathrm{T}_{\mathrm{A}}$ : Recommended operating conditions, $\mathrm{Vcc}=\mathrm{DVcc}=5.0 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{\mathrm{SS}}=\mathrm{DV}_{\mathrm{SS}}=\mathrm{AV} \mathrm{VS}=0.0 \mathrm{~V}$ )

| Parameter | Symbol | Pin Name | Value |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min | Typ | Max |  |  |
| Resolution | - | - | - | - | 12 | bit |  |
| Total Error | - | - | - | - | $\pm 12$ | LSB | *3 |
| Integral Nonlinearity | - | - | - | - | $\pm 4.0$ | LSB | *4 |
| Differential Nonlinearity | - | - | - | - | $\pm 1.9$ | LSB | * 4 |
| Zero transition voltage | $V_{z T}$ | *6 | $\begin{gathered} \text { AVRL } \\ -11.5 \mathrm{LSB} \end{gathered}$ | - | $\begin{gathered} \text { AVRL } \\ +12.5 \mathrm{LSB} \end{gathered}$ | V |  |
| Full-scale transition voltage | Vfst | *6 | $\begin{gathered} \text { AVRH } \\ -13.5 \mathrm{LSB} \end{gathered}$ | - | $\begin{gathered} \text { AVRH } \\ +10.5 \mathrm{LSB} \end{gathered}$ | V | 5 |
| Sampling time | tsmp | - | 0.3 | - | 12 | $\mu \mathrm{s}$ | *1 |
| Compare time | tcmp | - | 0.7 | - | 28 | $\mu \mathrm{s}$ | *1 |
| A/D conversion time | tcnv | - | 1.0 | - | 40 | $\mu \mathrm{s}$ | *1 |
| Analog port input current | Itin | *7 | -1.0 | - | 1.0 | $\mu \mathrm{A}$ | $V_{\text {Avss }} \leq$ <br> $\mathrm{V}_{\mathrm{AIN}} \leq \mathrm{V}_{\mathrm{AVCC}}$ |
|  |  | *8 | -2.0 | - | 2.0 |  |  |
|  |  | *9 | -3.0 | - | 3.0 |  |  |
| Analog input voltage | $V_{\text {AIN }}$ | * 6 | AVSS | - | AVRH | V |  |
| Reference voltage | AVRH | AVRH0,AVRH1 | 4.5 | - | 5.5 | V | AVcc $\geq$ AVRH |
|  | AVRL | AVRLO/AVSSO, <br> AVRL1/AVSS1 | - | 0.0 | - | V |  |
| Power supply current | $\mathrm{I}_{\mathrm{A}}$ | AVCC | - | 500 | 900 | $\mu \mathrm{A}$ | per one unit |
|  | IA |  | - | 1.0 | 100 | $\mu \mathrm{A}$ | *2 |
|  | IR | AVRH | - | 1 | 2 | mA | per one unit |
|  | IRH |  | - | - | 5.0 | $\mu \mathrm{A}$ | *2 |
| Variation between channels | - | *10 | - | - | 4 | LSB |  |
|  |  | AN32 to AN43, AN46 to AN53, AN55 to AN62 | - | - | 4 | LSB |  |

*1: Time for each channel
*2: The power supply current $\left(\mathrm{V}_{\mathrm{cc}}=A V_{c c}=5.0 \mathrm{~V}\right)$ is specified if the $\mathrm{A} / \mathrm{D}$ converter is not operating and CPU is stopped.
*3: Total Error is a comprehensive static error that includes the linearity. 1LSB = (AVRH-AVRL)/4096
*4: $1 \mathrm{LSB}=\left(\mathrm{V}_{\mathrm{FST}}-\mathrm{V}_{\mathrm{ZT}}\right) / 4094$
*5: 1LSB = (AVRH-AVRL)/4096
*6: AN3, AN5, AN6, AN9, AN10, AN12 to AN15, AN17 to AN24, AN27 to AN43, AN46 to AN53, and AN55 to AN62
*7: AN3, AN5, AN6, AN9, AN10, AN12 to AN15, AN17 to AN24, and AN27 to AN42
*8: AN0 to AN2, and AN43
*9: AN44 to AN62
*10: AN3, AN5, AN6, AN9, AN10, AN12 to AN15, AN17 to AN24, and AN27 to AN31

### 10.12.2 Notes on Using A/D converters

## About the Output Impedance of an External Circuit for Analog Input

When the external impedance is too high, the analog voltage sampling time may become insufficient. In this case, we recommend attaching a capacitor (about $0.1 \mu \mathrm{~F}$ ) to an analog input pin.

## Analog input circuit model



Rint : Analog input impedance 3.9 kiloohms (max) ( $4.5 \mathrm{~V} \leq \mathrm{AVcc} \leq 5.5 \mathrm{~V}$ )

Cint : Capacitance of MCU input pin 11.0 pF (max) ( $4.5 \mathrm{~V} \leq \mathrm{AVcc} \leq 5.5 \mathrm{~V}$ )

Rext : External driving impedance
Cext : Capacitance of PCB at A/D converter input
The following approximation formula for the replacement model above can be used: sampling time $($ minimum $)=9 \times(($ Rin + Rext $) \times$ Cin + Rext $\times$ Cext $)$

Note: Listed values must be considered as reference values.

### 10.12.3 Definition of Terms

Resolution: Analog variation that is recognized by an A/D converter
Integral Nonlinearity error *: Deviation of the straight line connecting the zero transition point ("0000 00000000 " <--> "0000 0000 0001") and full-scale transition point ("1111 1111 1110" <--> "1111 1111 1111") from actual conversion characteristics includes zero transition error, full-scale transition error, and non-linearity error.
Differential Nonlinearity error: Deviation from the ideal value of the input voltage required for changing the output code by 1 LSB Total error: Difference between the actual value and the theoretical value. The total error includes zero transition error, full-scale transition error, and non linearity error.
*: Represented as "Linearity error" in the former product series.


Integral Nonlinearity


Differential Nonlinearity


AVSS Analog input (AVRL)
Integral Nonlinearity of digital output $\mathrm{N}=\frac{\mathrm{V}_{\mathrm{NT}}-\left\{1 \mathrm{LSB} \times(\mathrm{N}-1)+\mathrm{V}_{\mathrm{ZT}}\right\}}{1 \mathrm{LSB}} \quad[\mathrm{LSB}]$
Differential Nonlinearity of digital output $N=\frac{V_{(N+1)} T-V_{N T}}{1 \text { LSB }}-1$ LSB [LSB]

$$
1 \mathrm{LSB}=\frac{\mathrm{V}_{\mathrm{FST}}-\mathrm{V}_{\mathrm{ZT}}}{4094} \quad[\mathrm{~V}]
$$

$\mathrm{V}_{\text {Zт: }}$ Voltage for which digital output changes from " $0 \times 000$ " to " $0 \times 001$ "
$V_{\text {FST: }}$ Voltage for which digital output changes from "0xFFE" to "0xFFF".

### 10.13Flash Memory

| Parameter | Rating |  |  | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | Min | Typ | Max |  |  |
| Sector erase time | - | 300 | 1100 | ms | 8-KB sector ${ }^{*}$ Internal preprogramming time included |
|  | - | 800 | 3700 | ms | 64-KB sector ${ }^{* 1}$ Internal preprogramming time included |
| 8-bit write time | - | 15 | 288 | $\mu \mathrm{s}$ | System-level overhead time excluded*1 |
| 16-bit write time | - | 19 | 384 | $\mu \mathrm{s}$ | System-level overhead time excluded*1 |
| 32-bit write time | - | 27 | 567 | $\mu \mathrm{s}$ | System-level overhead time excluded*1 |
| 64-bit write time | - | 45 | 945 | $\mu \mathrm{s}$ | System-level overhead time excluded ${ }^{* 1}$ |
| 8-bit (with ECC) write time | - | 19 | 384 | $\mu \mathrm{s}$ | System-level overhead time excluded*1 |
| 16-bit (with ECC) write time | - | 23 | 483 | $\mu \mathrm{s}$ | System-level overhead time excluded*1 |
| 32-bit (with ECC) write time | - | 31 | 651 | $\mu \mathrm{s}$ | System-level overhead time excluded*1 |
| 64-bit (with ECC) write time | - | 49 | 1029 | $\mu \mathrm{s}$ | System-level overhead time excluded*1 |
| Erase count ${ }^{*} 2 /$ <br> Data retention time | 1,000/20 years, 10,000/10 years, 100,000/5 years | - | - | - | Temperature at write/erase time Average temperature $\mathrm{T}_{\mathrm{A}}=+85$ degrees Celsius |

*1: Guaranteed value for up to 100,000 erases
*2: Number of erases for each sector

## Notes:

- While the Flash memory is written or erased, shutdown of the external power (Vcc) is prohibited.
- In the application system where Vcc might be shut down while writing or erasing, be sure to turn the power off by using an external low-voltage detection function.
- $\quad$ To put it concretely, after the external power supply voltage falls below the detection voltage (VDL), hold Vcc at 2.7 V or more within the duration calculated by the following expression:

$$
\mathrm{T}_{\mathrm{d}}^{* 1}[\mu \mathrm{~s}]+\left(1 / \mathrm{F}_{\mathrm{CRF}}{ }^{* 2}[\mathrm{MHz}]\right) \times 1029+25[\mu \mathrm{~s}]
$$

*1 : See "12.8 Low-voltage detection (external low-voltage detection)"
*2 : See "12.4.1 Source clock timing"

## 11. Ordering Information

| Part Number | Package |
| :---: | :---: |
| S6J3129HACSE20000 |  |
| $y$ S6J3129HBCSE2000A | 144-pin Plastic, TEQFP(LEU144) |
| S6J312AHACSE2000A |  |

## Note:

- S6J312xHzCSEy0000*
" $x$ "/" $y$ " is an part number option. For the part number option, see the following table. For details on each package, see "PACKAGE DIMENSIONS."
* z : A/B


## 12. Part Number Option

| Part Number Option "x" | FLASH Memory |
| :---: | :---: |
| A | 1 MByte |
| 9 | 768 KByte |


| Part Number Option "y" |  |
| :---: | :---: |
| 2 | PureSn \& Halogen Free |


| Part Number Option " $z$ " | SHE |
| :---: | :---: |
| A | SHE ON |
| B | SHE OFF |

## 13. Package Dimensions



## 14. Errata

This section describes the errata for the S6J3120 Series. Details include errata trigger conditions, scope of impact, available workarounds, and silicon revision applicability. Contact your local Cypress Sales Representative if you have questions.

## Part Numbers Affected

## Part Number

S6J3129HACSE20000
S6J3129HBCSE2000A
S6J312AHACSE2000A

## S6J3120 Qualification Status

Product Status: Production

## Errata Summary

The following table defines the errata applicability to available S6J3120 Series devices.

| Items | Part Number | Fix Status |
| :--- | :---: | :---: |
| 1. MCAN wrong message transmission |  |  |
| 2. CAN FD controller message order inversion when <br> transmitting from dedicated Tx Buffers configured with <br> same Message ID | S6J3129HACSE20000 <br> S6J3129HBCSE2000A | No silicon fix planned. |
| 3. CAN FD incomplete description of Dedicated Tx Buffers <br> and Tx Queue related to transmission from multiple buffers <br> configured with the same Message ID | S6J312AHACSE2000A |  |

1. MCAN wrong message transmission

## - Problem Definition

There is a possibility a message with an ID (arbitration field) and a format and DLC (control field) is transmitted which was not configured by the application. The message itself is syntactically correct and can be received by other nodes.

The occurrence of the limitation requires a certain relationship in time between a transmission request for sending a message and the coincidence of noise in the 3rd bit of intermission field which is treated as the start of new message transmission (SoF).

- Trigger Condition

Under the following conditions a message with wrong ID, format and DLC is transmitted:

- M_CAN is in state "Receiver" (PSR.ACT = "10"), no pending transmission.
- A new transmission is requested after sample point of 2 nd bit of intermission but before the 3rd bit of Intermission is reached.
- The CAN bus is sampled dominant at the third bit of Intermission which is treated as SoF (see ISO11898-1:2015 Section 10.4.2.2).


## - Scope of Impact

Under the conditions listed above it may happen, that:

- The shift register is not loaded with ID, format, and DLC of the requested message.
- The M_CAN will start arbitration with wrong ID, format, and DLC.
- In case the ID won arbitration, a CAN message with valid CRC is transmitted.
- In case this message is acknowledged, the ID stored in the Tx Event FIFO is the ID of the requested Tx message and not the ID of the message transmitted on the CAN bus
- Neither an error is detected by the transmitting node nor at the receiving node.


## ■ Workaround

## Workaround 1:

This workaround avoids submitting a transmission request in the critical time window of about one bit time before the sample point of the $3^{\text {rd }}$ bit of intermission field when on other pending transmission request exists:

- Request a new transmission if another transmission is already pending or when the M_CAN / M_TTCAN is not in state "Receiver" (when PSR.ACT = "10").
- If no pending transmission request exists, the application software needs to evaluate the Rx Interrupt flags IR.DRX, IR.RF0N, IR.RF1N which are set at the last bit of EoF when a received and accepted message gets valid.
- A new transmission may be requested by writing to TXBAR once the Rx interrupt occurred and the application waited another 3 bit times before submitting its Tx request. Note the Rx interrupt is generated at the last bit of EoF which is followed by three bits of Intermission.
- The application has to take care that the transmission request for the CAN Protocol Controller is activated before the critical window of the following reception is reached.
A supplemental action can be applied in order to detect messages which contain wrong ID and control filed information:
- A checksum covering arbitration and control fields can be added to the data field of the message to be transmitted, to detect frames transmitted with wrong arbitration and control fields.


## Workaround 2:

This workaround ensures that always at least one pending Tx request exists. If that is the case, the application may launch its $T x$ requests at any time without suffering from the limitation.

- Define a low priority message with DLC $=0$ that can be sent without harm. E.g. loses arbitration against all other application messages, does not pass any acceptance filter of nodes in the same network. DLC $=0$ shall reduce latency for other application messages.
- Configure sufficient Tx buffers - at least two - for this message type thus that there is always another one waiting to be sent. E.g. an application that cannot react quickly enough with the time a single message of this type is sent, more than 2 Tx buffer may become necessary.
- The application uses the standard interfaces of the CAN / CAN FD stack to feed these messages.
- Whenever Tx confirmation is indicated for the second but last message of this type with pending Tx request, the application needs to submit at least one new Tx request. Note Tx confirmation is a standard feature in the AUTOSAR SW architecture.
- Before initially leaving INIT state of the M_CAN IP by clearing CCCR.INIT bit, make sure to activate a Tx request after having cleared CCCR.CCE. This will ensure that the conditions for the occurrence of the limitation when synchronizing to the CAN bus the first time after RESET are prevented.


## - Fix Status

No silicon fix planned
2. CAN FD controller message order inversion when transmitting from dedicated Tx Buffers configured with same Message ID

## ■ Problem Definition

CAN FD controller message order inversion when multiple Tx Buffers that are configured with the same Message ID have pending Tx requests.

## - Configuration

Several Tx Buffers are configured with the same Message ID. Transmission of these Tx Buffers is requested sequentially with a delay between the individual Tx requests.

## - Expected behavior

When multiple Tx Buffers that are configured with the same Message ID have pending Tx requests, they shall be transmitted in ascending order of their Tx Buffer numbers. The Tx Buffer with lowest buffer number and pending Tx request is transmitted first.

## ■ Observed behavior

It may happen, depending on the delay between the individual Tx requests, that where multiple Tx buffers are configured with the same Message ID, the Tx buffers are not transmitted in order of the Tx buffer number (lowest number first).

## - Workaround

First, write the group of Tx messages with the same Message ID to the Message RAM and then request transmission of all these messages concurrently by a single write access to TXBAR. Before requesting a group of Tx messages with this Message ID, ensure that no message with this Message ID has a pending Tx request.
Applications that cannot use the above workaround can implement a counter within the data section of their messages sent with same ID in order to allow the recipients to determine the correct sending sequence.

## - Fix Status

No silicon fix planned
3. CAN FD incomplete description of Dedicated Tx Buffers and Tx Queue related to transmission from multiple buffers configured with the same Message ID

## - Problem Definition

There was an incomplete description related to transmission from multiple buffers configured with the same Message ID in Section 3.5.2 Dedicated Tx Buffers and Section 3.5.4 Tx Queue of the Hardware Manual.

## - Detailed explanation

The following is the updated description in Section 3.5.2 Dedicated Tx Buffers and Section 3.5.4 Tx Queue of the Hardware Manual.

## Section 3.5.2 Dedicated Tx Buffers:

- Original content in the Hardware Manual:

In case that multiple Tx Buffers are configured with the same Message ID, the Tx Buffer with the lowest buffer number is transmitted first.

- Enhancement:

These Tx buffers shall be requested in ascending order with the lowest buffer number first. Alternatively, all Tx buffers configured with the same Message ID can be requested simultaneously by a single write access to TXBAR.

## Section 3.5.4 Tx Queue:

- Original content in the Hardware Manual:

In case that multiple Queue Buffers are configured with the same Message ID, the Queue Buffer with the lowest buffer number is transmitted first.

- Replacement:

In case that multiple Tx Queue buffers are configured with the same Message ID, the transmission order depends on numbers of the buffers where the messages were stored for transmission. As these buffer numbers depend on the then current states of the PUT index, a prediction of the transmission order is not possible.

- Original content in the Hardware Manual:

An Add Request cyclically increments the Put Index to the next free Tx Buffer.

- Replacement:

The Put Index always points to that free buffer of the Tx Queue with the lowest buffer number.

## - Workaround

In case a defined order of transmission is required, the Tx FIFO shall be used for transmission of messages with the same Message ID. Alternatively, dedicated Tx buffers with the same Message ID shall be requested in ascending order with the lowest buffer number first or by a single write access to TXBAR. Alternatively, a single Tx Buffer can be used to transmit those messages one after the other.

## - Fix Status

No silicon fix planned. Use workaround.
Hardware Manual will be updated accordingly.

## 15. Appendix

### 15.1 Application 1: JTAG tool connection

This is an application example of JTAG tool connection.


## 16. Major Changes

| Page | Section | Change Results |
| :---: | :---: | :---: |
| Revision *A |  |  |
| 1 | Features Cortex-R5 Core | Revised the following note. (Error) <br> - ECC support for the TCM ports (Correct) <br> םECC support for the TCM ports for RAM |
| 1 | Features Peripheral Functions | ```Revised the full production and SHE-OFF series as follows. (Correct) ■Built-in Flash memory size \squareProgram: 1024 K + 64 KB (S6J312AHzB*)/768 K + 64 KB (S6J3129HzB*)/512 K +64 KB (S6J3128HzB*) \square*Z: A/B \squareWork: 112 KB (S6J312AHzB*)/ 112 KB (S6J3129HzB*)/112 KB (S6J3128HzB*) \square*Z: A/B``` |
| 1 | Features Peripheral Functions | ```Revised the full production and SHE-OFF series as follows. (Correct) Built-in RAM size -TCRAM 64 KB(S6J312AHzB*)/ 48 KB(S6J3129HzB*)/32 KB(S6J3128HzB*) - System SRAM 16 KB (S6J312AHzB*)/ 16 KB (S6J3129HzB*)/ 16 KB (S6J3128HzB*) - Backup RAM 8 KB (S6J312AHzB*)/ 8 KB (S6J3129HzB*)/8 KB (S6J3128HzB*) -*z: A/B``` |
| 1 | Features Peripheral Functions | Revised the full production and SHE-OFF series as follows. (Correct) <br> ■General-purpose ports: 112 channels (S6J312AHzB*)/ 112 channels (S6J3129HzB*)/ 112 channels (S6J3128HzB*) <br> - *Z: A/B |
| 1 | Features Peripheral Functions | Revised the full production and SHE-OFF series as follows. <br> (Correct) <br> ■A/D converter (successive approximation type) <br> -12-bit resolution, 2 units mounted: Max 50 channels ( 22 channels +28 channels)(S6J312AHzB*)/ Max 50 channels ( 22 channels + 28 channels)(S6J3129HzB*)/ Max 50 channels ( 22 channels +28 channels)(S6J3128HzB*) <br> - *z: A/B |
| 1 | Features Peripheral Functions | Revised the full production and SHE-OFF series as follows. (Correct) <br> Multi-function serial (transmission and reception FIFOs mounted) :Max 10 channels(S6J312AHzB*)/ Max 10 channels(S6J3129HzB*)/ Max 10 channels(S6J3128HzB*) <br> $\square{ }^{*}$ z: A/B |
| 1 | Features Peripheral Functions | Added the following function lists. <br> $<{ }^{2} \mathrm{C}>$ <br> -Full duplex, double buffering system; 64-byte transmission FIFO, 64-byte reception FIFO <br> $\square$ Standard mode (Max. 100kbps) is supported only. <br> $\square$ DMA transfer is supported. |
| 2 | Features Peripheral Functions | Revised the following function list. (Error) <br> - CAN transfer speed :1Mbps (Correct) <br> ㅁCAN transfer speed :5Mbps |


| Page | Section | Change Results |
| :---: | :---: | :---: |
| 2 | Features Peripheral Functions | Added the following function list under CAN controller. $\square 32$ message buffer/channel (transmission message buffer size) |
| 2 | Features Peripheral Functions | Added the following function list under Low-power consumption. - Partial wakeup function |
| 2 | Features Peripheral Functions | Revised the follows as full production. (Correct) ```■Package: LEU144 (S6J312xHzB*) \square*x:A/9/8, z: A/B``` |
| 6 | 1. Product Lineup | Added "Table 3-1 Memory Size" as full production. |
| 6 | 1. Product Lineup | Added "Table 3-2 SHE Option" as full production. |
| 6 | 1. Product Lineup | Added full production and notes as follows. <br> *1: x: A/9/8, z: A/B <br> *2: $I^{2} \mathrm{C}-$ UART function is not supported at Multi-function serial ch.1, ch.2, and ch.12. |
| 6 | 1. Product Lineup | Revised the following frequency. (Correct) <br> Maximum CPU operating frequency: 128 MHz |
| 7 | 1. Product Lineup | Added the following function list under Low-power consumption. - Partial wakeup function |
| 8 | 2. Pin Assignment | Revised "Figure 4-1 Pin Assignment for S6J312xHzB*" as follows. (Correct) <br> * $x: A / 9 / 8, z: A / B$ |
| 9 | 3. Pin Description | ```Revised the tables as follows for full production. (Correct) Table 5-1 S6J312xHzB* Pin Functions * x: A/9/8, z: A/B``` |


| Page | Section | Change Results |
| :---: | :---: | :---: |
| $\begin{gathered} \text { 10,11,12,15, } \\ 16,17,18 \\ 20,21,24 \end{gathered}$ | 3. Pin Description | Revised the "I/O pin" to "output pin" as follows (Correct) <br> Pin 13 Multi-function serial ch. 11 serial chip select 1 output pin (0) Pin14 Multi-function serial ch. 11 serial chip select 2 output pin (0) Pin 15 Multi-function serial ch. 11 serial chip select 3 output pin (0) Pin 23 Multi-function serial ch. 4 serial chip select 2 output pin (1) Pin 26 Multi-function serial ch. 4 serial chip select 3 output pin (1) Pin 49 Multi-function serial ch. 9 serial chip select 1 output pin (0) Pin 50 Multi-function serial ch. 9 serial chip select 2 output pin (0) Pin 51 Multi-function serial ch. 9 serial chip select 3 output pin (0) Pin 62 Multi-function serial ch. 4 serial chip select 3 output pin (0) Pin 64 Multi-function serial ch. 4 serial chip select 2 output pin (0) Pin 68 Multi-function serial ch. 4 serial chip select 1 output pin (0) Pin 76 Multi-function serial ch. 8 serial chip select 3 output pin (0) Pin 78 Multi-function serial ch. 8 serial chip select 1 output pin (0) Pin 97 Multi-function serial ch. 10 serial chip select 2 output pin (0) Pin 100 Multi-function serial ch. 10 serial chip select 1 output pin (0) Pin 136 Multi-function serial ch. 10 serial chip select 1 output pin (1) Pin 137 Multi-function serial ch. 10 serial chip select 3 output pin (1) |
| 19 | 3. Pin Description |  |
|  |  | (Correct) |



| Page | Section | Change Results |
| :---: | :---: | :---: |
| 27 | 4. I/O Circuit Types | Revised Type C of "I/O Circuit Type" as follows: (Correct) |
| 30 | 4. I/O Circuit Types | Added Type R to "11. I/O Circuit Type" R <br> Output of 2 mA |
| 37 | 6. Handling Devices | Revised the Vss Pin in Figure 8-1 Pin Assignment. <br> (Correct) <br> Figure 8-1 Pin Assignment |
| 38 | 6. Handling Devices | Revised the items as follows. (Correct) <br> This device has a built-in voltage step-down circuit. Be sure to connect a capacitor to the C pin (pin 126 in S6J312xHzB* specifications) for internal stabilization of the device. For the standard values, see "Recommended operating conditions" in the latest data sheet. *x:A/9/8, z: A/B |
| 39 | 7. Block Diagram | Revised the title as follows. (Correct) <br> Figure 9-1 S6J312xHzB* Block Diagram *x: A/9/8, z: A/B |
| 39 | 7. Block Diagram | Added "Partial Wake up" to "Block Diagram" |


| Page | Section | Change Results |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 40 | 8. Memory Map | Revised "Figure 10-1 Memory Map" as full production. (Correct) <br> Figure 10-1 Memory Map(S6J312AHzB/9HzB/8HzB*) *z: A/B |  |  |  |  |
|  |  | $\text { Start }{ }_{\text {ADORESS }}{ }_{\text {ENO }}$ |  | $\underset{\text { part }}{\text { S6J312AHzB* }}$ | S6J3129HzB* | $\mathrm{S} 6 \mathrm{~J} 3128 \mathrm{~Hz} \mathrm{~B}^{*}$ |
|  |  |  | Internal area for CR5 <br> Complex |  |  |  |
|  |  |  |  | ${ }_{\text {Reseved }}^{\text {Reened }}$ |  | Reesed Resered Reened |
|  |  |  |  |  | ${ }_{\text {Remen }}^{\text {Remed }}$ |  |
|  |  | ${ }^{\text {On }}$ |  |  | (smolsctoterexpree | (empast |
|  |  |  |  |  | (cose 78 serene) | (codesizeke) |
|  |  |  |  |  | Reese | Resenec |
|  |  |  |  | Reeere | nesmed | Reeseed |
|  |  |  |  |  |  |  |
|  |  | $0 \times 019 \mathrm{~F}$ _0000 $\quad 0 \times 019$ F_FFF |  |  |  |  |
|  |  |  |  |  | Axifusinemory | (tatass Memory |
|  |  |  |  |  |  |  |
|  |  |  |  | Reesved | Reeeved | Reeseed |
|  |  |  |  | Reeseed | Reesmed | Reesee |
|  |  |  | Shared Flash and memoryarea |  |  |  |
|  |  | (ex |  | Reseved <br> Resened | Reesened Reased | ${ }_{\substack{\text { Reeved } \\ \text { Reesred }}}$ |
|  |  |  |  | Excosut cacess memov | Excuste ceasememo | Excusve Cecess Memov |
|  |  |  |  |  | Axtseaveccoreo | Ax. Reave coromo |
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|  |  |  |  | $\begin{gathered} \hline \text { ERRCFG } \\ \hline \text { BootRom } \\ \hline \end{gathered}$ | $\begin{gathered} \hline \text { ERRCFG } \\ \hline \text { BootRom } \end{gathered}$ |  |
|  |  |  |  | Reesed |  |  |
| 41 | 8. Memory Map | Added item as follow "The ECC movem | Added item as follows. | port is based on | ECC setting in | ide the CPU." |
| 41 | 8. Memory Map | Revised " S6J312xHAA Peripheral Map" as follows |  |  |  |  |
|  |  | (Correct) |  |  |  |  |
|  |  | S6J312xHzB* Peripheral Map |  |  |  |  |


| Page | Section | Change Results |  |  |  |  |  |  |
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| 45 | 8. Memory Map | Added "Partial Wake Up" to address of "B484_8400 to B484_87FF". |  |  |  |  |  |  |
|  |  | B484_8400 | B484_87FF | APPS \#5 | A/D unit1 , Partial Wake Up |  | 297 |  |
| 45 | 8. Memory Map | Revised the memory map of APPS\#5 as follows. (Correct) |  |  |  |  |  |  |
|  |  | B484_8C00 | B484_8FFF |  | Reserved | - |  |  |
|  |  | B484_9000 | B484_93FF | APPS \#5 | Global Timer | 300 |  |  |
|  |  | B484_9400 | B484_FFFF |  | Reserved | , |  |  |
| 45 | 8. Memory Map | Revised the memory map of APPS\#7 as follows. (Correct) |  |  |  |  |  |  |
|  |  | START <br> Address | END <br> Address |  | Function |  |  | $\begin{aligned} & \text { PPU } \\ & \text { No } \end{aligned}$ |
|  |  | B48C_0000 | B48C_3FFF |  | Reserved |  |  |  |
|  |  | B48C_4000 | B48C_43FF | APPS \#7 | Stepper Motor Control ch. 0 |  |  | 317 |
|  |  | B48C_4400 | B48C_47FF | APPS \#7 | Stepper Motor Control ch. 1 |  |  | 318 |
|  |  | B48C_4800 | B48C_4BFF | APPS \#7 | Stepper Motor Control ch. 2 |  |  | 319 |
|  |  | B48C_4C00 | B48C_4FFF | APPS \#7 | Stepper Motor Control ch. 3 |  |  | 320 |
|  |  | B48C_5000 | B48C_57FF |  | Reserved |  |  |  |
|  |  | B48C_5800 | B48C_5BFF | APPS \#7 | SMC Trigger Generator |  |  | 323 |
|  |  | B48C_5C00 | B48C_5FFF | APPS \#7 | Liquid Crystal Display Controller |  |  | 324 |
|  |  | B48C_6000 | B48C_63FF | APPS \#7 | Liquid Crystal Display inputoutput control |  |  | 325 |
|  |  | B48C_6400 | B48C_FFFF |  | Reserved |  |  | - |
| 45 | 8. Memory Map | Added the following note. <br> When MPU attribute of Cortex®-R5 is configured as "Normal", store buffer inside Cortex-R5 can operate and write data can be merged. To avoid influence of this data merger, MPU attribute "Device" or "Strongly Ordered" should be used. MPU attribute "Device" or "Strongly Ordered" must be used for areas below, to avoid this influence. <br> -Backup RAM area (BACKUP_RAM) [0E80_0000 ~ 0E87_FFFF] <br> -Peripheral area (Peri area) [B000_0000 ~ B7FF_FFFF] <br> -Error Config area (ERRCFG) [FFFE_E000~FFFEEFFFFF] <br> MPU attribute "Device" or "Strongly Ordered" is required for accesses to areas below, in particular situation. <br> - $\quad$ FLASH Memory (when writing commands) |  |  |  |  |  |  |
| 45 | 8. Memory Map | Added the following note. <br> SHE OFF product is prohibited to access SHE area (B200_0000 to B20F_FFFF) |  |  |  |  |  |  |
| 46,47 | 9. Pin Status in CPU Status | Added Pin name about $\mathrm{I}^{2} \mathrm{C}$ and PWU to Table 11-1 Pin State Table (1/2) and Table 11-2 Pin State Table (2/2). |  |  |  |  |  |  |
| 47 | 9. Pin Status in CPU Status | Pin132: TX2_1 <br> Pin131: RX2_1 <br> Pin87: RX0_1 <br> Pin97: RX0-0 |  |  |  |  |  |  |
| 48 | 9. Pin Status in CPU Status | Added the item as follows <br> *7: When the PWU function is enabled, a change to output occurs. <br> *8: When PPC_PCFGRijj:POF[2:0] is set to initial value. <br> *9: When reset is issued, the following ports become "L" output as the initial state. |  |  |  |  |  |  |


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| 50 | 10. Electrical Characteristics 10.1 Absolute Maximum Ratings | Revised the remarks of Analog supply voltage (Error) <br> $\mathrm{AV}_{\mathrm{cc}} \leq \mathrm{V}_{\mathrm{cc}}$ <br> (Correct) <br> $\mathrm{AV} \mathrm{cc}=\mathrm{V}_{\mathrm{cc}}$ |  |  |  |  |
| 50 | 10. Electrical Characteristics 10.1 Absolute Maximum Ratings | Revised the Symbol of Maximum clamp current. (Error) <br> Iclamp <br> (Correct) <br> \|Iclamp| |  |  |  |  |
| 50 | 10. Electrical Characteristics 10.1 Absolute Maximum Ratings | Revised the following note. (Error) <br> *2: VCC and DVCC must be set to the same voltage. Caution must be taken that AVCC and DVCC does not exceed VCC upon power-on and under other circumstances. <br> (Correct) <br> *2: AVCC, DVCC and VCC must be set to the same voltage. It is required that AVCC and DVCC do not exceed VCC and that the voltage at the analog inputs does not exceed AVCC when the power is switched on. |  |  |  |  |
| 52 | 10. Electrical Characteristics 10.2 Recommended operating conditions | Revised the following title. (Error) Rating (Correct) Value |  |  |  |  |
|  | 10. Electrical Characteristics 10.2 Recommended operating conditions | Revised the parameter of Smoothing capacitor as follows. (Correct) |  |  |  |  |
| 52 |  | Smoothing capacitor | Cs1 | 4.7 | $\mu \mathrm{F}$ Tolerance of <br> Use a ceramic <br> has the simila <br> Use a capacit <br> than CS as th <br> VCC pin. | to $\pm 40 \%, 126$ pin capacitor or a capacitor that frequency characteristics. $r$ with a capacitance greater smoothing capacitor on the |
| 52 | 10. Electrical Characteristics 10.2 Recommended operating conditions | ```Revised the remarks of Operating temperature as follows. (Error) S6J312HAA (Correct) S6J312xHzB* * \(x: A / 9 / 8, z: A / B\)``` |  |  |  |  |
| 52 | 10. Electrical Characteristics 10.2 Recommended operating conditions | Revised the following Diagram <br> (Correct) <br> - C Pin Connection Diagram |  |  |  |  |


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| 74 | 10. Electrical Characteristics 10.4.4 Power-on Conditions | Revised the value of "Level detection voltage" (Error) min $2.25 \mathrm{~V} \mid$ typ $2.45 \mathrm{~V} \mid \max 2.65 \mathrm{~V}$ (Correct) min $2.15 \mathrm{~V} \mid$ typ $2.35 \mathrm{~V} \mid \max 2.55 \mathrm{~V}$ |
| 101,102 | 10. Electrical Characteristics 10.4.7.4 $\mathrm{I}^{2} \mathrm{C}$ Timing (SMR:MD[2:0]=100B) | Added the characteristic of " ${ }^{2} \mathrm{C}$ Timing (SMR:MD[2:0]=100B)" |
| 116,117 | 10. Electrical Characteristics 10.12 A/D Converter 10.12.1 Electrical Characteristics | Revised the value of "Analog port input current" in the table, and revised the pin name note *7 to *9 <br> (Correct) <br> *7: AN3, AN5, AN6, AN9, AN10, AN12 to AN15, AN17 to AN24, and AN27 to AN42 <br> *8: AN0 to AN2, and AN43 <br> *9: AN44 to AN62 |
| 119 | 10. Electrical Characteristics 10.12 A/D Converter 10.12.3 Definition of Terms | Revised the followings. <br> (Error) <br> Total error: Difference between the actual value and the theoretical value. The total error <br> (Correct) <br> Total error: Difference between the actual value and the theoretical value. The total error includes zero transition error, full-scale transition error, and non linearity error. |
| 121 | 10. Electrical Characteristics 10.13 Flash Memory | Deleted the followings. <br> *3: Target value |
| 122 | 11. Ordering Information | Added SHE option to the part number |
| 122 | 12.Part Number Option | Added Flash memory size option to the part number. |
| Revision *B |  |  |
| 1 | Cover | Revised the title as follow (error) <br> S6J3120 Series <br> 32-bit Microcontroller <br> Spansion® Traveo ${ }^{\text {TM }}$ Family (correct) <br> S6J3120 Series <br> 32-Bit Traveo ${ }^{\text {TM }}$ Family <br> Microcontroller Datasheet |
| 2 | Features | Added "CAN-FD (V3.2.0)" under "CAN controller: CAN-FD Max 3 channel". |
| 37 | 6.Handling Devices | Revised the following notice. <br> (Error) <br> About the Power-on Time <br> To prevent the internal built-in voltage step-down circuit from malfunctioning, secure a voltage rising time of $50 \mu \mathrm{~s}$ (between 0.2 V and 2.7 V ) or longer at the power-on time. <br> (Correct) <br> About the Power-on Time <br> To prevent a malfunction of the voltage step-down circuit built in the device, the voltage rising must be monotonic during power-on. |


| Page | Section | Change Results |
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| 70 | 10. Electrical <br> Characteristics <br> 10.4 .2 Internal Clock <br> Timing | Revised the following symbol. <br> (Error) tCLK_FMA <br> (Correct) tCLK_DMA |
| 74 | 10. Electrical <br> Characteristics <br> 10.4.4 Power-on <br> Conditions | Deleted the Slope detection undetected specification. <br> Added the Power ramp rate and Maximum ramp rate guaranteed to not generate <br> power-on reset. <br> *1, 2: Changed the sentence. <br> Added *3, *4, Note, Figure at the Power off time, Power ramp rate, Maximum ramp <br> rate guaranteed to not generate power-on reset. |
| 101 | 10. Electrical <br> Characteristics <br> 10.4.7.4 I2C Timing <br> (SMR:MD[2:0]=100B) | Revised the following pin names. <br> (Error) SCL0 to SCL4 / SDA0 to SDA4 <br> (Correct) SCL0, SCL3, SCL4 / SDA0, SDA3, SDA4 |
| 115 | 10. Electrical <br> Characteristics <br> 10.10 Low-Voltage <br> Detection (RAM Retention <br> Low-Voltage Detection) | Revised the title in 10.10 "Internal Low-Voltage Detection" to "RAM Retention Low- <br> Voltage Detection". |
| 115 | 10. Electrical <br> Characteristics <br> 10.11 Low-Voltage <br> Detection (1.2 V Power <br> Supply Low-Voltage <br> Detection) | Added the notice *4 |

## NOTE: Please see "Document History" for later revised information.

## Document History

Document Title: S6J3120 Series, 32-Bit TRAVEO ${ }^{\text {TM }}$ T1G Family Microcontroller
Document Number: 002-04863

| Revision | ECN | Submission Date | Description of Change |
| :---: | :---: | :---: | :---: |
| ** | - | 08/07/2014 | Initial release New Spec. |
| *A | 4993737 | 10/29/2015 | Added full product names. <br> Added 144pin PWUTRG function. <br> Added simultaneous function for start timing of PWM does not overlap. <br> Added I2C function. <br> Added SHE-OFF Option. <br> Updated CANFD macro (updated to v3.2.0). <br> Revised min value of VIH6 (TRST, TCK, TDI, TMS) from 2.0 V to 2.3 V . <br> Revised operating frequency to 128 MHz , <br> and revised clock frequency based 128 MHz . <br> Revised current consumption standard (ICC5, ICCT52, ICCT52M, ICCH52). <br> Added partial wakeup macro. <br> For detail, see "Major Changes". <br> Updated to Cypress template. |
| *B | 5309249 | 06/16/2016 | Revised part number from S6J311xxxB to S6J311xxxC. <br> For detail, see "Major Changes". |
| *C | 5375465 | 07/27/2016 | Page74, <br> 10.4.4 Power-on Conditions <br> Revised Level detection time from 30 to 540, <br> Revised *1 to *4 and Note. <br> Page115, <br> 10.10 Low-Voltage Detection (RAM Retention Low-Voltage Detection) <br> Added * and Note to Detection voltage. <br> Page115, <br> 10.11 Low-Voltage Detection (1.2 V Power Supply Low-Voltage Detection) <br> Added * and Note to Detection voltage. |
| *D | 5554888 | 12/15/2016 | Page 124, <br> Replaced 13. Package Dimensions <br> Page 125, <br> Added 14. Appendix |
| *E | 5782640 | 06/22/2017 | Updated Cypress Logo and Copyright. |
| *F | 6251474 | 07/18/2018 | Part Number Option is updated. Updated to new template. |
| *G | 6295507 | 08/30/2018 | Page 99 Added 14. Errata |
| *H | 6578141 | 06/27/2019 | Updated to new template. |
| * | 7100466 | 03/12/2021 | Updated 14. Errata For details, see 16. Major Changes. |
| *J | 7388124 | 10/25/2021 | Updated 14. Errata For details, see 16. Major Changes. |

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[^0]:    *x:A/9, z: A/B

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